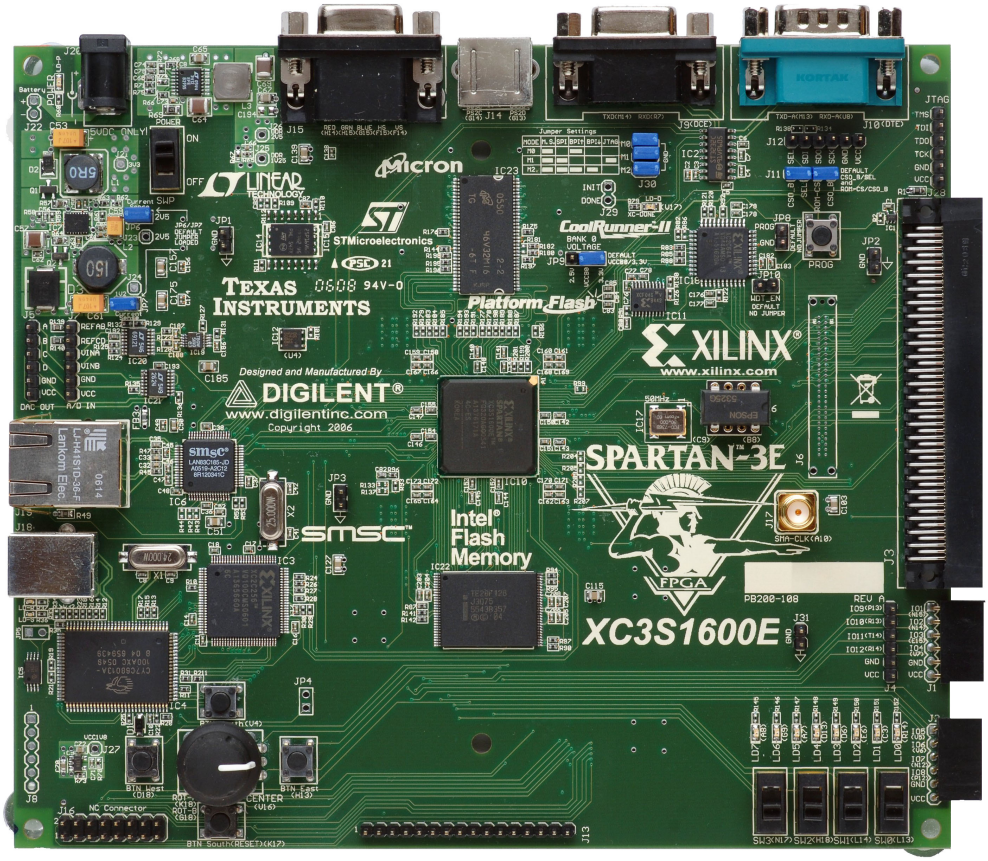
# MicroBlaze Development Kit Spartan-3E 1600E Edition User Guide

**UG257 (v1.1) December 5, 2007**

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# Revision History

The following table shows the revision history for this document.

| Date | Version | Revision |
|---|---|---|
| 6/23/06 | 1.0 | Initial release. |
| 12/5/07 | 1.1 | Updated Figures 15-8, 15-9, and 15-10 to comply with UCF I/O location constraints. |

# Table of Contents

# About This Guide

This user guide provides basic information on the MicroBlaze Development Kit board capabilities, functions, and design. It includes general information on how to use the various peripheral functions included on the board. For detailed reference designs, including VHDL or Verilog source code, please visit the following web link.

- Spartan™-3E Starter Kit Board Reference Page
  http://www.xilinx.com/sp3e1600e

## Acknowledgements

Xilinx wishes to thank the following companies for their support of the MicroBlaze Development Kit board:

- Intel Corporation for the 128 Mbit StrataFlash memory
- Linear Technology for the SPI-compatible A/D and D/A converters, the programmable pre-amplifier, and the power regulators for the non-FPGA components
- Micron Technology, Inc. for the 32M x 16 DDR SDRAM
- SMSC for the 10/100 Ethernet PHY
- STMicroelectronics for the 16M x 1 SPI serial Flash PROM
- Texas Instruments Incorporated for the three-rail TPS75003 regulator supplying most of the FPGA supply voltages
- Xilinx, Inc. Configuration Solutions Division for the XCF04S Platform Flash PROM and their support for the embedded USB programmer
- Xilinx, Inc. CPLD Division for the XC2C64A CoolRunner™-II CPLD

## Guide Contents

This manual contains the following chapters:

- Chapter 1, "Introduction and Overview," provides an overview of the key features of the MicroBlaze Development Kit board.
- Chapter 2, "Switches, Buttons, and Knob," defines the switches, buttons, and knobs present on the MicroBlaze Development Kit board.
- Chapter 3, "Clock Sources," describes the various clock sources available on the MicroBlaze Development Kit board.
- Chapter 4, "FPGA Configuration Options," describes the configuration options for the FPGA on the MicroBlaze Development Kit board.

- Chapter 5, "Character LCD Screen," describes the functionality of the character LCD screen.
- Chapter 6, "VGA Display Port," describes the functionality of the VGA port.
- Chapter 7, "RS-232 Serial Ports," describes the functionality of the RS-232 serial ports.
- Chapter 8, "PS/2 Mouse/Keyboard Port," describes the functionality of the PS/2 mouse and keyboard port.
- Chapter 9, "Digital to Analog Converter (DAC)," describes the functionality of the DAC.
- Chapter 10, "Analog Capture Circuit," describes the functionality of the A/D converter with a programmable gain pre-amplifier.
- Chapter 11, "Intel StrataFlash Parallel NOR Flash PROM," describes the functionality of the StrataFlash PROM.
- Chapter 12, "SPI Serial Flash," describes the functionality of the SPI Serial Flash memory.
- Chapter 13, "DDR SDRAM," describes the functionality of the DDR SDRAM.
- Chapter 14, "10/100 Ethernet Physical Layer Interface," describes the functionality of the 10/100Base-T Ethernet physical layer interface.
- Chapter 15, "Expansion Connectors," describes the various connectors available on the MicroBlaze Development Kit board.
- Chapter 16, "XC2C64A CoolRunner-II CPLD" describes how the CPLD is involved in FPGA configuration when using Master Serial and BPI mode.
- Chapter 17, "DS2432 1-Wire SHA-1 EEPROM" provides a brief introduction to the SHA-1 secure EEPROM for authenticating or copy-protecting FPGA configuration bitstreams.
- Appendix A, "Schematics," lists the schematics for the MicroBlaze Development Kit board.
- Appendix B, "Example User Constraints File (UCF)," provides example code from a UCF.

## Additional Resources

To find addtional resources for the MicroBlaze Processor or the Xilinx Embedded development tools, see the Xilinx website at:

http://www.Xilinx.com/Microblaze or http://www.Xilinx.com/EDK

To find additional documentation, see the Xilinx website at:

http://www.xilinx.com/literature.

To search the Answer Database of silicon, software, and IP questions and answers, or to create a technical support WebCase, see the Xilinx website at:

http://www.xilinx.com/support.

Chapter 1

# Introduction and Overview

Thank you for purchasing the Xilinx MicroBlaze™ Development Kit Spartan™-3E 1600E Edition. You will find it useful in developing your Spartan-3E FPGA application.

## Choose the Starter Kit Board for Your Needs

Depending on specific requirements, choose the Xilinx development board that best suits your needs.

### Spartan-3E FPGA Features and Embedded Processing Functions

The MicroBlaze Development Kit board highlights the unique features of the Spartan-3E FPGA family and provides a convenient development board for embedded processing applications. The board highlights these features:

- Spartan-3E specific features
  - Parallel NOR Flash configuration
  - MultiBoot FPGA configuration from Parallel NOR Flash PROM
  - SPI serial Flash configuration
- Embedded development
  - MicroBlaze 32-bit embedded RISC processor
  - PicoBlaze™ 8-bit embedded controller
  - DDR memory interfaces
  - 10-100 Ethernet
  - UART

### Learning Xilinx FPGA, CPLD, and ISE Development Software Basics

The MicroBlaze Development Kit board is more advanced and complex compared to other Spartan development boards.

### Advanced Spartan-3 Generation Development Boards

The MicroBlaze Development Kit board demonstrates the basic capabilities of the MicroBlaze embedded processor and the Xilinx Embedded Development Kit (EDK). For more advanced development on a board with additional peripherals and FPGA logic, consider the V4 FX12 Board:

- http://www.xilinx.com/xlnx/xebiz/designResources/ip_product_details.jsp?key=DO-ML403-EDK-ISE

Also consider the capable boards offered by Xilinx partners:

- http://www.xilinx.com/products/devboards/index.htm

# Key Components and Features

The key features of the MicroBlaze Development Kit board are:

- Xilinx XC3S1600E Spartan-3E FPGA
  - Up to 250
  - user-I/O pins
  - 320-pin FBGA package
  - Over 33,000 logic cells
- Two Xilinx 4 Mbit Platform Flash configuration PROM
- Xilinx 64-macrocell XC2C64A CoolRunner CPLD
- 64 MByte (512 Mbit) of DDR SDRAM, x16 data interface, 100+ MHz
- 16 MByte (128 Mbit) of parallel NOR Flash (Intel StrataFlash)
  - FPGA configuration storage
  - MicroBlaze code storage/shadowing
- 16 Mbits of SPI serial Flash (STMicro)
  - FPGA configuration storage
  - MicroBlaze code shadowing
- 2 x 16 LCD display screen
- PS/2 mouse or keyboard port
- VGA display port
- 10/100 Ethernet PHY (requires Ethernet MAC in FPGA)
- Two 9-pin RS-232 ports (DTE- and DCE-style)
- On-board USB-based FPGA/CPLD download/debug interface
- 50 MHz and 66 MHz clock oscillators
- SHA-1 1-wire serial EEPROM for bitstream copy protection
- Hirose FX2 expansion connector with 40-user I/O
- Three Digilent 6-pin expansion connectors
- Four-output, SPI-based Digital-to-Analog Converter (DAC)
- Two-input, SPI-based Analog-to-Digital Converter (ADC) with programmable-gain pre-amplifier
- ChipScope™ SoftTouch debugging port
- Rotary-encoder with push-button shaft
- Eight discrete LEDs
- Four slide switches
- Four push-button switches
- SMA clock input

- 8-pin DIP socket for auxiliary clock oscillator

# Design Trade-Offs

A few system-level design trade-offs were required in order to provide the MicroBlaze Development Kit board with the most functionality.

## Configuration Methods Galore!

A typical FPGA application uses a single non-volatile memory to store configuration images. To demonstrate new Spartan-3E capabilities, the MicroBlaze Development Kit board has three different configuration memory sources that all need to function well together. The extra configuration functions make the starter kit board more complex than typical Spartan-3E applications.

The starter kit board also includes an on-board USB-based JTAG programming interface. The on-chip circuitry simplifies the device programming experience. In typical applications, the JTAG programming hardware resides off-board or in a separate programming module, such as the Xilinx Platform USB cable. This USB port is for programming only and can not be used as an independent USB interface.

## Voltages for all Applications

The MicroBlaze Development Kit board showcases a triple-output regulator developed by Texas Instruments, the TPS75003 specifically to power Spartan-3 and Spartan-3E FPGAs. This regulator is sufficient for most stand-alone FPGA applications. However, the starter kit board includes DDR SDRAM, which requires its own high-current supply. Similarly, the USB-based JTAG download solution requires a separate 1.8V supply.

# Related Resources

- Xilinx MicroBlaze Soft Processor
  http://www.xilinx.com/microblaze
- Xilinx PicoBlaze Soft Processor
  http://www.xilinx.com/picoblaze
- Xilinx Embedded Development Kit
  http://www.xilinx.com/ise/embedded_design_prod/platform_studio.htm
- Xilinx software tutorials
  http://www.xilinx.com/support/techsup/tutorials/
- Texas Instruments TPS75003
  http://focus.ti.com/docs/prod/folders/print/tps75003.html

Chapter 2

# Switches, Buttons, and Knob

## Slide Switches

### Locations and Labels

The MicroBlaze Development Kit board has four slide switches, as shown in Figure 2-1. The slide switches are located in the lower right corner of the board and are labeled SW3 through SW0. Switch SW3 is the left-most switch, and SW0 is the right-most switch.

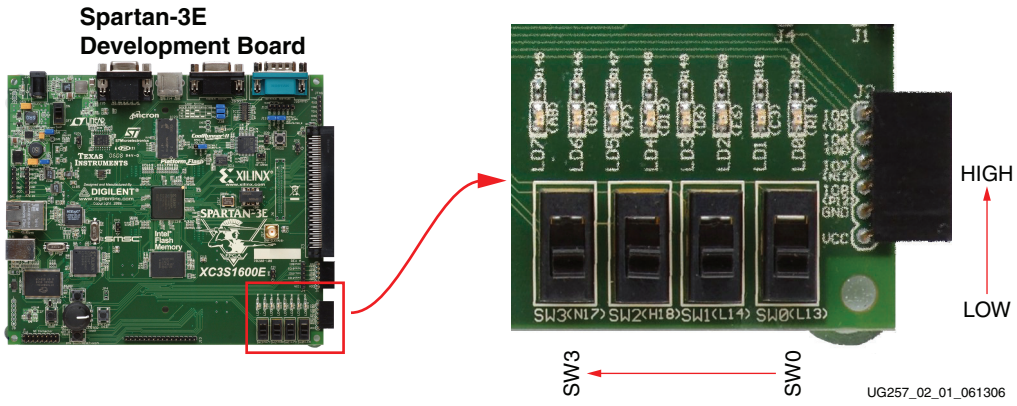


*Figure 2-1:* **Four Slide Switches**

### Operation

When in the UP or ON position, a switch connects the FPGA pin to 3.3V, a logic High. When DOWN or in the OFF position, the switch connects the FPGA pin to ground, a logic Low. The switches typically exhibit about 2 ms of mechanical bounce and there is no active debouncing circuitry, although such circuitry could easily be added to the FPGA design programmed on the board.

### UCF Location Constraints

Figure 2-2 provides the UCF constraints for the four slide switches, including the I/O pin assignment and the I/O standard used. The PULLUP resistor is not required, but it defines the input value when the switch is in the middle of a transition.

```
NET "SW<0>" LOC = "L13" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<1>" LOC = "L14" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<2>" LOC = "H18" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<3>" LOC = "N17" | IOSTANDARD = LVTTL | PULLUP ;
```

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*Figure 2-2:* **UCF Constraints for Slide Switches**

# Push-Button Switches

## Locations and Labels

The MicroBlaze Development Kit board has four momentary-contact push-button switches, shown in Figure 2-3. The push buttons are located in the lower left corner of the board and are labeled BTN_NORTH, BTN_EAST, BTN_SOUTH, and BTN_WEST. The FPGA pins that connect to the push buttons appear in parentheses in Figure 2-3 and the associated UCF appears in Figure 2-5.

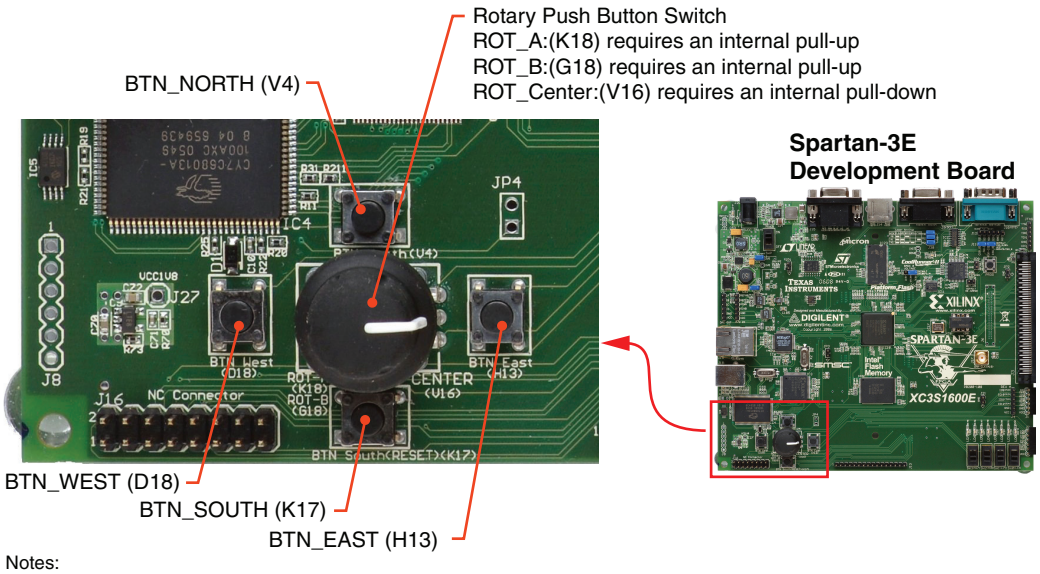


*Figure 2-3:* **Four Push-Button Switches Surround Rotary Push-Button Switch**

## Operation

Pressing a push button connects the associated FPGA pin to 3.3V, as shown in Figure 2-4. Use an internal pull-down resistor within the FPGA pin to generate a logic Low when the button is not pressed. Figure 2-5 shows how to specify a pull-down resistor within the UCF. There is no active debouncing circuitry on the push button.

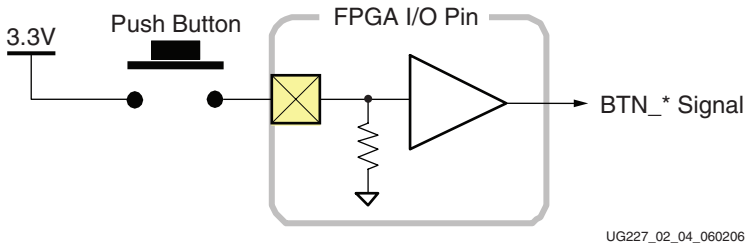


*Figure 2-4:* **Push-Button Switches Require an Internal Pull-Down Resistor in FPGA Input Pin**

In some applications, the BTN_SOUTH push-button switch is also a soft reset that selectively resets functions within the FPGA.

### UCF Location Constraints

Figure 2-5 provides the UCF constraints for the four push-button switches, including the I/O pin assignment and the I/O standard used, and defines a pull-down resistor on each input.

```
NET "BTN_EAST"  LOC = "H13" | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_NORTH" LOC = "V4"  | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_SOUTH" LOC = "K17" | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_WEST"  LOC = "D18" | IOSTANDARD = LVTTL | PULLDOWN ;
```

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*Figure 2-5:* **UCF Constraints for Push-Button Switches**

## Rotary Push-Button Switch

### Locations and Labels

The rotary push-button switch is located in the center of the four individual push-button switches, as shown in Figure 2-3. The switch produces three outputs. The two shaft encoder outputs are ROT_A and ROT_B. The center push-button switch is ROT_CENTER.

### Operation

The rotary push-button switch integrates two different functions. The switch shaft rotates and outputs values whenever the shaft turns. The shaft can also be pressed, acting as a push-button switch.

#### Push-Button Switch

Pressing the knob on the rotary/push-button switch connects the associated FPGA pin to 3.3V, as shown in Figure 2-6. Use an internal pull-down resistor within the FPGA pin to generate a logic Low. Figure 2-9 shows how to specify a pull-down resistor within the UCF. There is no active debouncing circuitry on the push button.

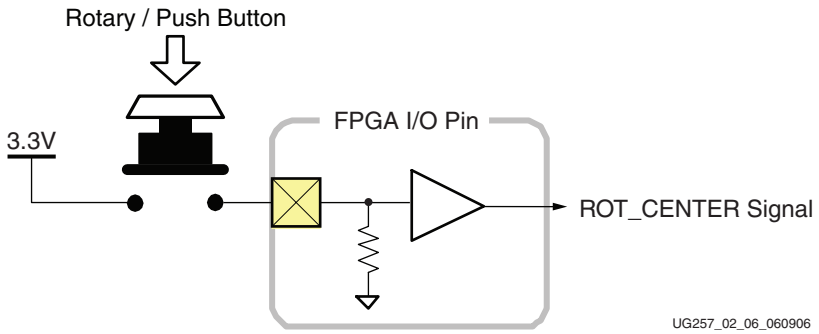


*Figure 2-6:* **Push-Button Switches Require Internal Pull-up Resistor in FPGA Input Pin**

## Rotary Shaft Encoder

In principal, the rotary shaft encoder behaves much like a cam, connected to central shaft. Rotating the shaft then operates two push-button switches, as shown in Figure 2-7. Depending on which way the shaft is rotated, one of the switches opens before the other. Likewise, as the rotation continues, one switch closes before the other. However, when the shaft is stationary, also called the *detent* position, both switches are closed.

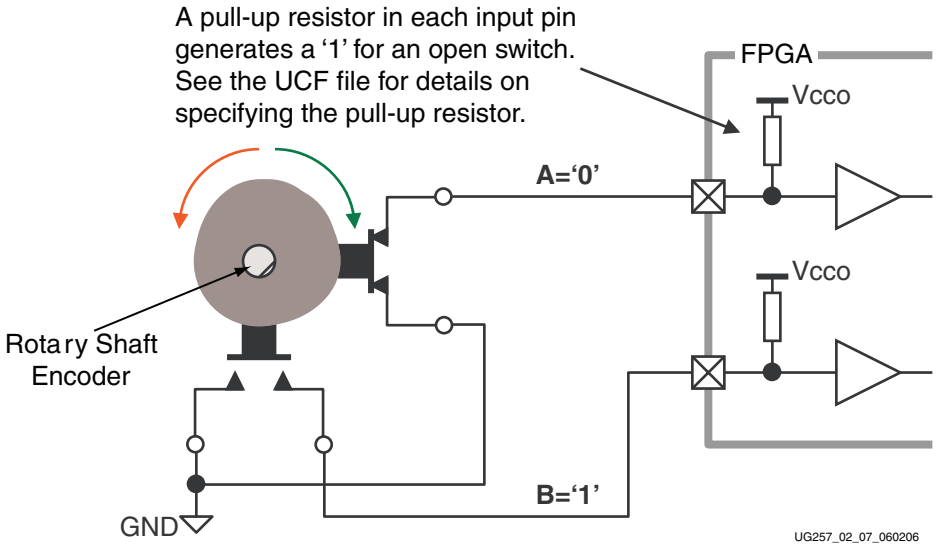


*Figure 2-7:* **Basic example of rotary shaft encoder circuitry**

Closing a switch connects it to ground, generating a logic Low. When the switch is open, a pull-up resistor within the FPGA pin pulls the signal to a logic High. The UCF constraints in Figure 2-9 describe how to define the pull-up resistor.

The FPGA circuitry to decode the 'A' and 'B' inputs is simple, but must consider the mechanical switching noise on the inputs, also called chatter. As shown in Figure 2-8, the chatter can falsely indicate extra rotation events or even indicate rotations in the opposite direction! See the Rotary Encoder Interface reference design in"Related Resources" for an example.

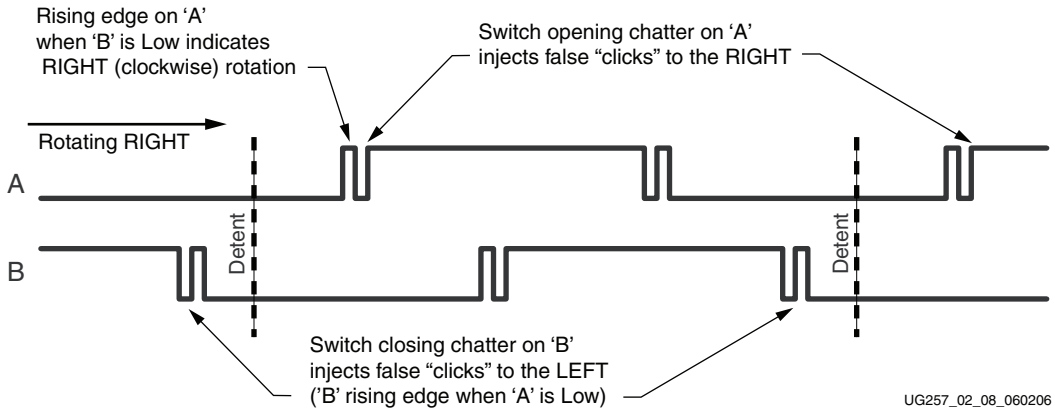


*Figure 2-8:* **Outputs from Rotary Shaft Encoder May Include Mechanical Chatter**

## UCF Location Constraints

Figure 2-9 provides the UCF constraints for the four push-button switches, including the I/O pin assignment and the I/O standard used, and defines a pull-down resistor on each input.

```
NET "ROT_A"      LOC = "K18" | IOSTANDARD = LVTTL | PULLUP   ;
NET "ROT_B"      LOC = "G18" | IOSTANDARD = LVTTL | PULLUP   ;
NET "ROT_CENTER" LOC = "V16" | IOSTANDARD = LVTTL | PULLDOWN ;
```

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*Figure 2-9:* **UCF Constraints for Rotary Push-Button Switch**

# Discrete LEDs

## Locations and Labels

The MicroBlaze Development Kit board has eight individual surface-mount LEDs located above the slide switches as shown in Figure 2-10. The LEDs are labeled LED7 through LED0. LED7 is the left-most LED, LED0 the right-most LED.

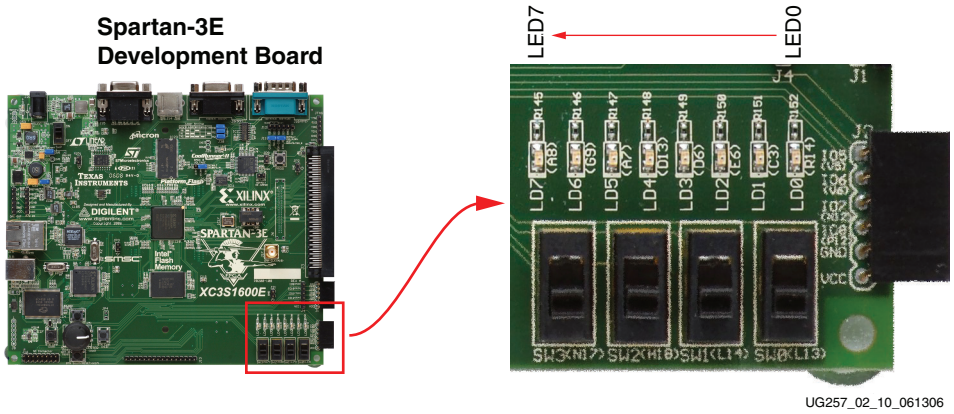


*Figure 2-10:* **Eight Discrete LEDs**

## Operation

Each LED has one side connected to ground and the other side connected to a pin on the Spartan-3E device via a 390Ω current limiting resistor. To light an individual LED, drive the associated FPGA control signal High.

## UCF Location Constraints

Figure 2-11 provides the UCF constraints for the four push-button switches, including the I/O pin assignment, the I/O standard used, the output slew rate, and the output drive current.

```
NET "LED<7>" LOC = "A8" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<6>" LOC = "G9" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<5>" LOC = "A7" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
 NET "LED<4>" LOC = "D13" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<3>" LOC = "E6" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<2>" LOC = "D6" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<1>" LOC = "C3" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ;
NET "LED<0>" LOC = "D4" | IOSTANDARD = SSTL2_I ;
```

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*Figure 2-11:* **UCF Constraints for Eight Discrete LEDs**

# Related Resources

- Rotary Encoder Interface for Spartan-3E Starter Kit (Reference Design)
  http://www.xilinx.com/s3estarter
  http://www.xilinx.com/sp3e1600E

Chapter 3

# Clock Sources

## Overview

As shown in Figure 3-1, the MicroBlaze Development Kit board supports three primary clock input sources, all of which are located below the Xilinx logo, near the Spartan-3E logo.

- The board includes an on-board 50 MHz clock oscillator.
- The user clock socket is populated with a 66 MHz oscillator
- Clocks can be supplied off-board via an SMA-style connector. Alternatively, the FPGA can generate clock signals or other high-speed signals on the SMA-style connector.
- Optionally install a separate 8-pin DIP-style clock oscillator in the supplied socket

.

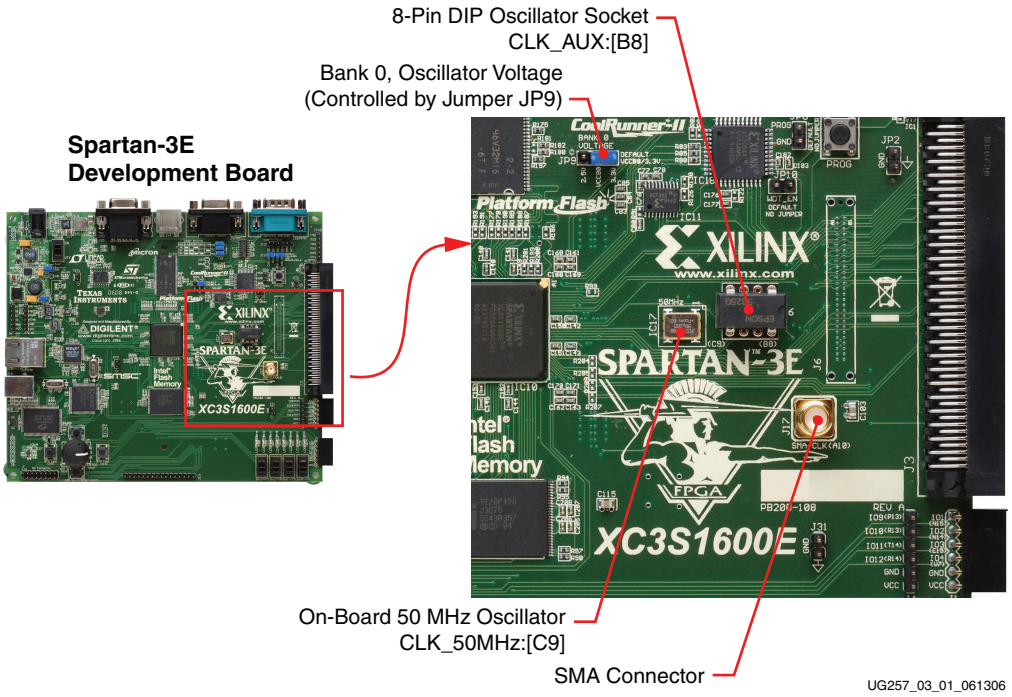


*Figure 3-1:* **Available Clock Inputs**

# Clock Connections

Each of the clock inputs connect directly to a global buffer input in I/O Bank 0, along the top of the FPGA. As shown in Table 3-1, each of the clock inputs also optimally connects to an associated DCM.

*Table 3-1:* **Clock Inputs and Associated Global Buffers and DCMs**

| Clock Input | FPGA Pin | Global Buffer | Associated DCM |
|---|---|---|---|
| CLK_50MHZ | C9 | GCLK10 | DCM_X0Y1 |
| CLK_AUX | B8 | GCLK8 | DCM_X0Y1 |
| CLK_SMA | A10 | GCLK7 | DCM_X1Y1 |

# Voltage Control

The voltage for all I/O pins in FPGA I/O Bank 0 is controlled by jumper JP9. Consequently, these clock resources are also controlled by jumper JP9. By default, JP9 is set for 3.3V. The on-board oscillator is a 3.3V device and might not perform as expected when jumper JP9 is set for 2.5V.

# 50 MHz On-Board Oscillator

The board includes a 50 MHz oscillator with a 40% to 60% output duty cycle. The oscillator is accurate to ±2500 Hz or ±50 ppm.

# Auxiliary Clock Oscillator Socket

The provided 8-pin socket accepts clock oscillators that fit the 8-pin DIP footprint. Use this socket if the FPGA application requires a frequency other than 50 MHz. This socket is populated with a 66 MHz oscillator. This clock input is used for some of the reference designs provided with the board. Alternatively, use the FPGA's Digital Clock Manager (DCM) to generate or synthesize other frequencies from the on-board 50 MHz oscillator.

# SMA Clock Input or Output Connector

To provide a clock from an external source, connect the input clock signal to the SMA connector. The FPGA can also generate a single-ended clock output or other high-speed signal on the SMA clock connector for an external device.

# UCF Constraints

The clock input sources require two different types of constraints. The location constraints define the I/O pin assignments and I/O standards. The period constraints define the clock period—and consequently the clock frequency—and the duty cycle of the incoming clock signal.

### Location

Figure 3-2 provides the UCF constraints for the three clock input sources, including the I/O pin assignment and the I/O standard used. The settings assume that jumper JP9 is set for 3.3V. If JP9 is set for 2.5V, adjust the IOSTANDARD settings accordingly.

```
NET "CLK_50MHZ" LOC = "C9"  | IOSTANDARD = LVCMOS33 ;
NET "CLK_SMA"   LOC = "A10" | IOSTANDARD = LVCMOS33 ;
NET "CLK_AUX"   LOC = "B8"  | IOSTANDARD = LVCMOS33 ;
```

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*Figure 3-2:* **UCF Location Constraints for Clock Sources**

### Clock Period Constraints

The Xilinx ISE development software uses timing-driven logic placement and routing. Set the clock PERIOD constraint as appropriate. An example constraint appears in Figure 3-3 for the on-board 50 MHz clock oscillator. The CLK_50MHZ frequency is 50 MHz, which equates to a 20 ns period. The output duty cycle from the oscillator ranges between 40% to 60%.

```
# Define clock period for 50 MHz oscillator
NET "CLK_50MHZ" PERIOD = 20.0ns HIGH 40%;
```

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*Figure 3-3:* **UCF Clock PERIOD Constraint**

## Related Resources

- Epson SG-8002JF Series Oscillator Data Sheet (50 MHz Oscillator) http://www.eea.epson.com/go/Prod_Admin/Categories/EEA/QD/Crystal_Oscillators/prog_oscillators/go/Resources/TestC2/SG8002JF

Chapter 4

# FPGA Configuration Options

The MicroBlaze Development Kit board supports a variety of FPGA configuration options:

- Download FPGA designs directly to the Spartan-3E FPGA via JTAG, using the on-board USB interface. The on-board USB-JTAG logic also provides in-system programming for the on-board Platform Flash PROM and the Xilinx XC2C64A CPLD. SPI serial Flash and StrataFlash programming are performed separately.
- Program the on-board 4 Mbit Xilinx XCF04S serial Platform Flash PROM, then configure the FPGA from the image stored in the Platform Flash PROM using Master Serial mode.
- Program the on-board 16 Mbit ST Microelectronics SPI serial Flash PROM, then configure the FPGA from the image stored in the SPI serial Flash PROM using SPI mode.
- Program the on-board 128 Mbit Intel StrataFlash parallel NOR Flash PROM, then configure the FPGA from the image stored in the Flash PROM using BPI Up or BPI Down configuration modes. Further, an FPGA application can dynamically load two different FPGA configurations using the Spartan-3E FPGA's MultiBoot mode. See the Spartan-3E data sheet (DS312) for additional details on the MultiBoot feature.

Figure 4-1 indicates the position of the USB download/programming interface and the on-board non-volatile memories that potentially store FPGA configuration images. Figure 4-2 provides additional details on configuration options.

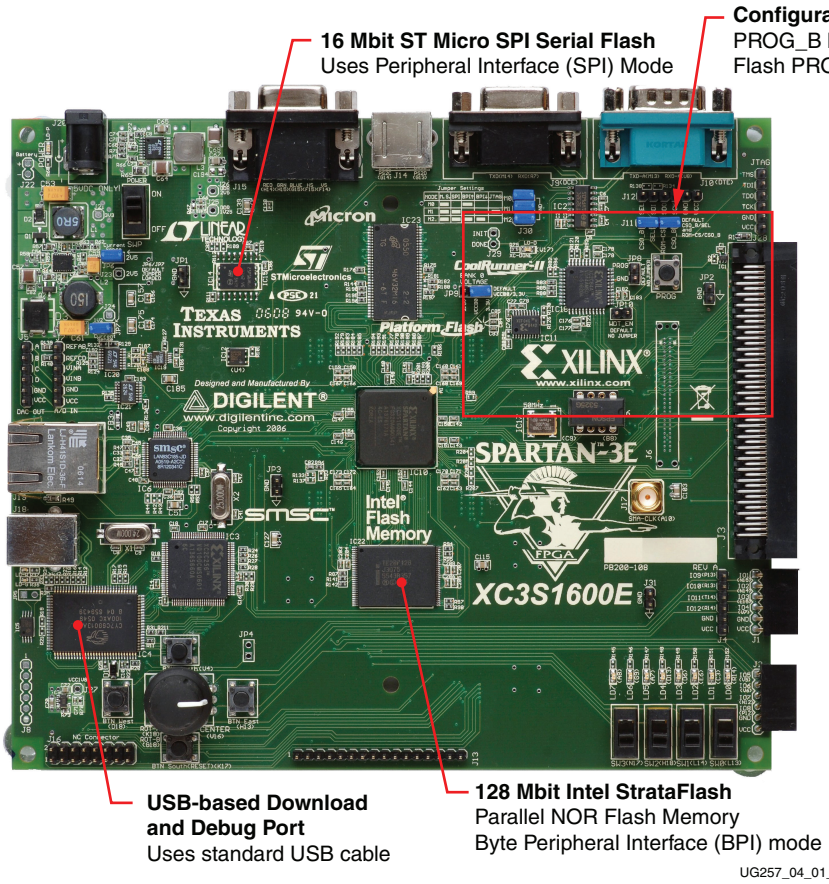



*Figure 4-1:* **MicroBlaze Development Kit Board FPGA Configuration Options**

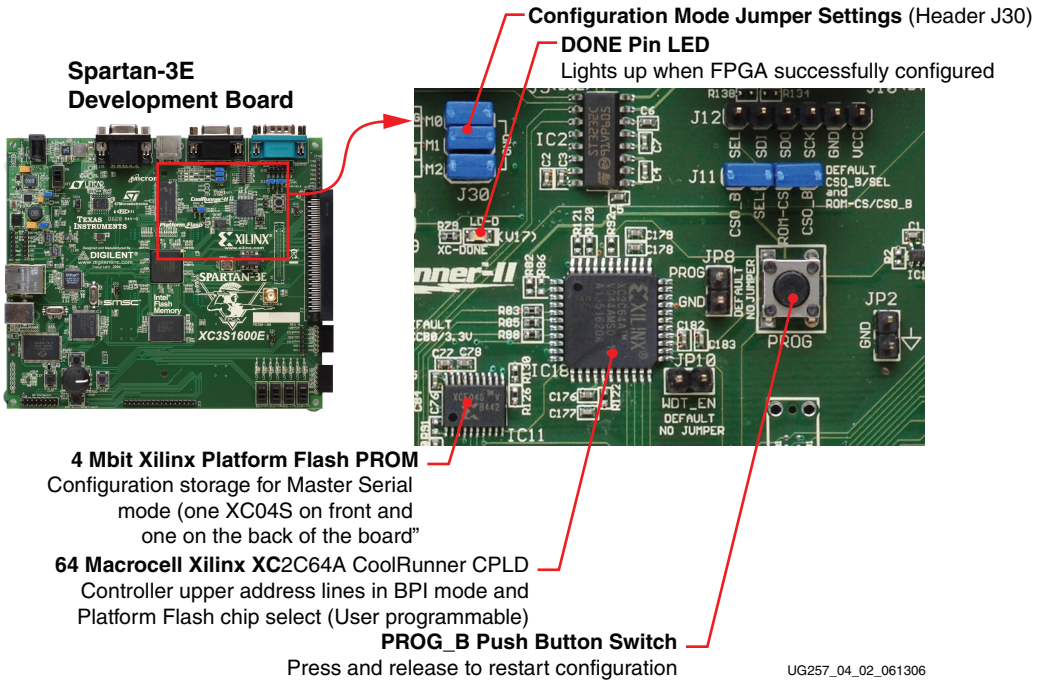



*Figure 4-2:* **Detailed Configuration Options**

The configuration mode jumpers determine which configuration mode the FPGA uses when power is first applied, or whenever the PROG button is pressed.

The DONE pin LED lights when the FPGA successfully finishes configuration.

Pressing the PROG button forces the FPGA to restart its configuration process.

The 4 Mbit Xilinx Platform Flash PROM provides easy, JTAG-programmable configuration storage for the FPGA. The FPGA configures from the Platform Flash using Master Serial mode.

The 64-macrocell XC2C64A CoolRunner II CPLD provides additional programming capabilities and flexibility when using the BPI Up, BPI Down, or MultiBoot configuration modes and loading the FPGA from the StrataFlash parallel Flash PROM. The CPLD is user-programmable.

# Configuration Mode Jumpers

As shown in Table 4-1, the J30 jumper block settings control the FPGA's configuration mode. Inserting a jumper grounds the associated mode pin. Insert or remove individual jumpers to select the FPGA's configuration mode and associated configuration memory source.

*Table 4-1:* **MicroBlaze Development Kit Board Configuration Mode Jumper Settings (Header J30 in Figure 4-2)**

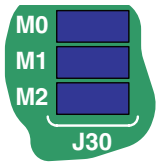
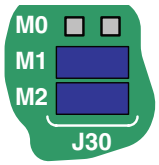
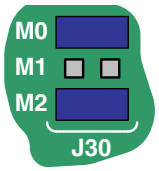
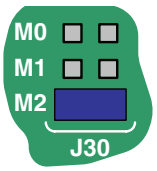
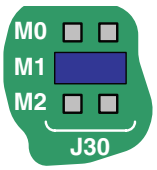
| Configuration Mode | Mode Pins M2:M1:M0 | FPGA Configuration Image Source | Jumper Settings |
|---|---|---|---|
| Master Serial | 000 | Platform Flash PROM |  |
| SPI<br>(see Chapter 12, "SPI Serial Flash") | 001 | SPI Serial Flash PROM starting at address 0 |  |
| BPI Up<br>(see Chapter 11, "Intel StrataFlash Parallel NOR Flash PROM") | 010 | StrataFlash parallel Flash PROM, starting at address 0 and incrementing through address space. The CPLD controls address lines A[24:20] during BPI configuration. |  |

*Table 4-1:* **MicroBlaze Development Kit Board Configuration Mode Jumper Settings (Header J30 in Figure 4-2)**

| Configuration Mode | Mode Pins M2:M1:M0 | FPGA Configuration Image Source | Jumper Settings |
|---|---|---|---|
| BPI Down (see Chapter 11, "Intel StrataFlash Parallel NOR Flash PROM") | 011 | StrataFlash parallel Flash PROM, starting at address 0x1FF_FFFF and decrementing through address space. The CPLD controls address lines A[24:20] during BPI configuration. |  |
| JTAG | 101 | Downloaded from host via USB-JTAG port |  |

## PROG Push Button

The PROG push button, shown in Figure 4-2, page 24, forces the FPGA to reconfigure from the selected configuration memory source. Press and release this button to restart the FPGA configuration process at any time.

## DONE Pin LED

The DONE pin LED, shown in Figure 4-2, page 24, lights whenever the FPGA is successfully configured. If this LED is not lit, then the FPGA is not configured.

# Programming the FPGA, CPLD, or Platform Flash PROM via USB

As shown in Figure 4-1, page 24, the MicroBlaze Development Kit board includes embedded USB-based programming logic and an USB endpoint with a Type B connector. Via a USB cable connection with the host PC, the iMPACT programming software directly programs the FPGA, the Platform Flash PROM, or the on-board CPLD. Direct programming of the parallel or serial Flash PROMs is not presently supported.

## Connecting the USB Cable

The kit includes a standard USB Type A/Type B cable, similar to the one shown in Figure 4-3. The actual cable color might vary from the picture.

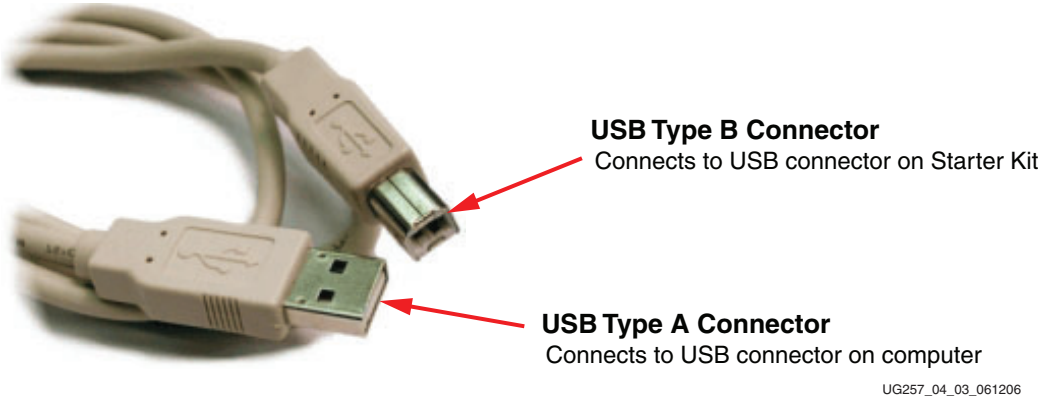



*Figure 4-3:* **Standard USB Type A/Type B Cable**

The wider and narrower Type A connector fits the USB connector at the back of the computer.

After installing the Xilinx software, connect the square Type B connector to the MicroBlaze Development Kit board, as shown in Figure 4-4. The USB connector is on the left side of the board, immediately next to the Ethernet connector. When the board is powered on, the Windows operating system should recognize and install the associated driver software.

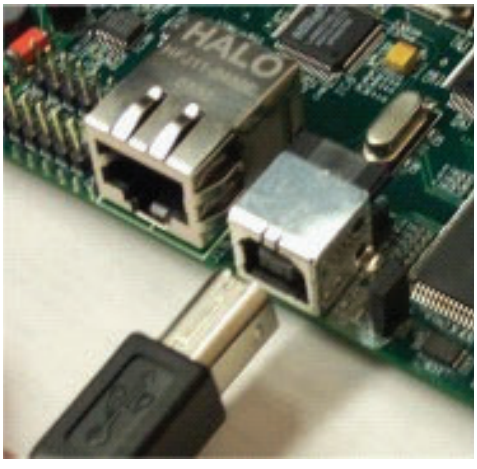



*Figure 4-4:* **Connect the USB Type B Connector to the MicroBlaze Development Kit Board Connector**

When the USB cable driver is successfully installed and the board is correctly connected to the PC, a green LED lights up, indicating a good connection.

## Programming via iMPACT

After successfully compiling an FPGA design using the Xilinx development software, the design can be downloaded using the iMPACT programming software and the USB cable.

To begin programming, connect the USB cable to the starter kit board and apply power to the board. Then, double-click **`Configure Device (iMPACT)`** from within Project Navigator, as shown in Figure 4-5.

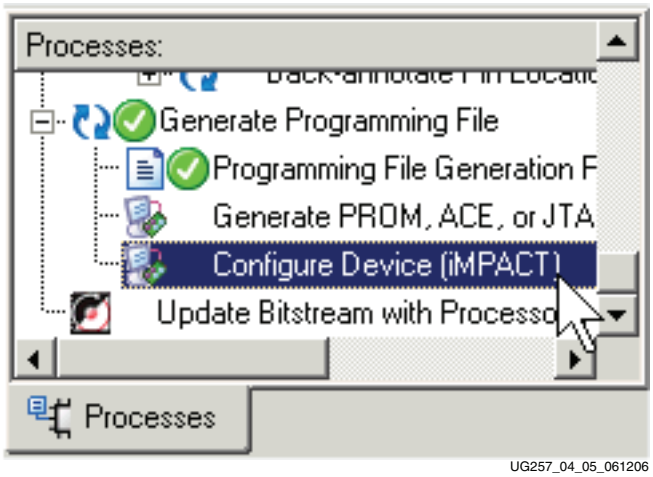



*Figure 4-5:* **Double-Click to Invoke iMPACT**

If the board is connected properly, the iMPACT programming software automatically recognizes the three devices in the JTAG programming file, as shown in Figure 4-6. If not already prompted, click the first device in the chain, the Spartan-3E FPGA, to highlight it. Right-click the FPGA and select **`Assign New Configuration File`**. Select the desired FPGA configuration file and click **`OK`**.

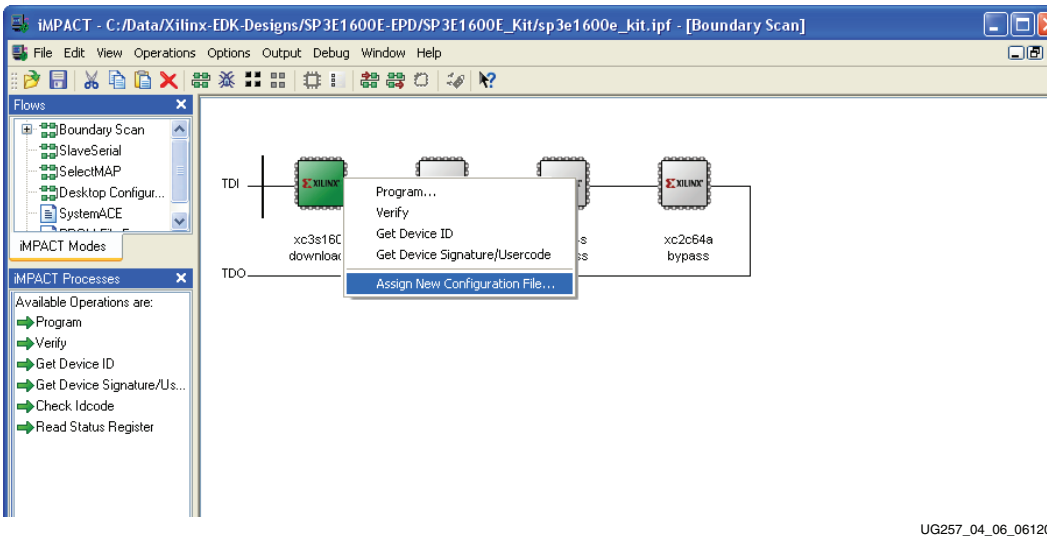



*Figure 4-6:* **Right-Click to Assign a Configuration File to the Spartan-3E FPGA**

If the original FPGA configuration file used the default StartUp clock source, CCLK, iMPACT issues the warning message shown in Figure 4-7. This message can be safely ignored. When downloading via JTAG, the iMPACT software must change the StartUP clock source to use the TCK JTAG clock source.

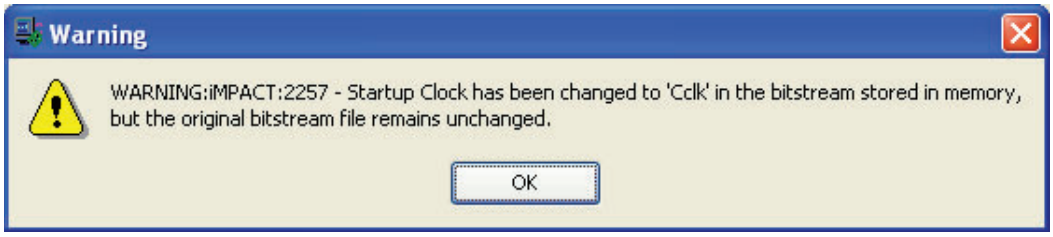



*Figure 4-7:* **iMPACT Issues a Warning if the StartUp Clock Was Not CCLK**

To start programming the FPGA, right-click the FPGA and select **`Program`**. The iMPACT software reports status during programming process. Direct programming to the FPGA takes a few seconds to less than a minute, depending on the speed of the PC's USB port and the iMPACT settings.

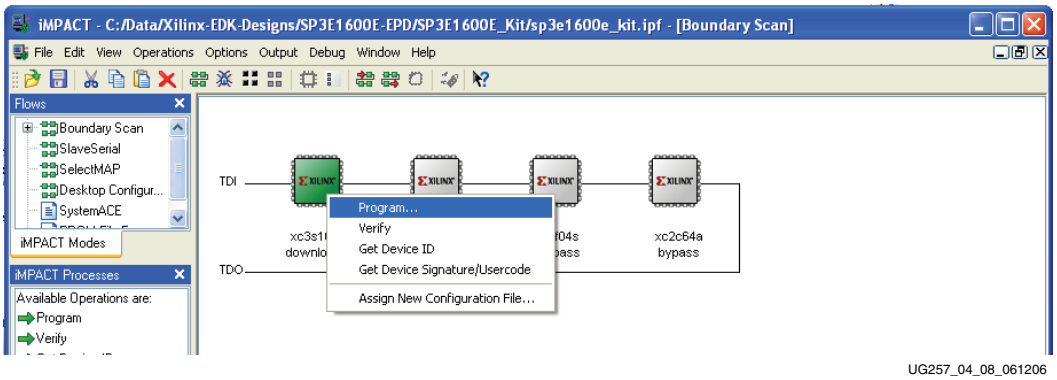



*Figure 4-8:* **Right-Click to Program the Spartan-3E FPGA**

When the FPGA successfully programs, the iMPACT software indicates success, as shown in Figure 4-9. The FPGA application is now executing on the board and the DONE pin LED (see Figure 4-2) lights up.

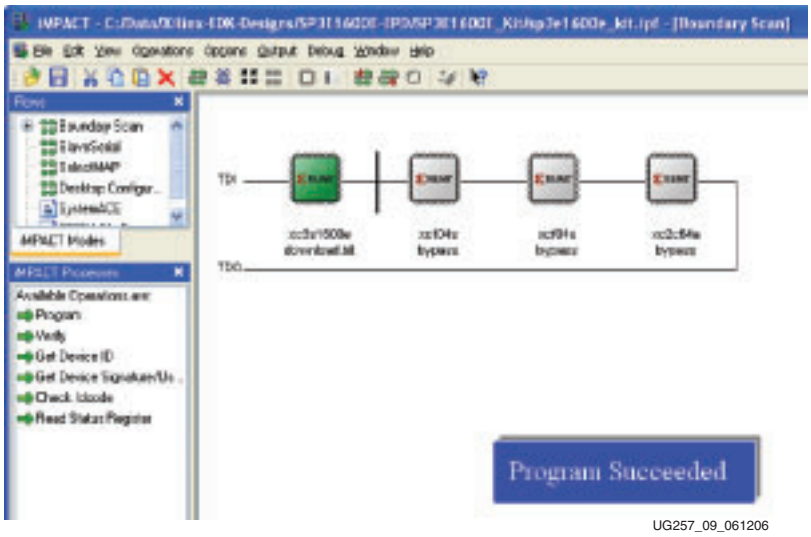



*Figure 4-9:* **iMPACT Programming Succeeded, the FPGA's DONE Pin is High**

## Programming Platform Flash PROM via USB

The on-board USB-JTAG circuitry also programs the two Xilinx XCF04S serial Platform Flash PROM. The steps provided in this section describe how to set up the PROM file and how to download it to the board to ultimately program the FPGA.

### Generating the FPGA Configuration Bitstream File

Before generating the PROM file, create the FPGA bitstream file. The FPGA provides an output clock, CCLK, when loading itself from an external PROM. The FPGA's internal CCLK oscillator always starts at its slowest setting, approximately 1.5 MHz. Most external PROMs support a higher frequency. Increase the CCLK frequency as appropriate to reduce the FPGA's configuration time. The Xilinx XCF04S Platform Flash supports a 25 MHz CCLK frequency.

Right-click **`Generator Programming File`** in the Processes pane, as shown in Figure 4-10. Left-click **`Properties`**.

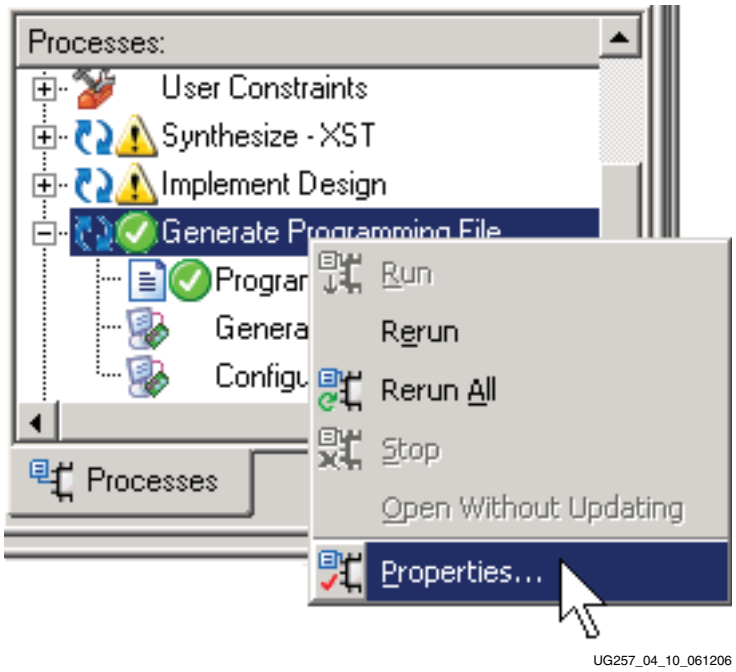



*Figure 4-10:* **Set Properties for Bitstream Generator**

Click **`Configuration Options`** as shown in Figure 4-11. Using the **`Configuration Rate`** drop list, choose **`25`** to increase the internal CCLK oscillator to approximately 25 MHz, the fastest frequency when using an XCF04S Platform Flash PROM. Click **`OK`** when finished.

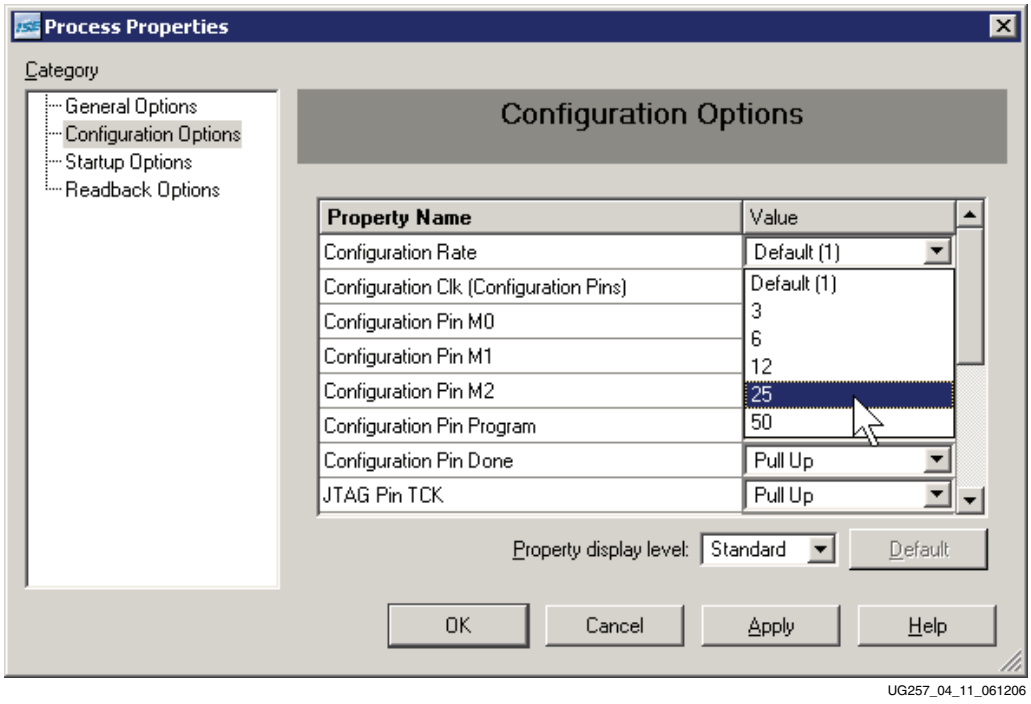



*Figure 4-11:* **Set CCLK Configuration Rate under Configuration Options**

To regenerate the programming file, double-click **`Generate Programming File`**, as shown in Figure 4-12.

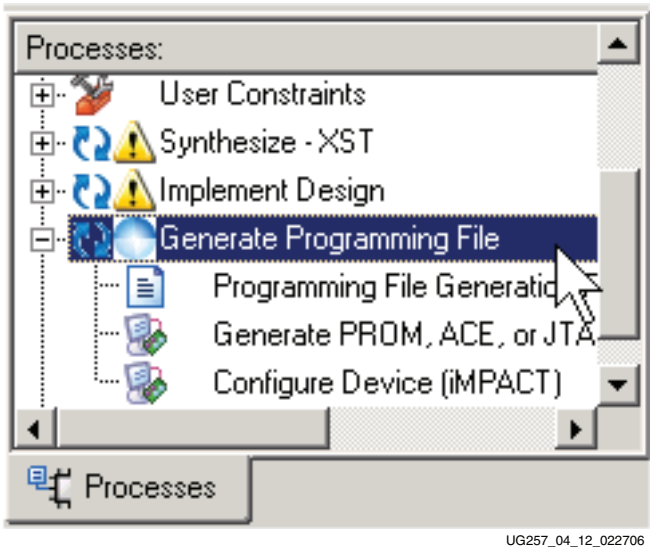



*Figure 4-12:* **Double-Click Generate Programming File**

## Generating the PROM File

After generating the program file, double-click **`Generate PROM, ACE, or JTAG File`** to launch the iMPACT software, as shown in Figure 4-13.

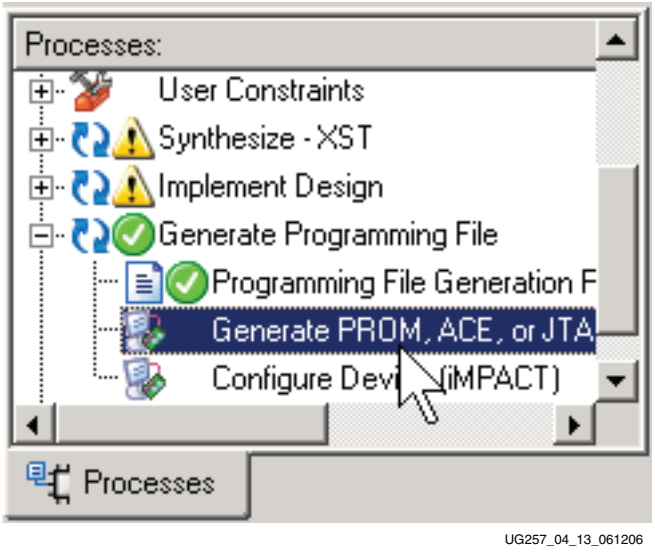



*Figure 4-13:* **Double-Click Generate PROM, ACE, or JTAG File**

After iMPACT starts, double-click **`PROM File Formatter`**, as shown in Figure 4-14.

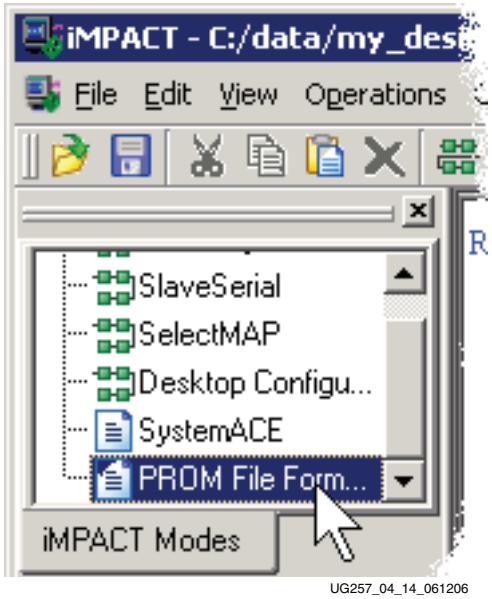



*Figure 4-14:* **Double-Click PROM File Formatter**

Choose **`Xilinx PROM`** as the target PROM type, as shown in Figure 4-15. Select from any of the PROM File Formats; the Intel Hex format (**`MCS`**) is popular. Enter the **`Location`** of the directory and the **`PROM File Name`**. Click **`Next >`** when finished.

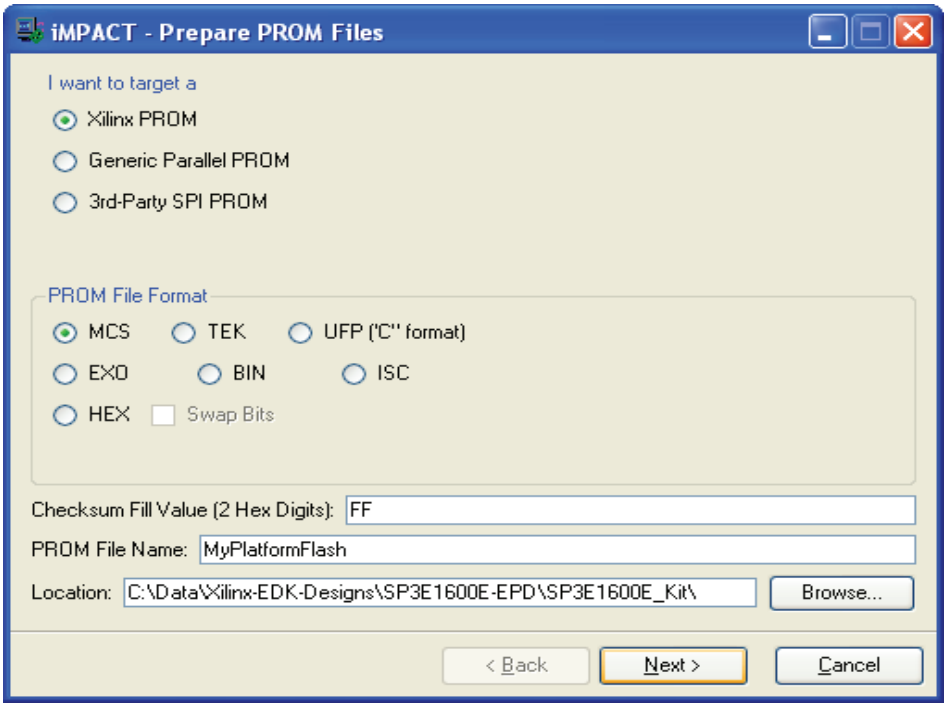



*Figure 4-15:* **Choose the PROM Target Type, the, Data Format, and File Location**

The Spartan-3E Starter Kit board has an XCF04S Platform Flash PROM. Select **`xcf04s`** from the drop list, as shown in Figure 4-16. Click **`Add`**, then click **`Next >`**.

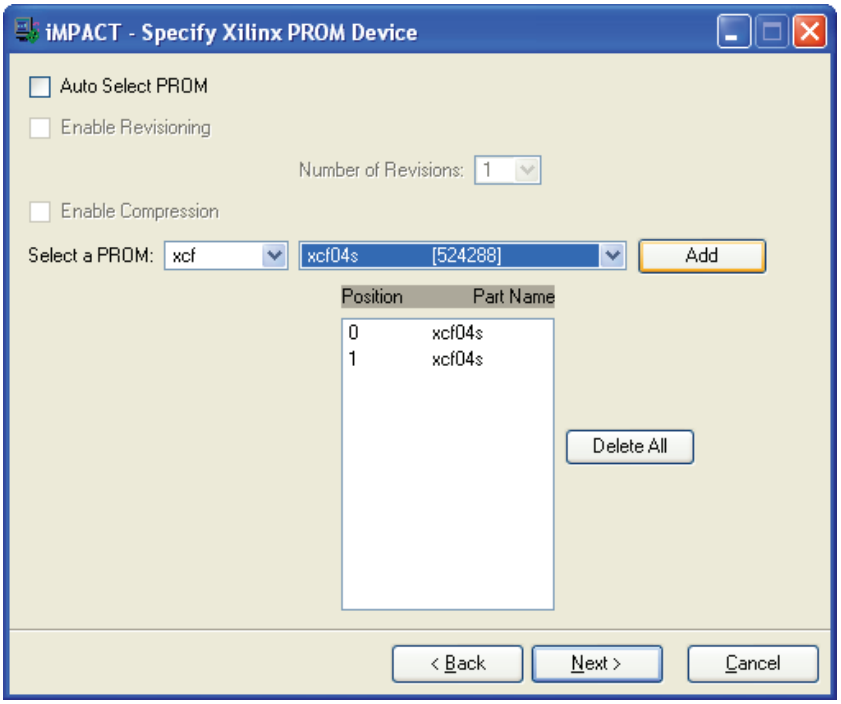



*Figure 4-16:* **Choose the XCF04S Platform Flash PROM**

The PROM Formatter then echoes the settings, as shown in Figure 4-17. Click **`Finish`**.

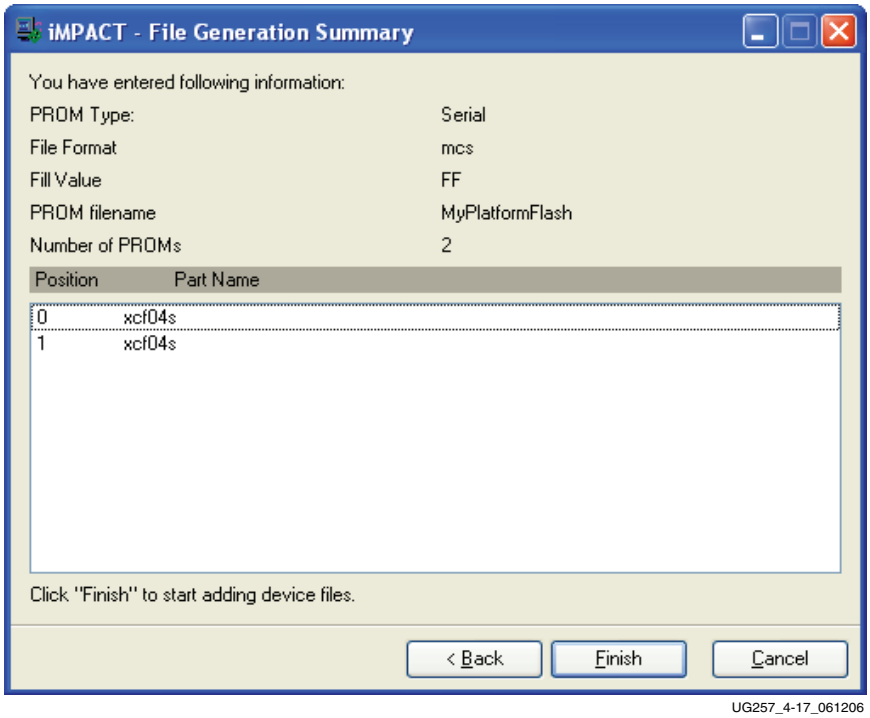



*Figure 4-17:* **Click Finish after Entering PROM Formatter Settings**

The PROM Formatter then prompts for the name(s) of the FPGA configuration bitstream file. As shown in Figure 4-18, click **OK** to start selecting files. Select an FPGA bitstream file (*.bit). Choose **No** after selecting the last FPGA file. Finally, click **OK** to continue.

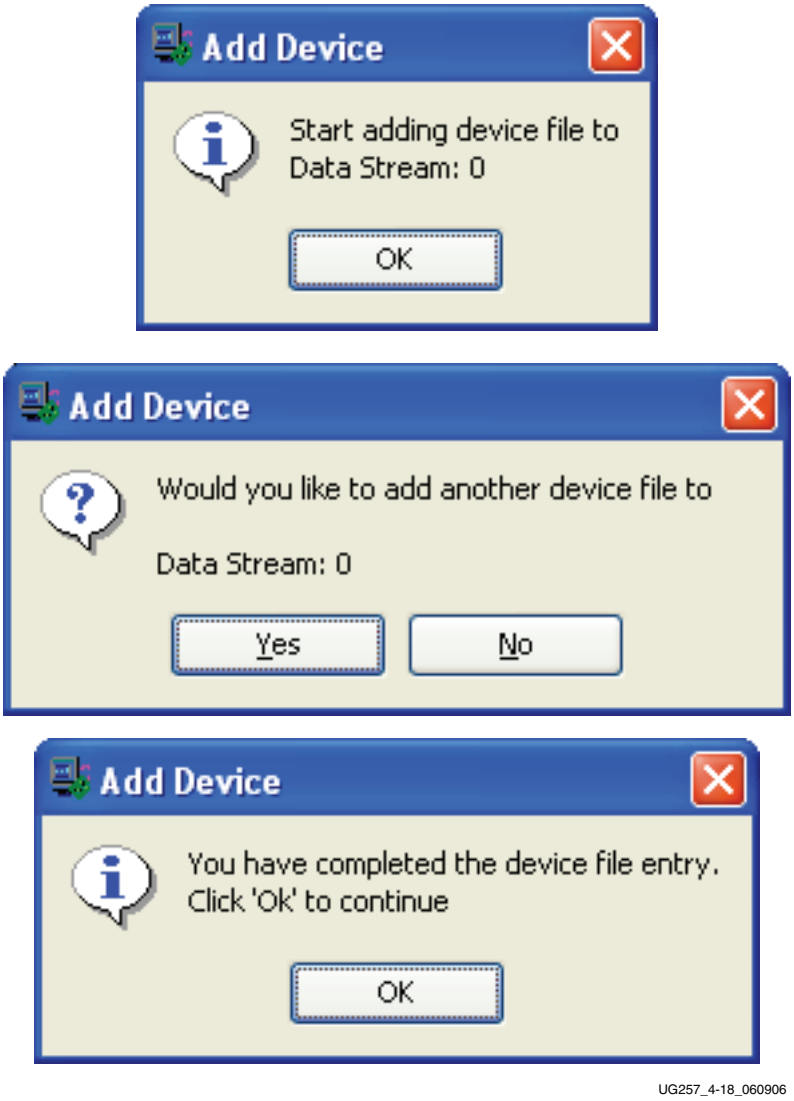



*Figure 4-18:* **Enter FPGA Configuration Bitstream File(s)**

When PROM formatting is complete, the iMPACT software presents the present settings by showing the PROM, the select FPGA bitstream(s), and the amount of PROM space consumed by the bitstream. Figure 4-19 shows an example for a single XC3S500E FPGA bitstream stored in an XCF04S Platform Flash PROM.

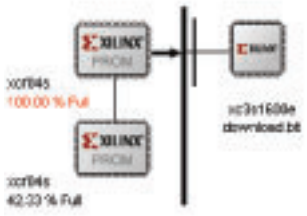



*Figure 4-19:* **PROM Formatting Completed**

To generate the actual PROM file, click **`Operations`** → **`Generate File`** as shown in Figure 4-20.

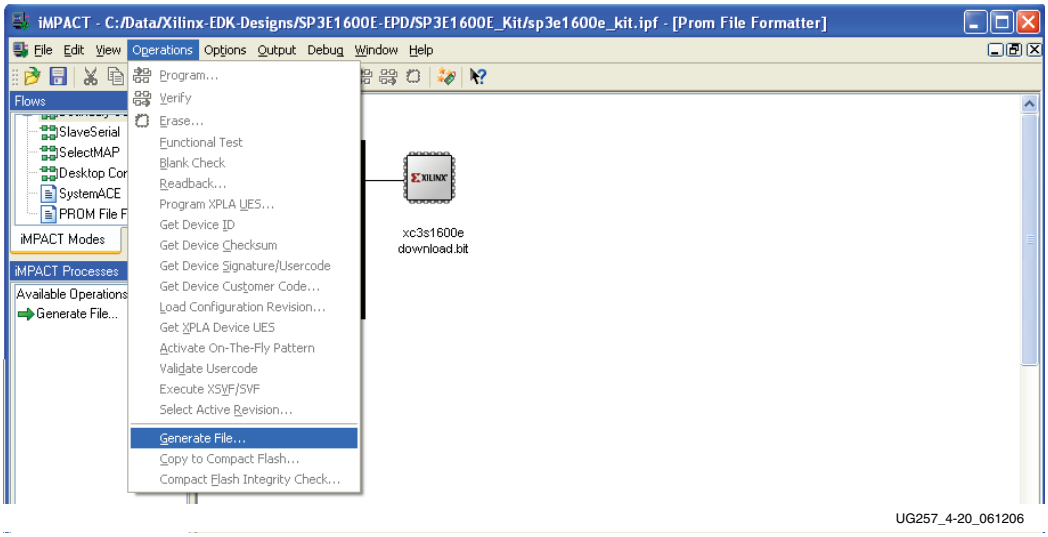



*Figure 4-20:* **Click Operations → Generate File to Create the Formatted PROM File**

The iMPACT software indicates that the PROM file was successfully created, as shown in Figure 4-21.

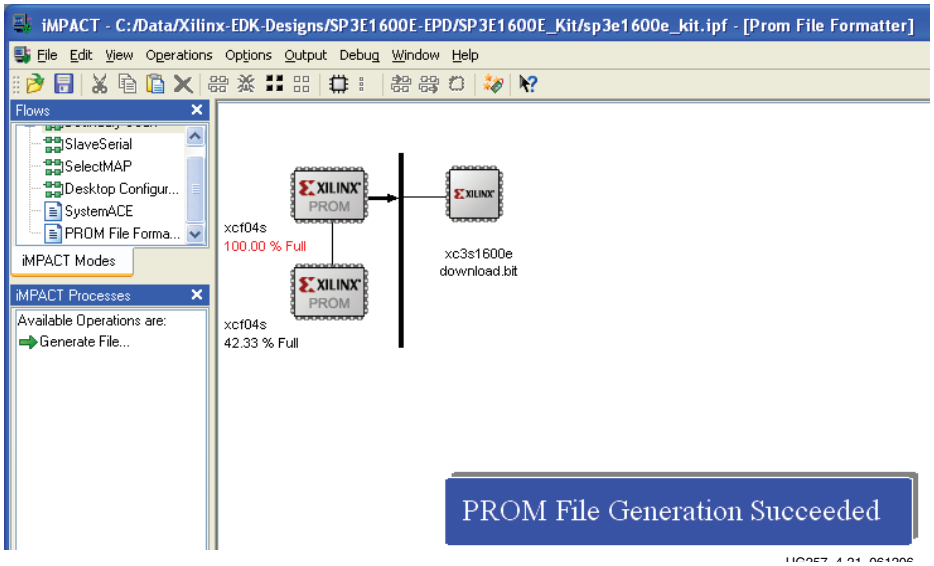



*Figure 4-21:* **PROM File Formatter Succeeded**

## Programming the Platform Flash PROM

To program the formatted PROM file into the Platform Flash PROM via the on-board USB-JTAG circuitry, follow the steps outlined in this subsection.

Place the iMPACT software in the JTAG Boundary Scan mode, either by choosing **`Boundary Scan`** in the iMPACT Modes pane, as shown in Figure 4-22, or by clicking on the **`Boundary Scan`** tab.

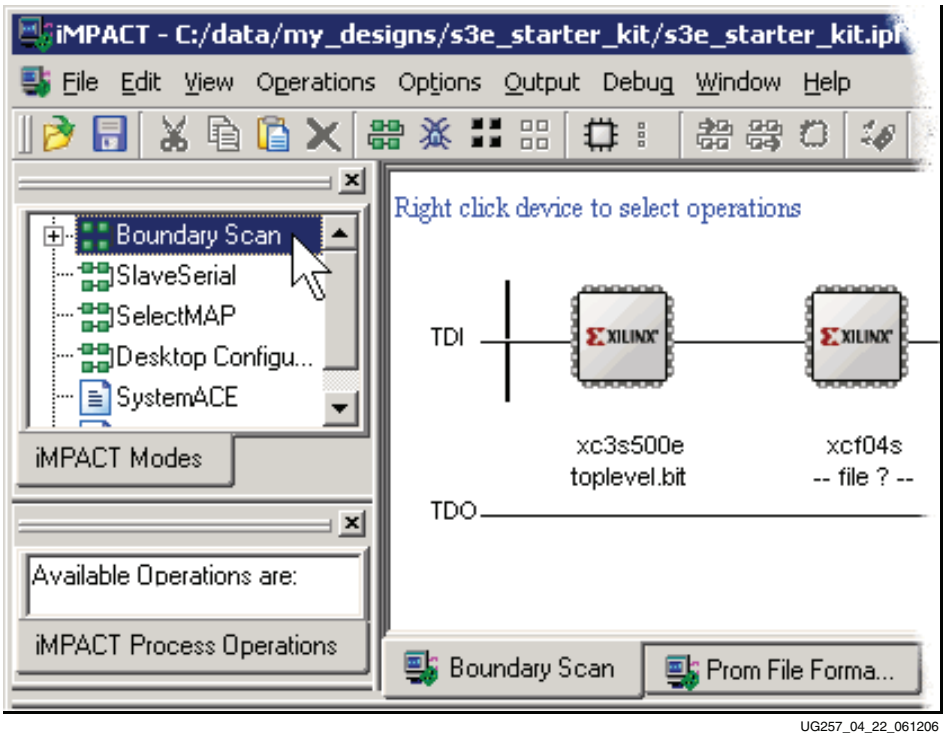



*Figure 4-22:* **Switch to Boundary Scan Mode**

Assign the PROM file to the XCF04S Platform Flash PROM on the JTAG chain, as shown in Figure 4-23. Right-click the PROM icon, then click **`Assign New Configuration File`**. Select a previously generated PROM format file and click **`OK`**.

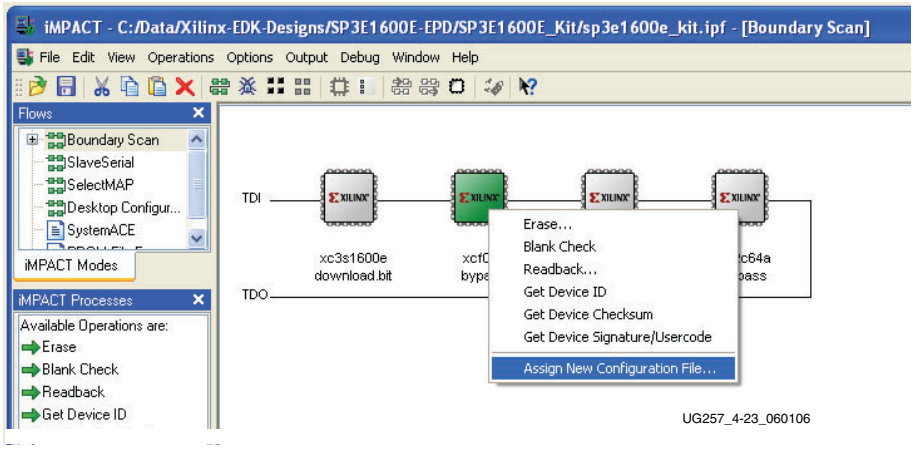



*Figure 4-23:* **Assign the PROM File to the XCF04S Platform Flash PROM**

To start programming the PROM, right-click the PROM icon and then click **`Program`**..

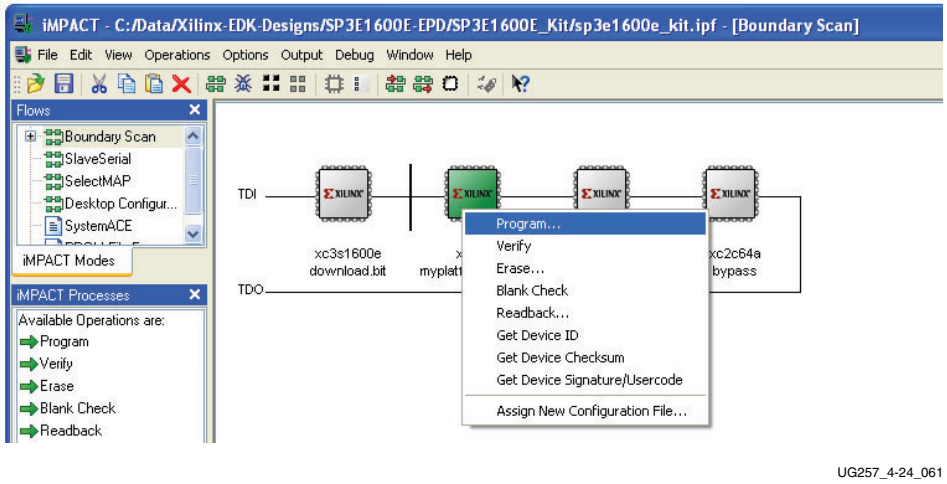



*Figure 4-24:* **Program the XCF04S Platform Flash PROM**

The programming software again prompts for the PROM type to be programmed. Select **`xcf04s`** and click **`OK`**, as shown in Figure 4-25.

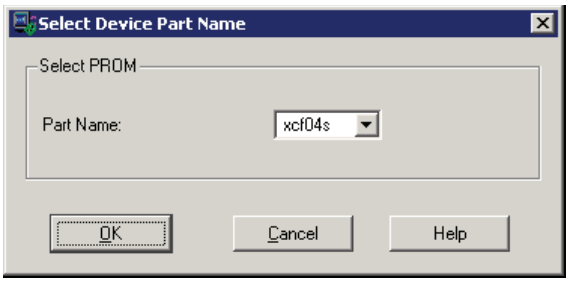



*Figure 4-25:* **Select XCF04S Platform Flash PROM**

Before programming, choose the programming options available in Figure 4-26. Checking the **Erase Before Programming** option erases the Platform Flash PROM completely before programming, ensuring that no previous data lingers. The **Verify** option checks that the PROM was correctly programmed and matches the downloaded configuration bitstream. Both these options are recommended even though they increase overall programming time.

The **Load FPGA** option immediately forces the FPGA to reconfigure after programming the Platform Flash PROM. The FPGA's configuration mode pins must be set for Master Serial mode, as defined in Table 4-1, page 25. Click **OK** when finished.

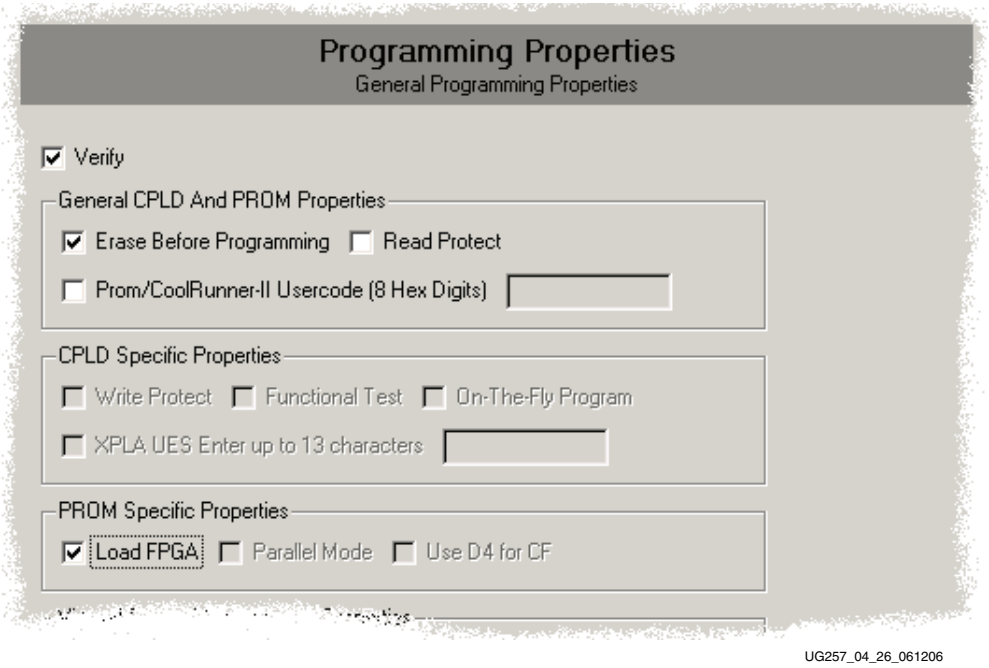



*Figure 4-26:* **PROM Programming Options**

The iMPACT software indicates if programming was successful or not. If programming was successful and the Load FPGA option was left unchecked, push the PROG_B push-button switch shown in Figure 4-2, page 24 to force the FPGA to reconfigure from the newly programmed Platform Flash PROM. If the FPGA successfully configures, the DONE LED, also shown in Figure 4-2, lights up.

Chapter 5

# Character LCD Screen

## Overview

The Spartan-3E MicroBlaze Development Kit board has been designed with a 16 pin female header connector. The Spartan-3E MicroBlaze Development board is shipped with a 2x16 LCD display attached, but any standard LCD display can be attached to this connector.

The Spartan-3E MicroBlaze Development Kit board prominently features a 2-line by 16-character liquid crystal display (LCD). The FPGA controls the LCD via the 4-bit data interface or 8 bit data interface in shown Figure 5-1.

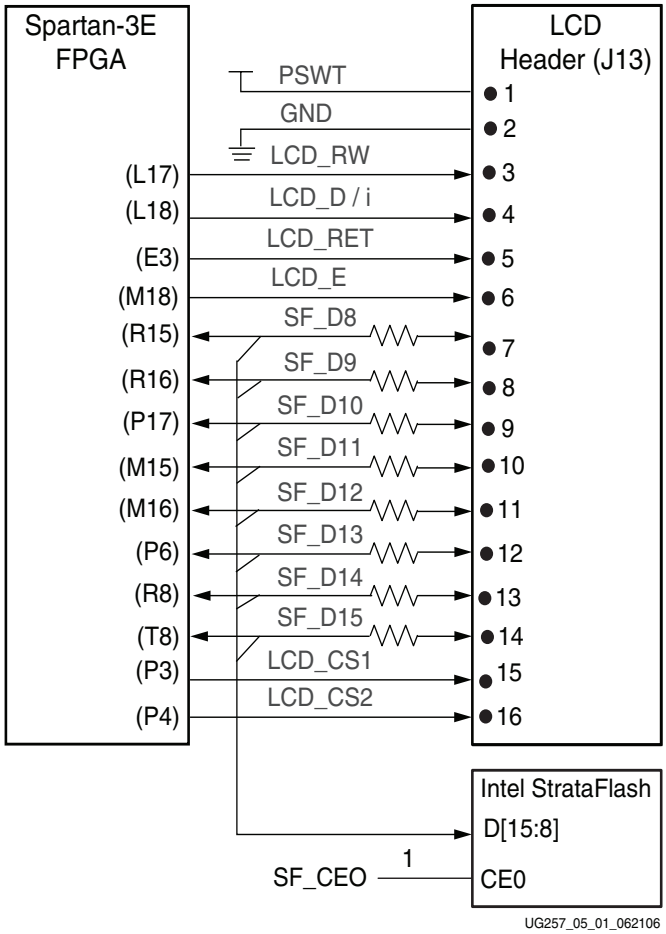



*Figure 5-1:* **Character LCD Interface**

Once mastered, the LCD is a practical way to display a variety of information using standard ASCII and custom characters. However, these displays are not fast. Scrolling the display at half-second intervals tests the practical limit for clarity. Compared with the 50 MHz clock available on the board, the display is slow. A PicoBlaze processor efficiently controls display timing plus the actual content of the display.

# Character LCD Interface Signals

Table 5-1 shows the interface character LCD interface signals.

*Table 5-1:* **Character LCD Interface**

| Signal Name | FPGA Pin | Function | |
|---|---|---|---|
| SF_D<15> | T8 | Data bit DB7 | Shared with StrataFlash pins SF_D<15:8> |
| SF_D<14> | R8 | Data bit DB6 | |
| SF_D<13> | P6 | Data bit DB5 | |
| SF_D<12> | M16 | Data bit DB4 | |
| SF_D<11> | M15 | Data bit DB3 | |
| SF_D<10> | P17 | Data bit DB2 | |
| SF_D<9> | R16 | Data bit DB1 | |
| SF_D<8> | R15 | Data bit DB0 | |
| LCD_E | M18 | Read/Write Enable Pulse<br>0: Disabled<br>1: Read/Write operation enabled | |
| LCD_RS | L18 | Register Select<br>0: Instruction register during write operations. Busy Flash during read operations<br>1: Data for read or write operations | |
| LCD_RW | L17 | Read/Write Control<br>0: WRITE, LCD accepts data<br>1: READ, LCD presents data | |
| LCD_RET | E3 | | |
| LCD_CS1 | P3 | | |
| LCD_CS2 | P4 | | |

# Voltage Compatibility

The character LCD is power by +5V. The FPGA I/O signals are powered by 3.3V. However, the FPGA's output levels are recognized as valid Low or High logic levels by the LCD. The LCD controller accepts 5V TTL signal levels and the 3.3V LVCMOS outputs provided by the FPGA meet the 5V TTL voltage level requirements.

The 390Ω series resistors on the data lines prevent overstressing on the FPGA and StrataFlash I/O pins when the character LCD drives a High logic value. The character LCD drives the data lines when LCD_RW is High. Most applications treat the LCD as a write-only peripheral and never read from from the display.

# Interaction with Intel StrataFlash

As shown in Figure 5-1, the four LCD data signals are also shared with StrataFlash data lines SF_D<11:8>. As shown in Table 5-2, the LCD/StrataFlash interaction depends on the application usage in the design. When the StrataFlash memory is disabled (SF_CE0 = High), then the FPGA application has full read/write access to the LCD. Conversely, when LCD read operations are disabled (LCD_RW = Low), then the FPGA application has full read/write access to the StrataFlash memory

*Table 5-2:* **LCD/StrataFlash Control Interaction**

| SF_CE0 | SF_BYTE | LCD_RW | Operation |
|---|---|---|---|
| 1 | X | X | StrataFlash disabled. Full read/write access to LCD. |
| X | X | 0 | LCD write access only. Full access to StrataFlash. |
| X | 0 | X | StrataFlash in byte-wide (x8) mode. Upper address lines are not used. Full access to both LCD and StrataFlash. |

**Notes:**

1. 'X' indicates a don't care, can be either 0 or 1.

If the StrataFlash memory is in byte-wide (x8) mode (SF_BYTE = Low), the FPGA application has full simultaneous read/write access to both the LCD and the StrataFlash memory. In byte-wide mode, the StrataFlash memory does not use the SF_D<15:8> data lines.

# UCF Location Constraints

Figure 5-2 provides the UCF constraints for the Character LCD, including the I/O pin assignment and the I/O standard used.

```
# ==== Character LCD (LCD) ====
NET "LCD_E" LOC = "M18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_DI" LOC = "L18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_RW" LOC = "L17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_RET" LOC = "E3" | IOSTANDARD = SSTL2_I ;
NET "LCD_CS1" LOC = "P3" | IOSTANDARD = SSTL2_I ;
NET "LCD_CS2" LOC = "P4" | IOSTANDARD = SSTL2_I ;

# LCD data connections are shared with StrataFlash connections SF_D<15:8>
NET "SF_D<8>" LOC = "R15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<9>" LOC = "R16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<10>" LOC = "P17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<11>" LOC = "M15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<12>" LOC = "M16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<13>" LOC = "P6" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<14>" LOC = "R8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<15>" LOC = "T8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
```

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*Figure 5-2:* **UCF Location Constraints for the Character LCD**

# LCD Controller

The 2 x 16 character LCD has an internal Sitronix ST7066U graphics controller that is functionally equivalent with the following devices.

- Samsung S6A0069X or KS0066U
- Hitachi HD44780
- SMOS SED1278

## Memory Map

The controller has three internal memory regions, each with a specific purpose. The display must be initialized before accessing any of these memory regions.

### DD RAM

The Display Data RAM (DD RAM) stores the character code to be displayed on the screen. Most applications interact primarily with DD RAM. The character code stored in a DD RAM location references a specific character bitmap stored either in the predefined CG ROM character set or in the user-defined CG RAM character set.

Figure 5-3shows the default address for the 32 character locations on the display. The upper line of characters is stored between addresses 0x00 and 0x0F. The second line of characters is stored between addresses 0x40 and 0x4F.

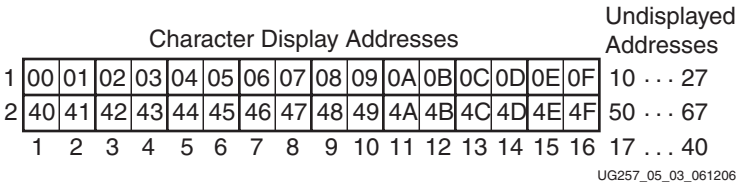


*Figure 5-3:* **DD RAM Hexadecimal Addresses (No Display Shifting)**

Physically, there are 80 total character locations in DD RAM with 40 characters available per line. Locations 0x10 through 0x27 and 0x50 through 0x67 can be used to store other non-display data. Alternatively, these locations can also store characters that can only displayed using controller's display shifting functions.

The Set DD RAM Address command initializes the address counter before reading or writing to DD RAM. Write DD RAM data using the Write Data to CG RAM or DD RAM command, and read DD RAM using the Read Data from CG RAM or DD RAM command.

The DD RAM address counter either remains constant after read or write operations, or auto-increments or auto-decrements by one location, as defined by the I/D set by the Entry Mode Set command.

### CG ROM

The Character Generator ROM (CG ROM) contains the font bitmap for each of the predefined characters that the LCD screen can display, shown in Figure 5-4. The character code stored in DD RAM for each character location subsequently references a position with the CG ROM. For example, a hexadecimal character code of 0x53 stored in a DD RAM location displays the character 'S'. The upper nibble of 0x53 equates to DB[7:4]="0101"

binary and the lower nibble equates to DB[3:0] = “0011” binary. As shown in Figure 5-4, the character ‘S’ appears on the screen.

English/Roman characters are stored in CG ROM at their equivalent ASCII code address.

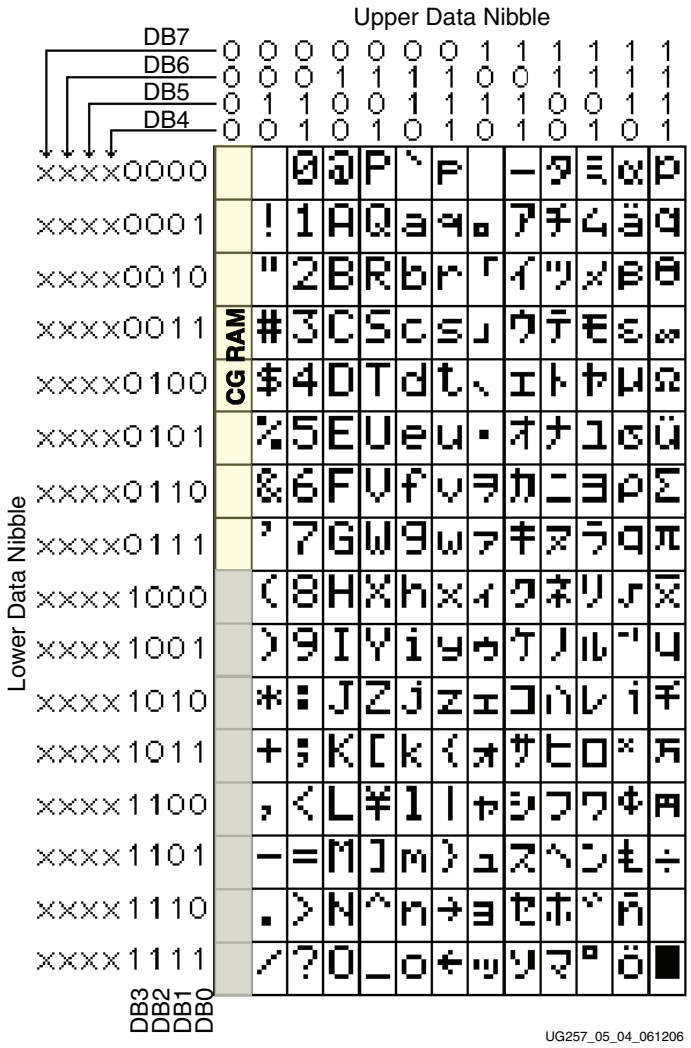


*Figure 5-4:* **LCD Character Set**

The character ROM contains the ASCII English character set and Japanese kana characters.

The controller also provides for eight custom character bitmaps, stored in CG RAM. These eight custom characters are displayed by storing character codes 0x00 through 0x07 in a DD RAM location.

## CG RAM

The Character Generator RAM (CG RAM) provides space to create eight custom character bitmaps. Each custom character location consists of a 5-dot by 8-line bitmap, as shown in Figure 5-5.

The Set CG RAM Address command initializes the address counter before reading or writing to CG RAM. Write CG RAM data using the Write Data to CG RAM or DD RAM command, and read CG RAM using the Read Data from CG RAM or DD RAM command.

The CG RAM address counter can either remain constant after read or write operations, or auto-increments or auto-decrements by one location, as defined by the I/D set by the Entry Mode Set command.

Figure 5-5 provides an example, creating a special *checkerboard* character. The custom character is stored in the fourth CG RAM character location, which is displayed when a DD RAM location is 0x03. To write the custom character, the CG RAM address is first initialized using the Set CG RAM Address command. The upper three address bits point to the custom character location. The lower three address bits point to the row address for the character bitmap. The Write Data to CG RAM or DD RAM command is used to write each character bitmap row. A '1' lights a bit on the display. A '0' leaves the bit unlit. Only the lower five data bits are used; the upper three data bits are *don't care* positions. The eighth row of bitmap data is usually left as all zeros to accommodate the cursor.

| | | | | | | Upper Nibble | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | | | Lower Nibble | | | | | | | |
| | | | | | | Write Data to CG RAM or DD RAM | | | | | | | |
| A5 | A4 | A3 | A2 | A1 | A0 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| Character Addresses | | | Row Addresses | | | Don't Care | | | Character Bitmap | | | | |
| 0 | 1 | 1 | 0 | 0 | 0 | – | – | – | 0 | | 0 | | 0 |
| 0 | 1 | 1 | 0 | 0 | 1 | – | – | – | | 0 | | 0 | |
| 0 | 1 | 1 | 0 | 1 | 0 | – | – | – | 0 | | 0 | | 0 |
| 0 | 1 | 1 | 0 | 1 | 1 | – | – | – | | 0 | | 0 | |
| 0 | 1 | 1 | 1 | 0 | 0 | – | – | – | 0 | | 0 | | 0 |
| 0 | 1 | 1 | 1 | 0 | 1 | – | – | – | | 0 | | 0 | |
| 0 | 1 | 1 | 1 | 1 | 0 | – | – | – | 0 | | 0 | | 0 |
| 0 | 1 | 1 | 1 | 1 | 1 | – | – | – | 0 | 0 | 0 | 0 | 0 |

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*Figure 5-5:* **Example Custom Checkerboard Character with Character Code 0x03**

## Command Set

Table 5-3 summarizes the available LCD controller commands and bit definitions. Because the display is set up for 4-bit operation, each 8-bit command is sent as two 4-bit nibbles. The upper nibble is transferred first, followed by the lower nibble.

*Table 5-3:* **LCD Character Display Command Set**

| Function | LCD_RS | LCD_RW | Upper Nibble | | | | Lower Nibble | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
| Clear Display | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 |
| Return Cursor Home | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | - |
| Entry Mode Set | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | I/D | S |
| Display On/Off | 0 | 0 | 0 | 0 | 0 | 0 | 1 | D | C | B |
| Cursor and Display Shift | 0 | 0 | 0 | 0 | 0 | 1 | S/C | R/L | - | - |
| Function Set | 0 | 0 | 0 | 0 | 1 | 0 | 1 | 0 | - | - |

*Table 5-3:* **LCD Character Display Command Set *(Continued)***

| Function | LCD_RS | LCD_RW | Upper Nibble | | | | Lower Nibble | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
| Set CG RAM Address | 0 | 0 | 0 | 1 | A5 | A4 | A3 | A2 | A1 | A0 |
| Set DD RAM Address | 0 | 0 | 1 | A6 | A5 | A4 | A3 | A2 | A1 | A0 |
| Read Busy Flag and Address | 0 | 1 | BF | A6 | A5 | A4 | A3 | A2 | A1 | A0 |
| Write Data to CG RAM or DD RAM | 1 | 0 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| Read Data from CG RAM or DD RAM | 1 | 1 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |

## Disabled

If the LCD_E enable signal is Low, all other inputs to the LCD are ignored.

## Clear Display

Clear the display and return the cursor to the home position, the top-left corner.

This command writes a blank space (ASCII/ANSI character code 0x20) into all DD RAM addresses. The address counter is reset to 0, location 0x00 in DD RAM. Clears all option settings. The I/D control bit is set to 1 (increment address counter mode) in the Entry Mode Set command.

Execution Time: 82 µs – 1.64 ms

## Return Cursor Home

Return the cursor to the home position, the top-left corner. DD RAM contents are unaffected. Also returns the display being shifted to the original position, shown in Figure 5-3.

The address counter is reset to 0, location 0x00 in DD RAM. The display is returned to its original status if it was shifted. The cursor or blink move to the top-left character location.

Execution Time: 40 µs – 1.6 ms

## Entry Mode Set

Sets the cursor move direction and specifies whether or not to shift the display.

These operations are performed during data reads and writes.

Execution Time: 40 µs

### Bit DB1: (I/D) Increment/Decrement

| | |
|---|---|
| 0 | Auto-decrement address counter. Cursor/blink moves to left. |
| 1 | Auto-increment address counter. Cursor/blink moves to right. |

This bit either auto-increments or auto-decrements the DD RAM and CG RAM address counter by one location after each Write Data to CG RAM or DD RAM or Read Data from CG RAM or DD RAM command. The cursor or blink position moves accordingly.

### Bit DB0: (S) Shift

| | |
|---|---|
| 0 | Shifting disabled |
| 1 | During a DD RAM write operation, shift the entire display value in the direction controlled by Bit DB1 (I/D). Appears as though the cursor position remains constant and the display moves. |

## Display On/Off

Display is turned on or off, controlling all characters, cursor and cursor position character (underscore) blink.

Execution Time: 40 µs

### Bit DB2: (D) Display On/Off

| | |
|---|---|
| 0 | No characters displayed. However, data stored in DD RAM is retained |
| 1 | Display characters stored in DD RAM |

### Bit DB1: (C) Cursor On/Off

The cursor uses the five dots on the bottom line of the character. The cursor appears as a line under the displayed character.

| | |
|---|---|
| 0 | No cursor |
| 1 | Display cursor |

### Bit DB0: (B) Cursor Blink On/Off

| | |
|---|---|
| 0 | No cursor blinking |
| 1 | Cursor blinks on and off approximately every half second |

## Cursor and Display Shift

Moves the cursor and shifts the display without changing DD RAM contents. Shift cursor position or display to the right or left without writing or reading display data.

This function positions the cursor in order to modify an individual character, or to scroll the display window left or right to reveal additional data stored in the DD RAM, beyond the 16th character on a line. The cursor automatically moves to the second line when it shifts beyond the 40th character location of the first line. The first and second line displays shift at the same time.

When the displayed data is shifted repeatedly, both lines move horizontally. The second display line does not shift into the first display line.

Execution Time: 40 µs

*Table 5-4:* **Shift Patterns According to S/C and R/L Bits**

| DB3 (S/C) | DB2 (R/L) | Operation |
|---|---|---|
| 0 | 0 | Shift the cursor position to the left. The address counter is decremented by one. |
| 0 | 1 | Shift the cursor position to the right. The address counter is incremented by one. |
| 1 | 0 | Shift the entire display to the left. The cursor follows the display shift. The address counter is unchanged. |
| 1 | 1 | Shift the entire display to the right. The cursor follows the display shift. The address counter is unchanged. |

### Function Set

Sets interface data length, number of display lines, and character font.

The Starter Kit board supports a single function set with value 0x28.

Execution Time: 40 µs

### Set CG RAM Address

Set the initial CG RAM address.

After this command, all subsequent read or write operations to the display are to or from CG RAM.

Execution Time: 40 µs

### Set DD RAM Address

Set the initial DD RAM address.

After this command, all subsequentsubsequent read or write operations to the display are to or from DD RAM. The addresses for displayed characters appear in Figure 5-3.

Execution Time: 40 µs

### Read Busy Flag and Address

Read the Busy flag (BF) to determine if an internal operation is in progress, and read the current address counter contents.

BF = 1 indicates that an internal operation is in progress. The next instruction is not accepted until BF is cleared or until the current instruction is allowed the maximum time to execute.

This command also returns the present value of address counter. The address counter is used for both CG RAM and DD RAM addresses. The specific context depends on the most recent Set CG RAM Address or Set DD RAM Address command issued.

Execution Time: 1 µs

### Write Data to CG RAM or DD RAM

Write data into DD RAM if the command follows a previous Set DD RAM Address command, or write data into CG RAM if the command follows a previous Set CG RAM Address command.

After the write operation, the address is automatically incremented or decremented by 1 according to the Entry Mode Set command. The entry mode also determines display shift.

Execution Time: 40 µs

### Read Data from CG RAM or DD RAM

Read data from DD RAM if the command follows a previous Set DD RAM Address command, or read data from CG RAM if the command follows a previous Set CG RAM Address command.

After the read operation, the address is automatically incremented or decremented by 1 according to the Entry Mode Set command. However, a display shift is not executed during read operations.

Execution Time: 40 µs

# Operation

## Four-Bit Data Interface

The board uses a 4-bit data interface to the character LCD.

Figure 5-6 illustrates a write operation to the LCD, showing the minimum times allowed for setup, hold, and enable pulse length relative to the 50 MHz clock (20 ns period) provided on the board.

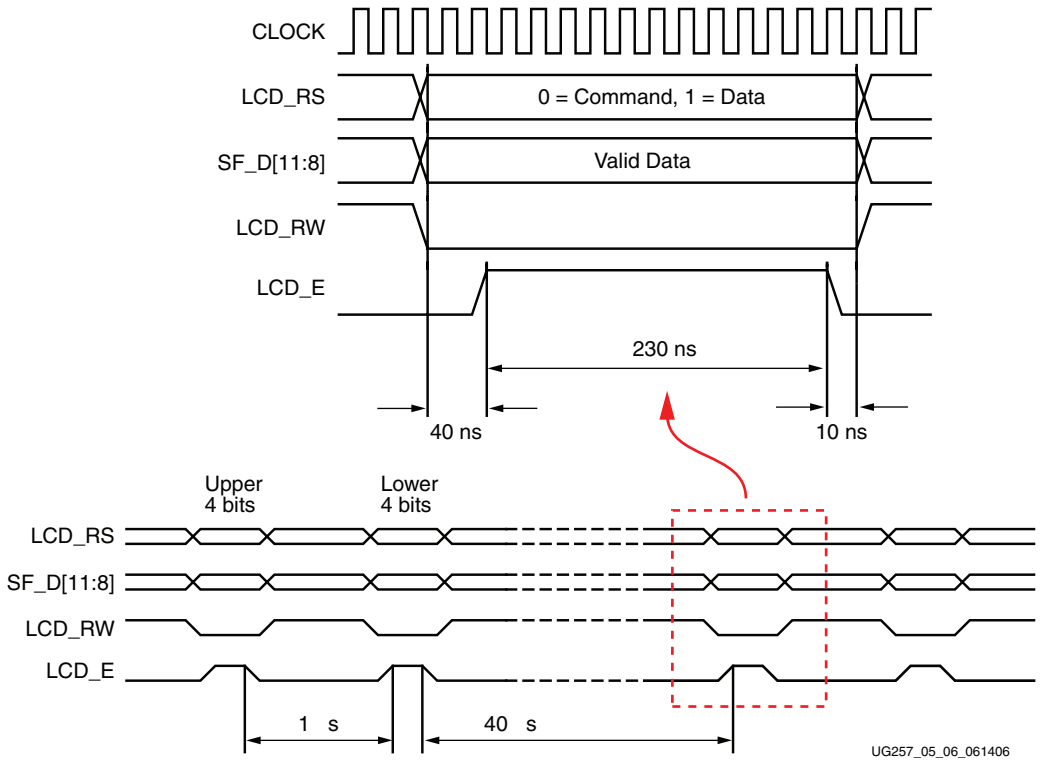


*Figure 5-6:* **Character LCD Interface Timing**

The data values on SF_D<11:8>, and the register select (LCD_RS) and the read/write (LCD_RW) control signals must be set up and stable at least 40 ns before the enable LCD_E goes High. The enable signal must remain High for 230 ns or longer—the equivalent of 12 or more clock cycles at 50 MHz.

In many applications, the LCD_RW signal can be tied Low permanently because the FPGA generally has no reason to read information from the display.

## Transferring 8-Bit Data over the 4-Bit Interface

After initializing the display and establishing communication, all commands and data transfers to the character display are via 8 bits, transferred using two sequential 4-bit operations. Each 8-bit transfer must be decomposed into two 4-bit transfers, spaced apart by at least 1 µs, as shown in Figure 5-6. The upper nibble is transferred first, followed by the lower nibble. An 8-bit write operation must be spaced least 40 µs before the next communication. This delay must be increased to 1.64 ms following a Clear Display command.

## Initializing the Display

After power-on, the display must be initialized to establish the required communication protocol. The initialization sequence is simple and ideally suited to the highly-efficient 8-bit PicoBlaze embedded controller. After initialization, the PicoBlaze controller is available for more complex control or computation beyond simply driving the display.

### Power-On Initialization

The initialization sequence first establishes that the FPGA application wishes to use the four-bit data interface to the LCD as follows:

- Wait 15 ms or longer, although the display is generally ready when the FPGA finishes configuration. The 15 ms interval is 750,000 clock cycles at 50 MHz.
- Write SF_D<11:8> = 0x3, pulse LCD_E High for 12 clock cycles.
- Wait 4.1 ms or longer, which is 205,000 clock cycles at 50 MHz.
- Write SF_D<11:8> = 0x3, pulse LCD_E High for 12 clock cycles.
- Wait 100 µs or longer, which is 5,000 clock cycles at 50 MHz.
- Write SF_D<11:8> = 0x3, pulse LCD_E High for 12 clock cycles.
- Wait 40 µs or longer, which is 2,000 clock cycles at 50 MHz.
- Write SF_D<11:8> = 0x2, pulse LCD_E High for 12 clock cycles.
- Wait 40 µs or longer, which is 2,000 clock cycles at 50 MHz.

### Display Configuration

After the power-on initialization is completed, the four-bit interface is now established. The next part of the sequence configures the display:

- Issue a Function Set command, 0x28, to configure the display for operation on the Spartan-3E Starter Kit board.
- Issue an Entry Mode Set command, 0x06, to set the display to automatically increment the address pointer.
- Issue a Display On/Off command, 0x0C, to turn the display on and disables the cursor and blinking.

- Finally, issue a Clear Display command. Allow at least 1.64 ms (82,000 clock cycles) after issuing this command.

### Writing Data to the Display

To write data to the display, specify the start address, followed by one or more data values.

Before writing any data, issue a Set DD RAM Address command to specify the initial 7-bit address in the DD RAM. See Figure 5-3 for DD RAM locations.

Write data to the display using a Write Data to CG RAM or DD RAM command. The 8-bit data value represents the look-up address into the CG ROM or CG RAM, shown in Figure 5-4. The stored bitmap in the CG ROM or CG RAM drives the 5 x 8 dot matrix to represent the associated character.

If the address counter is configured to auto-increment, as described earlier, the application can sequentially write multiple character codes and each character is automatically stored and displayed in the next available location.

Continuing to write characters, however, eventually falls off the end of the first display line. The additional characters do not automatically appear on the second line because the DD RAM map is not consecutive from the first line to the second.

### Disabling the Unused LCD

If the FPGA application does not use the character LCD screen, drive the LCD_E pin Low to disable it. Also drive the LCD_RW pin Low to prevent the LCD screen from presenting data.

## Related Resources

- Initial Design for Spartan-3E MicroBlaze Development Kit (Reference Design)
  http://www.xilinx.com/s3e1600e
- PowerTip PC1602-D Character LCD (Basic Electrical and Mechanical Data)
  http://www.powertipusa.com/pdf/pc1602d.pdf
- Sitronix ST7066U Character LCD Controller
  http://www.sitronix.com.tw/sitronix/product.nsf/Doc/ST7066U?OpenDocument
- Detailed Data Sheet on PowerTip Character LCD
  http://www.rapidelectronics.co.uk/images/siteimg/57-0910e.PDF
- Samsung S6A0069X Character LCD Controller
  http://www.samsung.com/Products/Semiconductor/DisplayDriverIC/MobileDDI/BWSTN/S6A0069X/S6A0069X.htm

Chapter 6

# VGA Display Port

The MicroBlaze Development Kit board includes a VGA display port via a J15 connector. Connect this port directly to most PC monitors or flat-panel LCDs using a standard monitor cable. As shown in Figure 6-1, the VGA connector is the left-most connector along the top of the board.

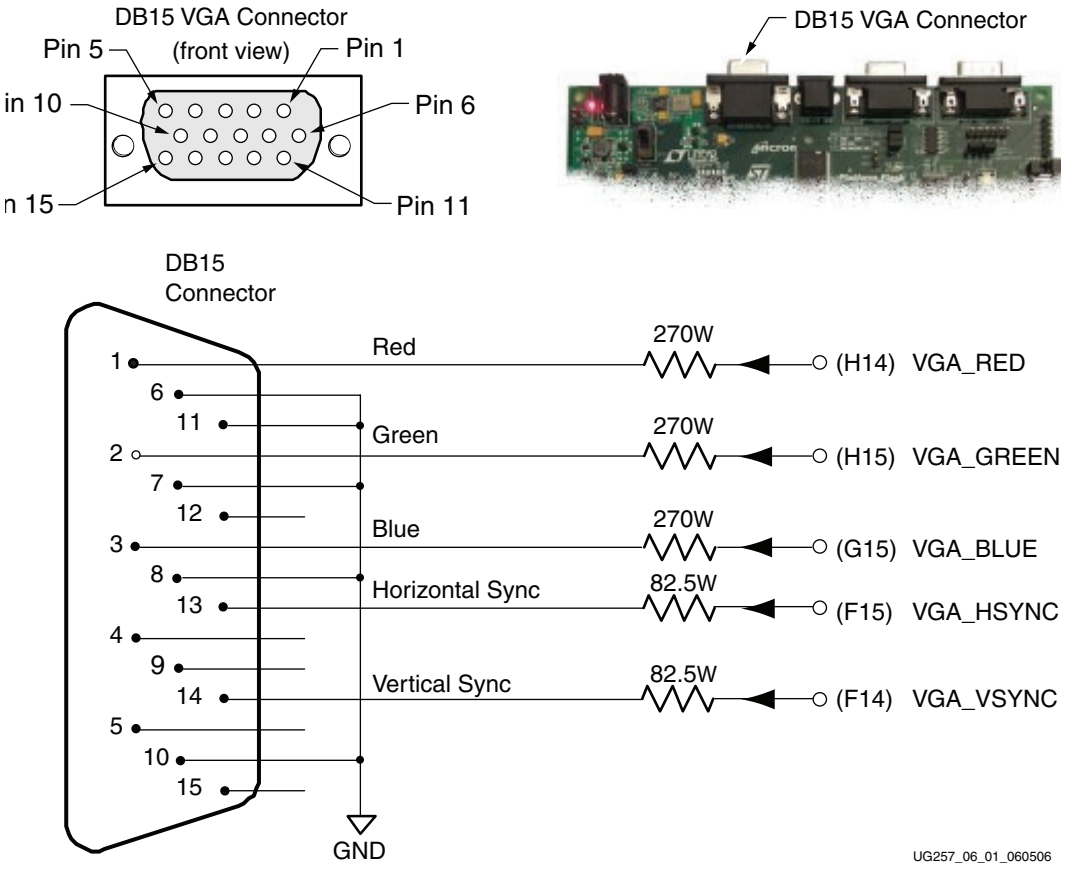


*Figure 6-1:* **VGA Connections from Spartan-3E Starter Kit Board**

The Spartan-3E FPGA directly drives the five VGA signals via resistors. Each color line has a series resistor, with one bit each for VGA_RED, VGA_GREEN, and VGA_BLUE. The series resistor, in combination with the 75Ω termination built into the VGA cable, ensures that the color signals remain in the VGA-specified 0V to 0.7V range. The VGA_HSYNC and VGA_VSYNC signals using LVTTL or LVCMOS33 I/O standard drive levels. Drive

the VGA_RED, VGA_GREEN, and VGA_BLUE signals High or Low to generate the eight colors shown in Table 6-1.

*Table 6-1:* **3-Bit Display Color Codes**

| VGA_RED | VGA_GREEN | VGA_BLUE | Resulting Color |
|---|---|---|---|
| 0 | 0 | 0 | Black |
| 0 | 0 | 1 | Blue |
| 0 | 1 | 0 | Green |
| 0 | 1 | 1 | Cyan |
| 1 | 0 | 0 | Red |
| 1 | 0 | 1 | Magenta |
| 1 | 1 | 0 | Yellow |
| 1 | 1 | 1 | White |

VGA signal timing is specified, published, copyrighted, and sold by the Video Electronics Standards Association (VESA). The following VGA system and timing information is provided as an example of how the FPGA might drive VGA monitor in 640 by 480 mode. For more precise information or for information on higher VGA frequencies, refer to documents available on the VESA website or other electronics websites (see "Related Resources," page 57).

## Signal Timing for a 60 Hz, 640x480 VGA Display

CRT-based VGA displays use amplitude-modulated, moving electron beams (or cathode rays) to display information on a phosphor-coated screen. LCDs use an array of switches that can impose a voltage across a small amount of liquid crystal, thereby changing light permittivity through the crystal on a pixel-by-pixel basis. Although the following description is limited to CRT displays, LCDs have evolved to use the same signal timings as CRT displays. Consequently, the following discussion pertains to both CRTs and LCDs.

Within a CRT display, current waveforms pass through the coils to produce magnetic fields that deflect electron beams to transverse the display surface in a *raster* pattern, horizontally from left to right and vertically from top to bottom. As shown in Figure 6-2, information is only displayed when the beam is moving in the *forward* direction—left to right and top to bottom—and not during the time the beam returns back to the left or top edge of the display. Much of the potential display time is therefore lost in *blanking* periods when the beam is reset and stabilized to begin a new horizontal or vertical display pass.

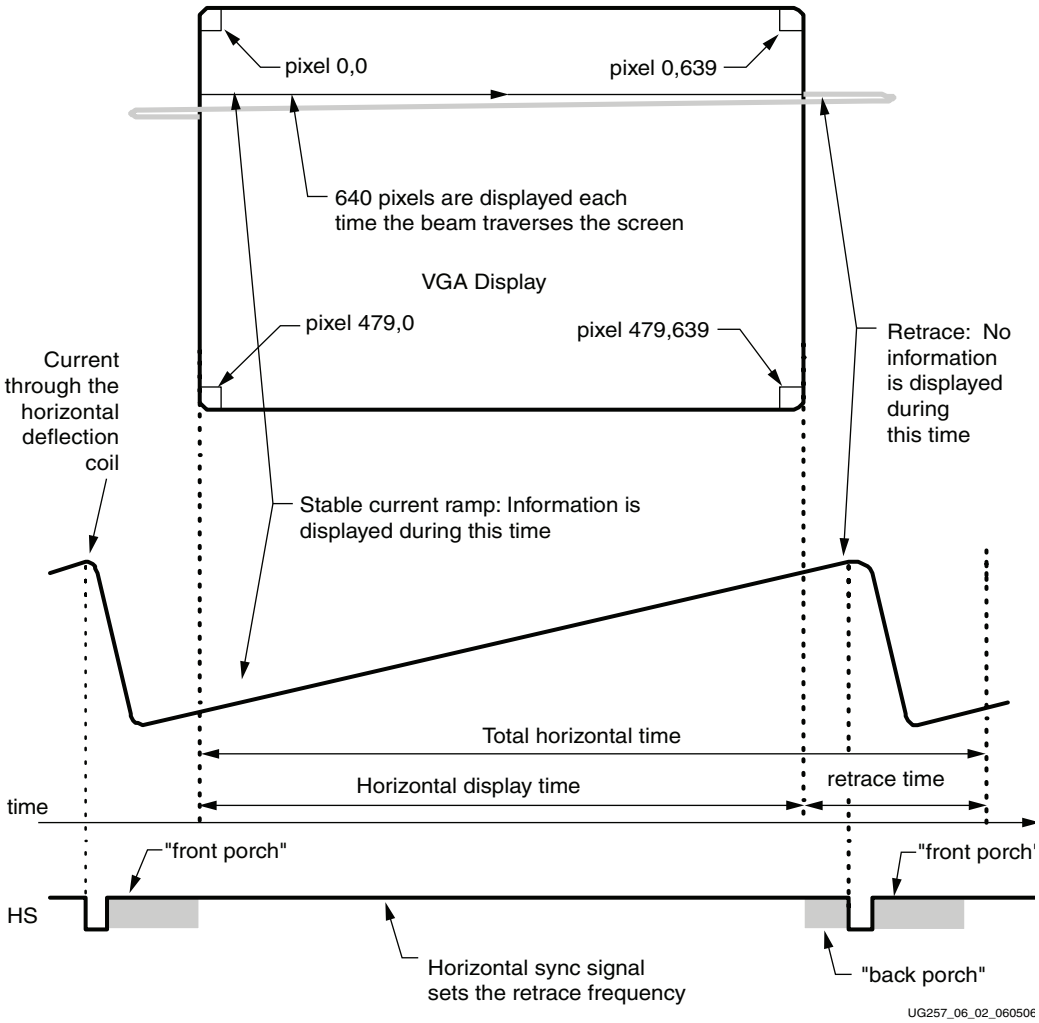


*Figure 6-2:* **CRT Display Timing Example**

The display resolution defines the size of the beams, the frequency at which the beam traces across the display, and the frequency at which the electron beam is modulated.

Modern VGA displays support multiple display resolutions, and the VGA controller dictates the resolution by producing timing signals to control the raster patterns. The controller produces TTL-level synchronizing pulses that set the frequency at which current flows through the deflection coils, and it ensures that pixel or video data is applied to the electron guns at the correct time.

Video data typically comes from a video refresh memory with one or more bytes assigned to each pixel location. The MicroBlaze Development Kit board uses three bits per pixel, producing one of the eight possible colors shown in Table 6-1. The controller indexes into the video data buffer as the beams move across the display. The controller then retrieves and applies video data to the display at precisely the time the electron beam is moving across a given pixel.

As shown in Figure 6-2, the VGA controller generates the horizontal sync (HS) and vertical sync (VS) timings signals and coordinates the delivery of video data on each pixel clock. The pixel clock defines the time available to display one pixel of information. The VS signal defines the *refresh* frequency of the display, or the frequency at which all information on the

display is redrawn. The minimum refresh frequency is a function of the display's phosphor and electron beam intensity, with practical refresh frequencies in the 60 Hz to 120 Hz range. The number of horizontal lines displayed at a given refresh frequency defines the horizontal *retrace* frequency.

# VGA Signal Timing

The signal timings in Table 6-2 are derived for a 640-pixel by 480-row display using a 25 MHz pixel clock and 60 Hz ± 1 refresh. Figure 6-3 shows the relation between each of the timing symbols. The timing for the sync pulse width ($T_{PW}$) and front and back porch intervals ($T_{FP}$ and $T_{BP}$) are based on observations from various VGA displays. The front and back porch intervals are the pre- and post-sync pulse times. Information cannot be displayed during these times.

*Table 6-2:* **640x480 Mode VGA Timing**

| Symbol | Parameter | Vertical Sync | | | Horizontal Sync | |
|---|---|---|---|---|---|---|
| | | Time | Clocks | Lines | Time | Clocks |
| $T_S$ | Sync pulse time | 16.7 ms | 416,800 | 521 | 32 µs | 800 |
| $T_{DISP}$ | Display time | 15.36 ms | 384,000 | 480 | 25.6 µs | 640 |
| $T_{PW}$ | Pulse width | 64 µs | 1,600 | 2 | 3.84 µs | 96 |
| $T_{FP}$ | Front porch | 320 µs | 8,000 | 10 | 640 ns | 16 |
| $T_{BP}$ | Back porch | 928 µs | 23,200 | 29 | 1.92 µs | 48 |

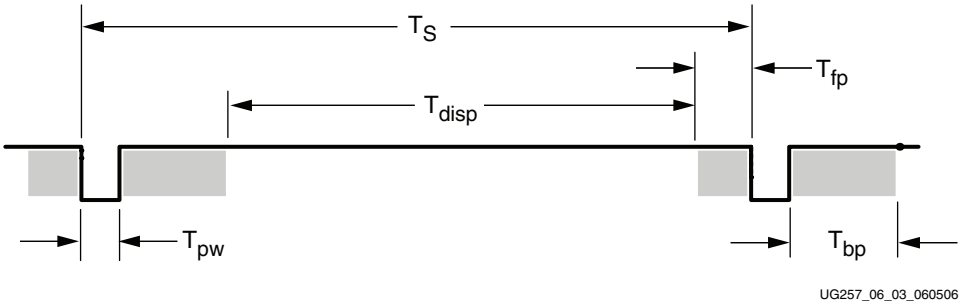


*Figure 6-3:* **VGA Control Timing**

Generally, a counter clocked by the pixel clock controls the horizontal timing. Decoded counter values generate the HS signal. This counter tracks the current pixel display location on a given row.

A separate counter tracks the vertical timing. The vertical-sync counter increments with each HS pulse and decoded values generate the VS signal. This counter tracks the current display row. These two continuously running counters form the address into a video display buffer. For example, the on-board DDR SDRAM provides an ideal display buffer.

No time relationship is specified between the onset of the HS pulse and the onset of the VS pulse. Consequently, the counters can be arranged to easily form video RAM addresses, or to minimize decoding logic for sync pulse generation.

# UCF Location Constraints

Figure 6-4 provides the UCF constraints for the VGA display port, including the I/O pin assignment, the I/O standard used, the output slew rate, and the output drive current.

```
NET "VGA_RED"   LOC = "H14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_GREEN" LOC = "H15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_BLUE"  LOC = "G15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_HSYNC" LOC = "F15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_VSYNC" LOC = "F14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
```

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*Figure 6-4:* **UCF Constraints for VGA Display Port**

# Related Resources

- VESA
  http://www.vesa.org
- VGA timing information
  http://www.epanorama.net/documents/pc/vga_timing.html

Chapter 7

# RS-232 Serial Ports

## Overview

As shown in Figure 7-1, the MicroBlaze Development Kit board has two RS-232 serial ports: a female DB9 DCE connector and a male DTE connector. The DCE-style port connects directly to the serial port connector available on most personal computers and workstations via a standard straight-through serial cable. Null modem, gender changers, or crossover cables are not required.

Use the DTE-style connector to control other RS-232 peripherals, such as modems or printers, or perform simple loopback testing with the DCE connector.

Figure 7-1 shows the connection between the FPGA and the two DB9 connectors. The FPGA supplies serial output data using LVTTL or LVCMOS levels to the Maxim device, which in turn, converts the logic value to the appropriate RS-232 voltage level. Likewise, the Maxim device converts the RS-232 serial input data to LVTTL levels for the FPGA. A series resistor between the Maxim output pin and the FPGA's RXD pin protects against accidental logic conflicts.

Hardware flow control is not supported on the connector. The port's DCD, DTR, and DSR signals connect together, as shown in Figure 7-1. Similarly, the port's RTS and CTS signals connect together.

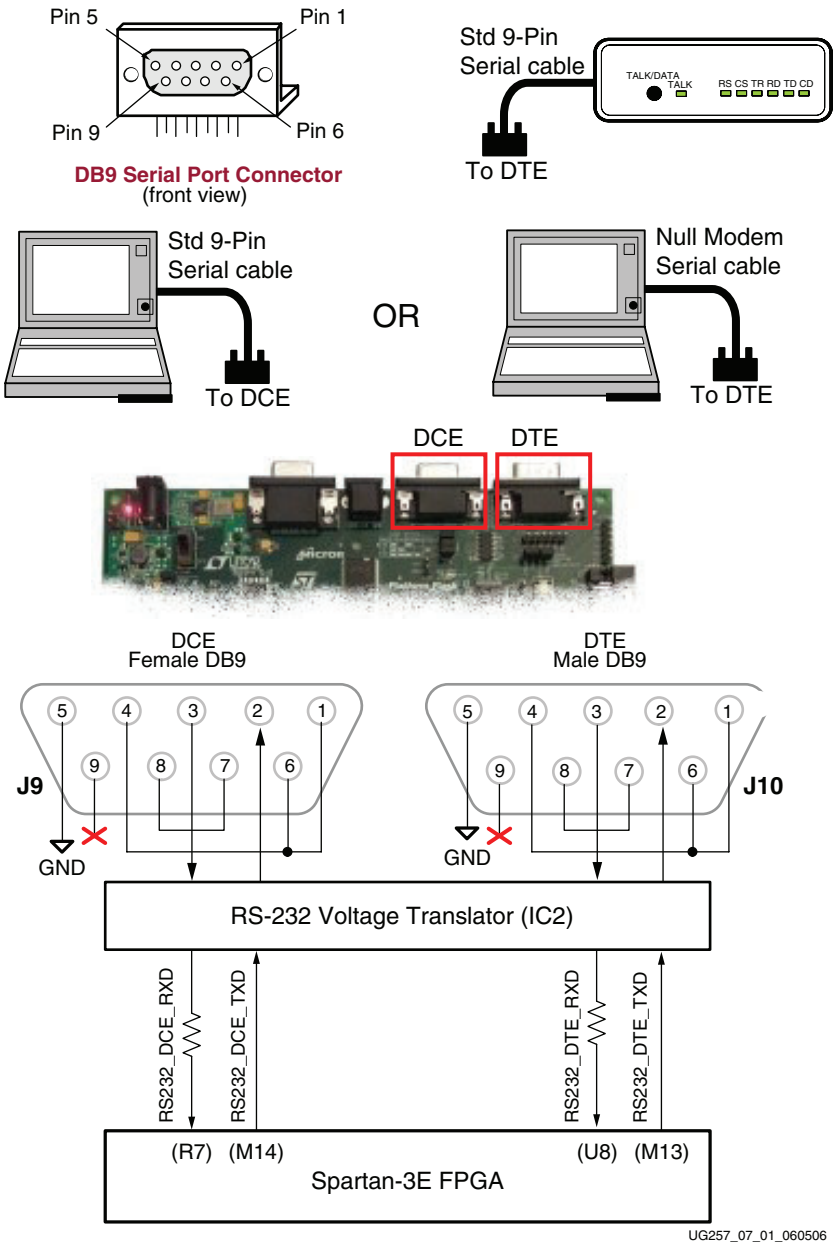


*Figure 7-1:* **RS-232 Serial Ports**

# UCF Location Constraints

Figure 7-2 and Figure 7-3 provide the UCF constraints for the DTE and DCE RS-232 ports, respectively, including the I/O pin assignment and the I/O standard used.

```
NET "RS232_DTE_RXD" LOC = "U8"  | IOSTANDARD = LVTTL ;
NET "RS232_DTE_TXD" LOC = "M13" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = SLOW ;
```

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*Figure 7-2:* **UCF Location Constraints for DTE RS-232 Serial Port**

```
NET "RS232_DCE_RXD" LOC = "R7"  | IOSTANDARD = LVTTL ;
NET "RS232_DCE_TXD" LOC = "M14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = SLOW ;
```

UG257_07_03_060506

*Figure 7-3:* **UCF Location Constraints for DCE RS-232 Serial Port**

Chapter 8

# PS/2 Mouse/Keyboard Port

The MicroBlaze Development Kit board includes a PS/2 mouse/keyboard port and the standard 6-pin mini-DIN connector, labeled J14 on the board. Figure 8-1 shows the PS/2 connector, and Table 8-1 shows the signals on the connector. Only pins 1 and 5 of the connector attach to the FPGA.

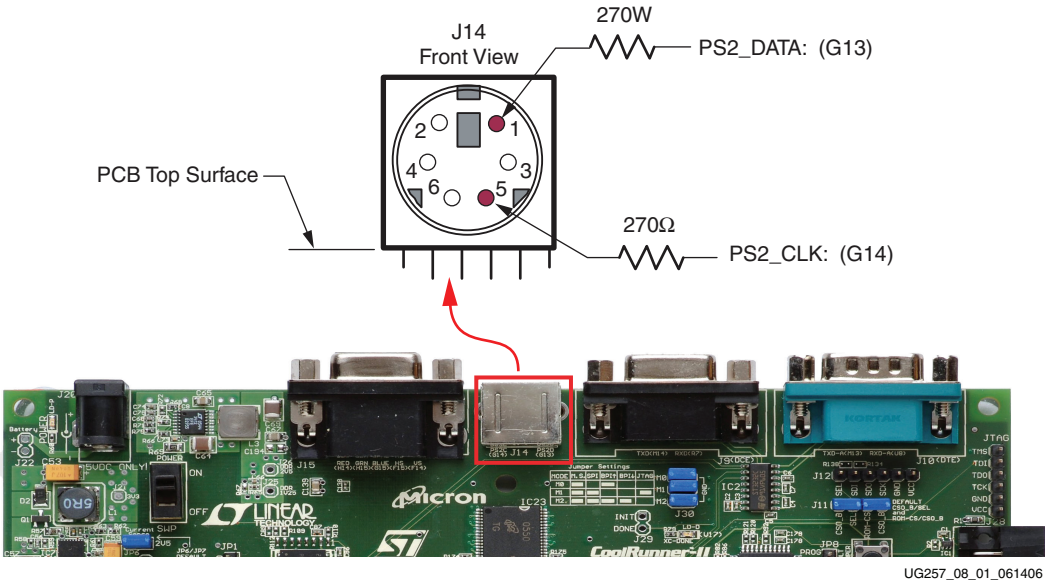


*Figure 8-1:* **PS/2 Connector Location and Signals**

*Table 8-1:* **PS/2 Connector Pinout**

| PS/2 DIN Pin | Signal | FPGA Pin |
|---|---|---|
| 1 | DATA (PS2_DATA) | G13 |
| 2 | Reserved | G13 |
| 3 | GND | GND |
| 4 | +5V | — |
| 5 | CLK (PS2_CLK) | G14 |
| 6 | Reserved | G14 |

Both a PC mouse and keyboard use the two-wire PS/2 serial bus to communicate with a host device, the Spartan-3E FPGA in this case. The PS/2 bus includes both clock and data. Both a mouse and keyboard drive the bus with identical signal timings and both use 11-bit words that include a start, stop and odd parity bit. However, the data packets are organized differently for a mouse and keyboard. Furthermore, the keyboard interface allows bidirectional data transfers so the host device can illuminate state LEDs on the keyboard.

The PS/2 bus timing appears in Table 8-2 and Figure 8-2. The clock and data signals are only driven when data transfers occur; otherwise they are held in the idle state at logic High. The timing defines signal requirements for mouse-to-host communications and bidirectional keyboard communications. As shown in Figure 8-2, the attached keyboard or mouse writes a bit on the data line when the clock signal is High, and the host reads the data line when the clock signal is Low.

*Table 8-2:* **PS/2 Bus Timing**

| Symbol | Parameter | Min | Max |
|---|---|---|---|
| $T_{CK}$ | Clock High or Low Time | 30 µs | 50 µs |
| $T_{SU}$ | Data-to-clock Setup Time | 5 µs | 25 µs |
| $T_{HLD}$ | Clock-to-data Hold Time | 5 µs | 25 µs |

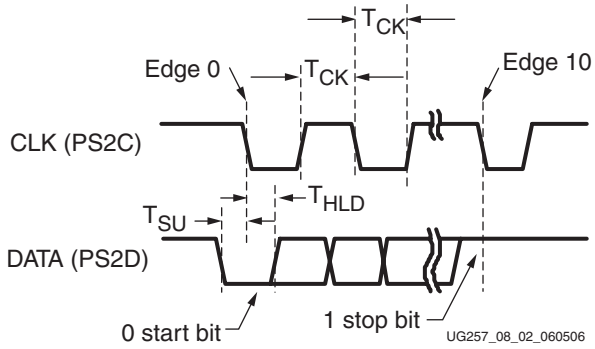


*Figure 8-2:* **PS/2 Bus Timing Waveforms**

# Keyboard

The keyboard uses open-collector drivers so that either the keyboard or the host can drive the two-wire bus. If the host never sends data to the keyboard, then the host can use simple input pins.

A PS/2-style keyboard uses scan codes to communicate key press data. Nearly all keyboards in use today are PS/2 style. Each key has a single, unique scan code that is sent whenever the corresponding key is pressed. The scan codes for most keys appear in Figure 8-3.

If the key is pressed and held, the keyboard repeatedly sends the scan code every 100 ms or so. When a key is released, the keyboard sends an "F0" key-up code, followed by the scan code of the released key. The keyboard sends the same scan code, regardless if a key has different *shift* and *non-shift* characters and regardless whether the Shift key is pressed or not. The host determines which character is intended.

Some keys, called extended keys, send an “E0” ahead of the scan code and furthermore, they might send more than one scan code. When an extended key is released, an “E0 F0” key-up code is sent, followed by the scan code.

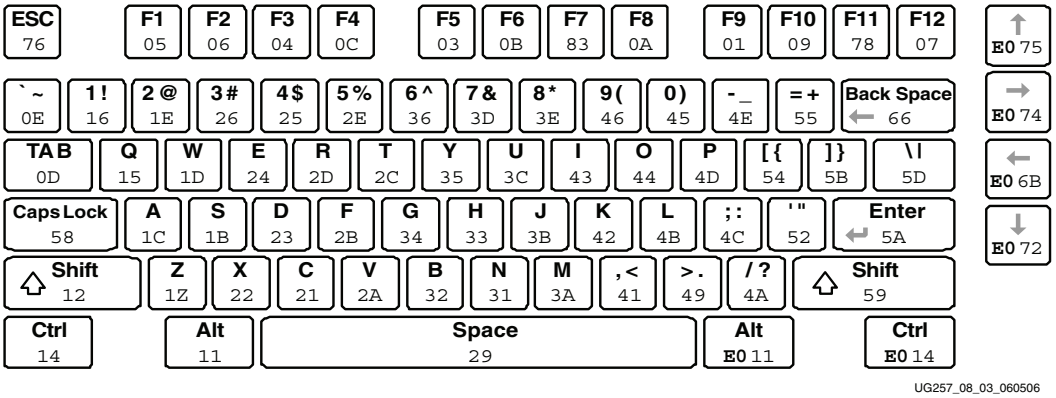


*Figure 8-3:* **PS/2 Keyboard Scan Codes**

The host can also send commands and data to the keyboard. Table 8-3 provides a short list of some often-used commands.

*Table 8-3:* **Common PS/2 Keyboard Commands**

| Command | Description |
|---|---|
| ED | **Turn on/off Num Lock, Caps Lock, and Scroll Lock LEDs.** The keyboard acknowledges receipt of an “ED” command by replying with an “FA”, after which the host sends another byte to set LED status. The bit positions for the keyboard LEDs are shown below. Write a ‘1’ to the specific bit to illuminate the associated keyboard LED.<br><br>7 \| 6 \| 5 \| 4 \| 3 \| 2 \| 1 \| 0<br>Ignored \| Caps Lock \| Num Lock \| Scroll Lock |
| EE | **Echo.** Upon receiving an echo command, the keyboard replies with the same scan code “EE”. |
| F3 | **Set scan code repeat rate.** The keyboard acknowledges receipt of an “F3” by returning an “FA”, after which the host sends a second byte to set the repeat rate. |
| FE | **Resend.** Upon receiving a resend command, the keyboard resends the last scan code sent. |
| FF | **Reset.** Resets the keyboard. |

The keyboard sends commands or data to the host only when both the data and clock lines are High, the Idle state.

Because the host is the *bus master*, the keyboard checks whether the host is sending data before driving the bus. The clock line can be used as a *clear to send* signal. If the host pulls the clock line Low, the keyboard must not send any data until the clock is released.

The keyboard sends data to the host in 11-bit words that contain a '0' start bit, followed by eight bits of scan code (LSB first), followed by an odd parity bit and terminated with a '1' stop bit. When the keyboard sends data, it generates 11 clock transitions at around 20 to 30 kHz, and data is valid on the falling edge of the clock as shown in Figure 8-2.

# Mouse

A mouse generates a clock and data signal when moved; otherwise, these signals remain High, indicating the Idle state. Each time the mouse is moved, the mouse sends three 11-bit words to the host. Each of the 11-bit words contains a '0' start bit, followed by 8 data bits (LSB first), followed by an odd parity bit, and terminated with a '1' stop bit. Each data transmission contains 33 total bits, where bits 0, 11, and 22 are '0' start bits, and bits 10, 21, and 32 are '1' stop bits. The three 8-bit data fields contain movement data as shown in Figure 8-4. Data is valid at the falling edge of the clock, and the clock period is 20 to 30 kHz.

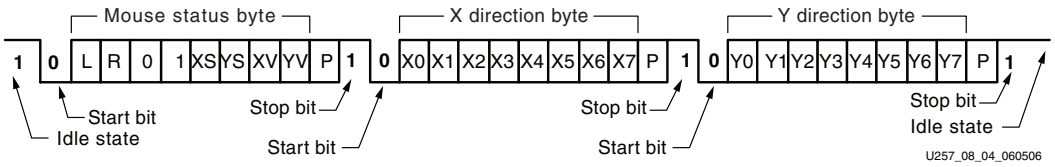


*Figure 8-4:* **PS/2 Mouse Transaction**

A PS/2-style mouse employs a relative coordinate system (see Figure 8-5), wherein moving the mouse to the right generates a positive value in the X field, and moving to the left generates a negative value. Likewise, moving the mouse up generates a positive value in the Y field, and moving it down represents a negative value. The XS and YS bits in the status byte define the sign of each value, where a '1' indicates a negative value.

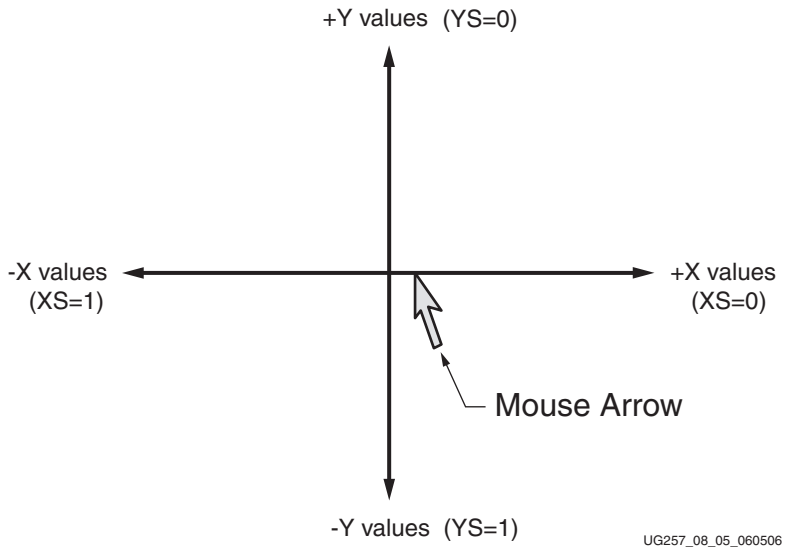


*Figure 8-5:* **The Mouse Uses a Relative Coordinate System to Track Movement**

The magnitude of the X and Y values represent the rate of mouse movement. The larger the value, the faster the mouse is moving. The XV and YV bits in the status byte indicate when

the X or Y values exceed their maximum value, an overflow condition. A ‘1’ indicates when an overflow occurs. If the mouse moves continuously, the 33-bit transmissions repeat every 50 ms or so.

The L and R fields in the status byte indicate Left and Right button presses. A ‘1’ indicates that the associated mouse button is being pressed.

## Voltage Supply

The PS/2 port on the MicroBlaze Development Kit board is powered by 5V. Although the Spartan-3E FPGA is not a 5V-tolerant device, it can communicate with a 5V device using series current-limiting resistors, as shown in Figure 8-1.

## UCF Location Constraints

Figure 8-6 provides the UCF constraints for the PS/2 port connecting, including the I/O pin assignment and the I/O standard used.

```
NET "PS2_CLK"  LOC = "G14" | IOSTANDARD = LVCMOS33 | DRIVE = 8 | SLEW = SLOW ;
NET "PS2_DATA" LOC = "G13" | IOSTANDARD = LVCMOS33 | DRIVE = 8 | SLEW = SLOW ;
```

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*Figure 8-6:* **UCF Location Constraints for PS/2 Port**

## Related Resources

- PS/2 Mouse/Keyboard Protocol
  http://www.computer-engineering.org/ps2protocol/
- PS/2 Keyboard Interface
  http://www.computer-engineering.org/ps2keyboard/
- PS/2 Mouse Interface
  http://www.computer-engineering.org/ps2mouse/

Chapter 9

# Digital to Analog Converter (DAC)

The MicroBlaze Development Kit board includes an SPI-compatible, four-channel, serial Digital-to-Analog Converter (DAC). The DAC device is a Linear Technology LTC2624 quad DAC with 12-bit unsigned resolution. The four outputs from the DAC appear on the J5 header, which uses the Digilent 6-pin Peripheral Module format. The DAC and the header are located immediately above the Ethernet RJ-45 connector, as shown in Figure 9-1.

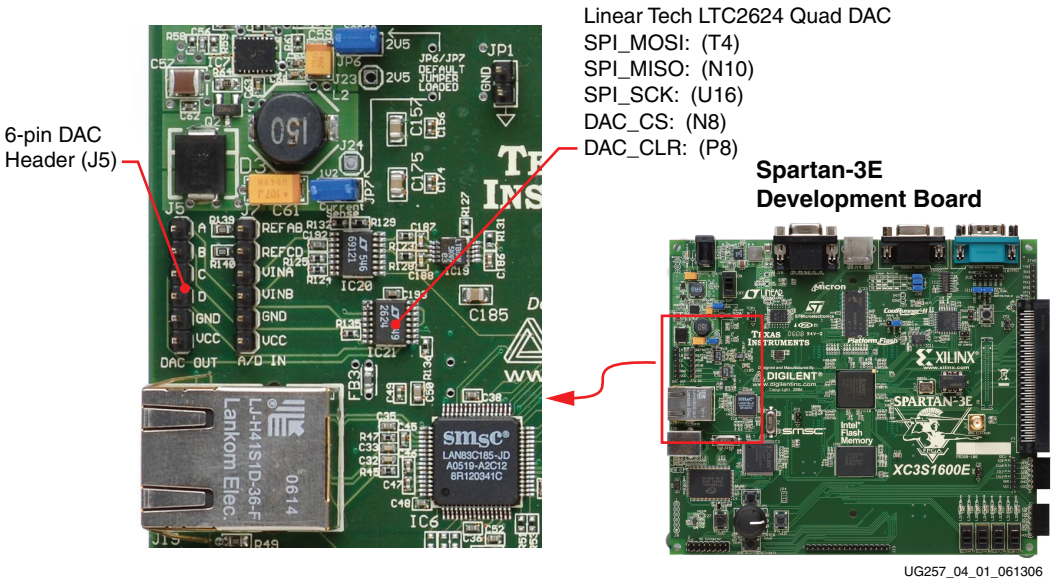


*Figure 9-1:* **Digital-to-Analog Converter and Associated Header**

## SPI Communication

As shown in Figure 9-2, the FPGA uses a Serial Peripheral Interface (SPI) to communicate digital values to each of the four DAC channels. The SPI bus is a full-duplex, synchronous, character-oriented channel employing a simple four-wire interface. A bus master—the FPGA in this example—drives the bus clock signal (SPI_SCK) and transmits serial data (SPI_MOSI) to the selected bus slave—the DAC in this example. At the same time, the bus slave provides serial data (SPI_MISO) back to the bus master.

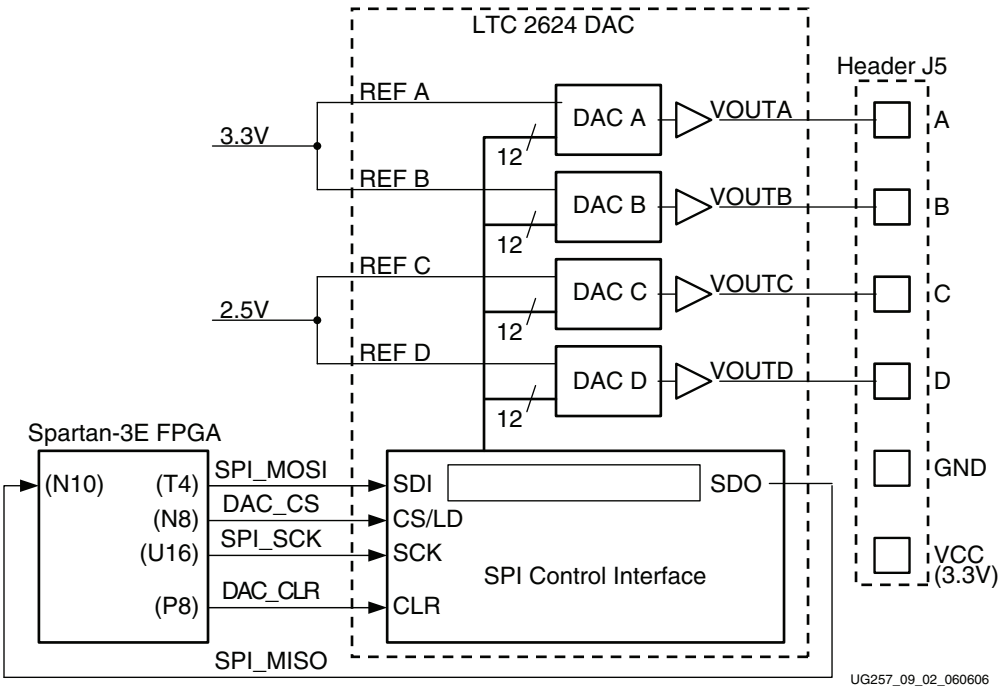


*Figure 9-2:* **Digital-to-Analog Connection Schematics**

## Interface Signals

Table 9-1 lists the interface signals between the FPGA and the DAC. The SPI_MOSI, SPI_MISO, and SPI_SCK signals are shared with other devices on the SPI bus. The DAC_CS signal is the active-Low slave select input to the DAC. The DAC_CLR signal is the active-Low, asynchronous reset input to the DAC.

*Table 9-1:* **DAC Interface Signals**

| Signal | FPGA Pin | Direction | Description |
|---|---|---|---|
| SPI_MOSI | T4 | FPGA→DAC | Serial data: Master Output, Slave Input |
| DAC_CS | N8 | FPGA→DAC | Active-Low chip-select. Digital-to-analog conversion starts when signal returns High. |
| SPI_SCK | U16 | FPGA→DAC | Clock |
| DAC_CLR | P8 | FPGA→DAC | Asynchronous, active-Low reset input |
| SPI_MISO | N10 | FPGA←DAC | Serial data: Master Input, Slave Output |

The serial data output from the DAC is primarily used to cascade multiple DACs. This signal can be ignored in most applications although it does demonstrate full-duplex communication over the SPI bus.

## Disable Other Devices on the SPI Bus to Avoid Contention

The SPI bus signals are shared by other devices on the board. It is vital that other devices are disabled when the FPGA communicates with the DAC to avoid bus contention. Table 9-2 provides the signals and logic values required to disable the other devices.

Although the StrataFlash PROM is a parallel device, its least-significant data bit is shared with the SPI_MISO signal.

*Table 9-2:* **Disabled Devices on the SPI Bus**

| Signal | Disabled Device | Disable Value |
|---|---|---|
| SPI_SS_B | SPI serial Flash | 1 |
| AMP_CS | Programmable pre-amplifier | 1 |
| AD_CONV | Analog-to-Digital Converter (ADC) | 0 |
| SF_CE0 | StrataFlash Parallel Flash PROM | 1 |
| FPGA_INIT_B | Platform Flash PROM | 1 |

## SPI Communication Details

Figure 9-3 shows a detailed example of the SPI bus timing. Each bit is transmitted or received relative to the SPI_SCK clock signal. The bus is fully static and supports clocks rate up to the maximum of 50 MHz. However, check all timing parameters using the LTC2624 data sheet if operating at or close to the maximum speed.

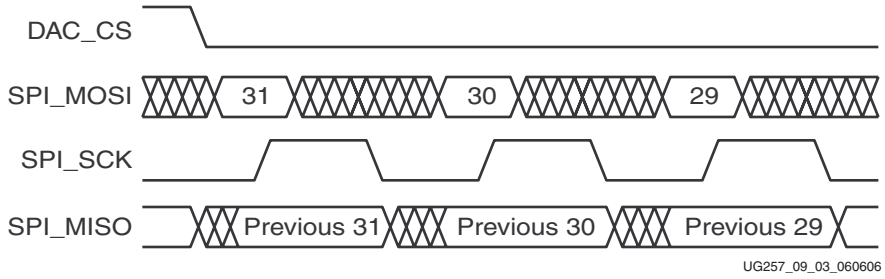


*Figure 9-3:* **SPI Communication Waveforms**

After driving the DAC_CS slave select signal Low, the FPGA transmits data on the SPI_MOSI signal, MSB first. The LTC2624 captures input data (SPI_MOSI) on the rising edge of SPI_SCK; the data must be valid for at least 4 ns relative to the rising clock edge.

The LTC2624 DAC transmits its data on the SPI_MISO signal on the falling edge of SPI_SCK. The FPGA captures this data on the next rising SPI_SCK edge. The FPGA must read the first SPI_MISO value on the first rising SPI_SCK edge after DAC_CS goes Low. Otherwise, bit 31 is missed.

After transmitting all 32 data bits, the FPGA completes the SPI bus transaction by returning the DAC_CS slave select signal High. The High-going edge starts the actual digital-to-analog conversion process within the DAC.

## Communication Protocol

Figure 9-4 shows the communications protocol required to interface with the LTC2624 DAC. The DAC supports both a 24-bit and 32-bit protocol. The 32-bit protocol is shown.

Inside the D/A converter, the SPI interface is formed by a 32-bit shift register. Each 32-bit command word consists of a command, an address, followed by data value. As a new command enters the DAC, the previous 32-bit command word is echoed back to the

master. The response from the DAC can be ignored although it is a useful to confirm correct communication.

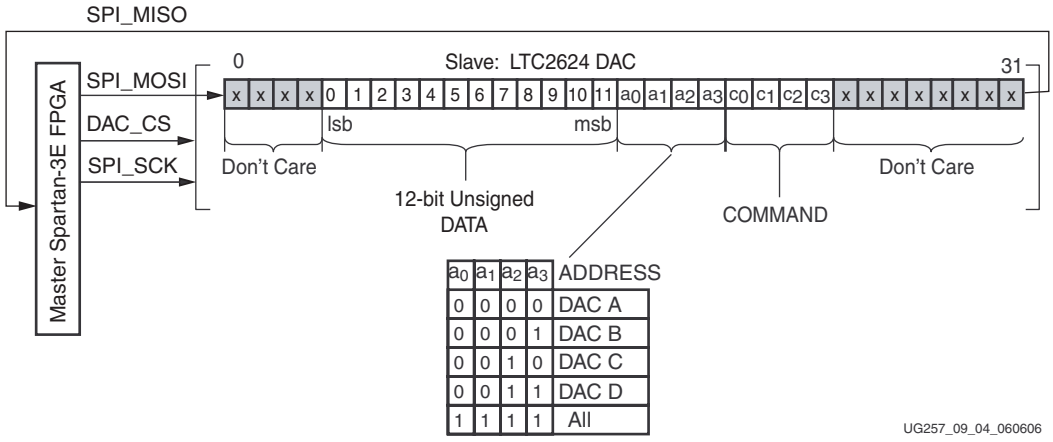


*Figure 9-4:* **SPI Communications Protocol to LTC2624 DAC**

The FPGA first sends eight dummy or "don't care" bits, followed by a 4-bit command. The most commonly used command with the board is COMMAND[3:0] = "0011", which immediately updates the selected DAC output with the specified data value. Following the command, the FPGA selects one or all the DAC output channels via a 4-bit address field. Following the address field, the FPGA sends a 12-bit unsigned data value that the DAC converts to an analog value on the selected output(s). Finally, four additional dummy or *don't care* bits pad the 32-bit command word.

# Specifying the DAC Output Voltage

As shown in Figure 9-2, each DAC output level is the analog equivalent of a 12-bit unsigned digital value, D[11:0], written by the FPGA to the DAC via the SPI interface.

The voltage on a specific output is generally described in Equation 9-1. The reference voltage, $V_{REFERENCE}$, is different between the four DAC outputs. Channels A and B use a 3.3V reference voltage and Channels C and D use a 2.5V reference. The reference voltages themselves have a ±5% tolerance, so there will be slight corresponding variances in the output voltage.

$$V_{OUT} = \frac{D[11:0]}{4096} \times V_{REFERENCE} \qquad \textit{Equation 9-1}$$

## DAC Outputs A and B

Equation 9-2 provides the output voltage equation for DAC outputs A and B. The reference voltage associated with DAC outputs A and B is 3.3V ± 5%.

$$V_{OUTA} = \frac{D[11:0]}{4096} \times (3.3V \pm 5\%) \qquad \textit{Equation 9-2}$$

### DAC Outputs C and D

Equation 9-3 provides the output voltage equation for DAC outputs A and B. The reference voltage associated with DAC outputs A and B is 2.5V ± 5%.

$$V_{OUTC} = \frac{D[11:0]}{4096} \times (2.5V \pm 5\%) \quad \textit{Equation 9-3}$$

## UCF Location Constraints

Figure 9-5 provides the UCF constraints for the DAC interface, including the I/O pin assignment and the I/O standard used.

```
NET "SPI_MISO" LOC = "N10" | IOSTANDARD = LVCMOS33 ;
NET "SPI_MOSI" LOC = "T4"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "SPI_SCK"  LOC = "U16" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "DAC_CS"   LOC = "N8"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "DAC_CLR"  LOC = "P8"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
```

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*Figure 9-5:* **UCF Location Constraints for the DAC Interface**

## Related Resources

- LTC2624 Quad DAC Data Sheet
- http://www.linear.com/pc/downloadDocument.do?navId=H0,C1,C1155,C1005,C1156,P2048,D2170
- PicoBlaze Based D/A Converter Control for the Spartan-3E Starter Kit (Reference Design)
- http://www.xilinx.com/sp3e1600e
- Xilinx PicoBlaze Soft Processor
- http://www.xilinx.com/picoblaze
- Digilent, Inc. Peripheral Modules http://www.digilentinc.com/Products/Catalog.cfm?Nav1=Products&Nav2=Peripheral&Cat=Peripheral

Chapter 10

# Analog Capture Circuit

The MicroBlaze Development Kit board includes a two-channel analog capture circuit, consisting of aprogrammable scaling pre-amplifier and an analog-to-digital converter (ADC), as shown in Figure 10-1. Analog inputs are supplied on the J7 header.

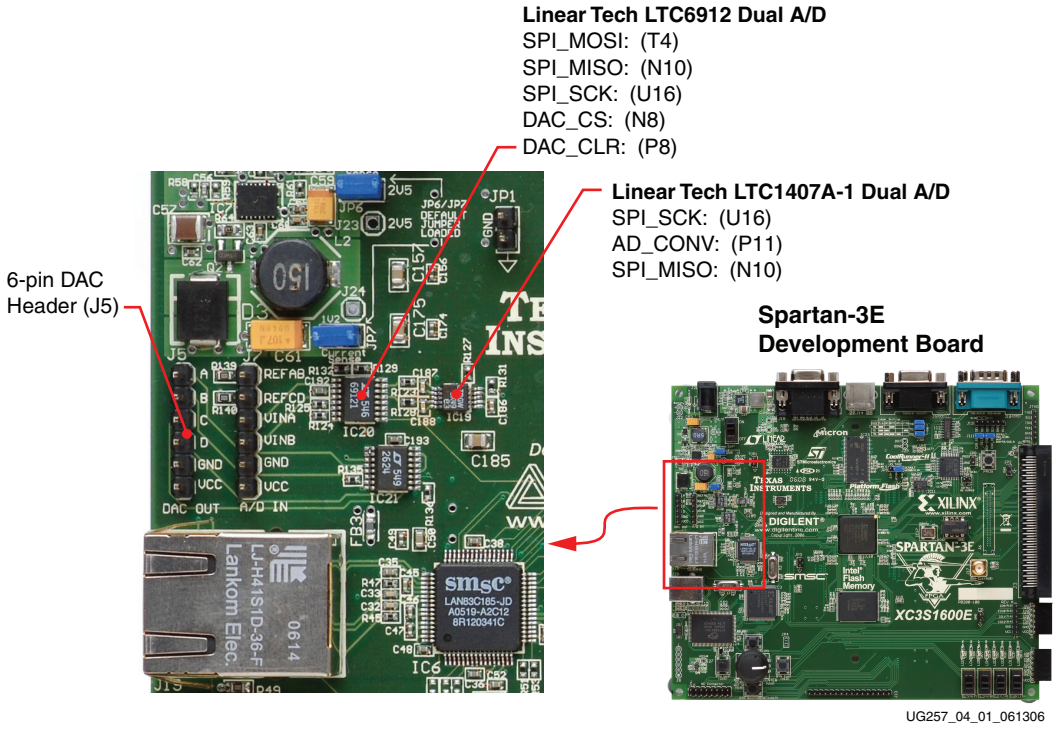


*Figure 10-1:* **Two-Channel Analog Capture Circuit**

The analog capture circuit consists of a Linear Technology LTC6912-1 programmable pre-amplifier that scales the incoming analog signal on header J7 (see Figure 10-2). The output of pre-amplifier connects to a Linear Technology LTC1407A-1 ADC. Both the pre-amplifier and the ADC are serially programmed or controlled by the FPGA.

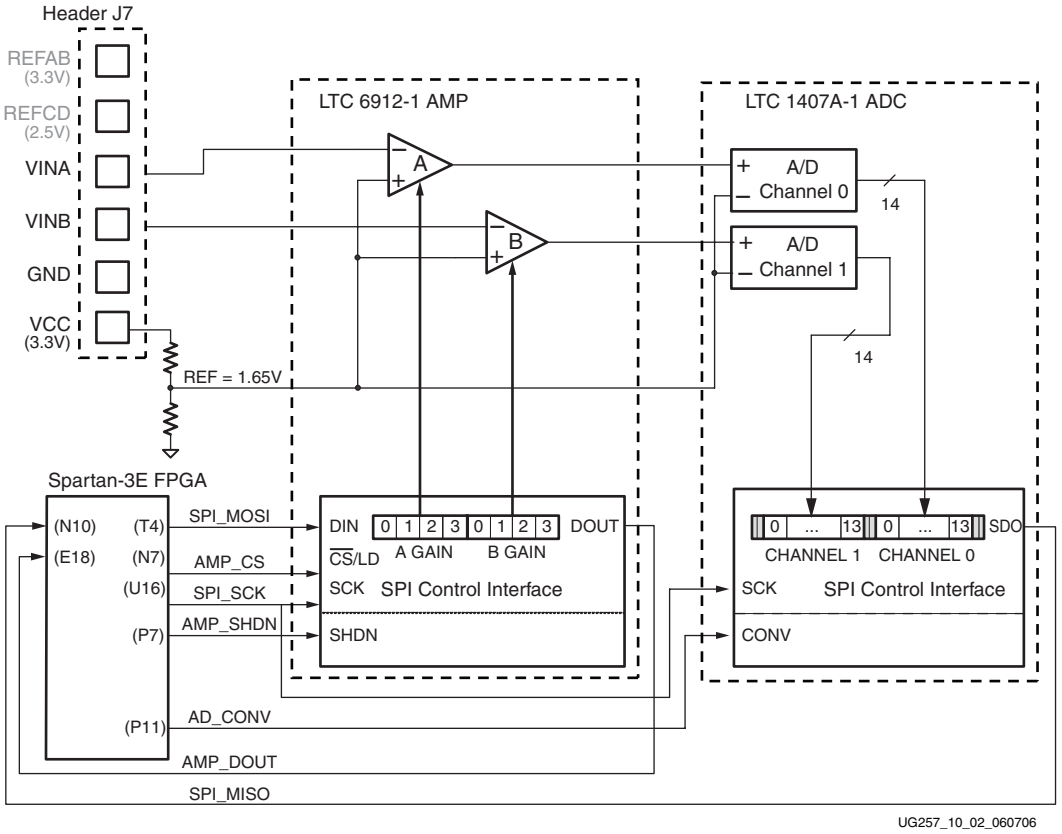


*Figure 10-2:* **Detailed View of Analog Capture Circuit**

# Digital Outputs from Analog Inputs

The analog capture circuit converts the analog voltage on VINA or VINB and converts it to a 14-bit digital representation, D[13:0], as expressed by Equation 10-1.

$$D[13:0] = GAIN \times \frac{(V_{IN} - 1.65V)}{1.25V} \times 8192 \qquad \textit{Equation 10-1}$$

The GAIN is the current setting loaded into the programmable pre-amplifier. The various allowable settings for GAIN and allowable voltages applied to the VINA and VINB inputs appear in Table 10-2.

The reference voltage for the amplifier and the ADC is 1.65V, generated via a voltage divider shown in Figure 10-2. Consequently, 1.65V is subtracted from the input voltage on VINA or VINB.

The maximum range of the ADC is ±1.25V, centered around the reference voltage, 1.65V. Hence, 1.25V appears in the denominator to scale the analog input accordingly.

Finally, the ADC presents a 14-bit, two's complement digital output. A 14-bit, two's complement number represents values between $-2^{13}$ and $2^{13}-1$. Therefore, the quantity is scaled by 8192, or $2^{13}$.

See "Programmable Pre-Amplifier" to control the GAIN settings on the programmable pre-amplifier.

The reference design files provide more information on converting the voltage applied on VINA or VINB to a digital representation (see "Related Resources," page 81).

# Programmable Pre-Amplifier

The LTC6912-1 provides two independent inverting amplifiers with programmable gain. The purpose of the amplifier is to scale the incoming voltage on VINA or VINB so that it maximizes the conversion range of the DAC, namely 1.65 ± 1.25V.

## Interface

Table 10-1 lists the interface signals between the FPGA and the amplifier. The SPI_MOSI, SPI_MISO, and SPI_SCK signals are shared with other devices on the SPI bus. The AMP_CS signal is the active-Low slave select input to the amplifier.

*Table 10-1:* **AMP Interface Signals**

| Signal | FPGA Pin | Direction | Description |
|---|---|---|---|
| SPI_MOSI | T4 | FPGA→AD | Serial data: Master Output, Slave Input. Presents 8-bit programmable gain settings, as defined in Table 10-2. |
| AMP_CS | N7 | FPGA→AMP | Active-Low chip-select. The amplifier gain is set when signal returns High. |
| SPI_SCK | U16 | FPGA→AMP | Clock |
| AMP_SHDN | P7 | FPGA→AMP | Active-High shutdown, reset |
| AMP_DOUT | E18 | FPGA←AMP | Serial data. Echoes previous amplifier gain settings. Can be ignored in most applications. |

## Programmable Gain

Each analog channel has an associated programmable gain amplifier (see Figure 10-2). Analog signals presented on the VINA or VINB inputs on header J7 are amplified relative to 1.65V. The 1.65V reference is generated using a voltage divider of the 3.3V voltage supply.

The gain of each amplifier is programmable from -1 to -100, as shown in Table 10-2.

*Table 10-2:* **Programmable Gain Settings for Pre-Amplifier**

| Gain | A3 | A2 | A1 | A0 | Input Voltage Range | |
|---|---|---|---|---|---|---|
| | B3 | B2 | B1 | B0 | Minimum | Maximum |
| 0 | 0 | 0 | 0 | 0 | | |
| -1 | 0 | 0 | 0 | 1 | 0.4 | 2.9 |
| -2 | 0 | 0 | 1 | 0 | 1.025 | 2.275 |
| -5 | 0 | 0 | 1 | 1 | 1.4 | 1.9 |
| -10 | 0 | 1 | 0 | 0 | 1.525 | 1.775 |
| -20 | 0 | 1 | 0 | 1 | 1.5875 | 1.7125 |

*Table 10-2:* **Programmable Gain Settings for Pre-Amplifier *(Continued)***

| Gain | A3 | A2 | A1 | A0 | Input Voltage Range | |
|---|---|---|---|---|---|---|
| | B3 | B2 | B1 | B0 | Minimum | Maximum |
| -50 | 0 | 1 | 1 | 0 | 1.625 | 1.675 |
| -100 | 0 | 1 | 1 | 1 | 1.6375 | 1.6625 |

## SPI Control Interface

Figure 10-3 highlights the SPI-based communications interface with the amplifier. The gain for each amplifier is sent as an 8-bit command word, consisting of two 4-bit fields. The most-significant bit, B3, is sent first.

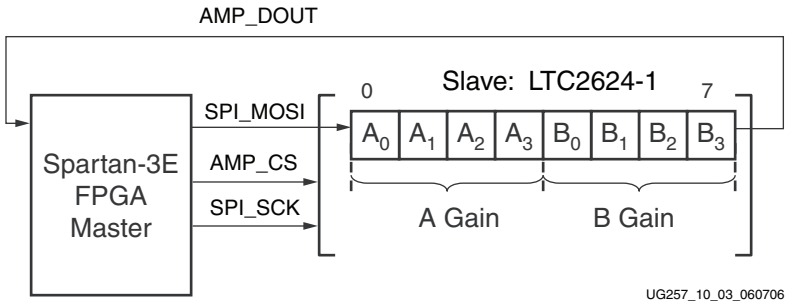


*Figure 10-3:* **SPI Serial Interface to Amplifier**

The AMP_DOUT output from the amplifier echoes the previous gain settings. These values can be ignored for most applications.

The SPI bus transaction starts when the FPGA asserts AMP_CS Low (see Figure 10-4). The amplifier captures serial data on SPI_MOSI on the rising edge of the SPI_SCK clock signal. The amplifier presents serial data on AMP_DOUT on the falling edge of SPI_SCK.

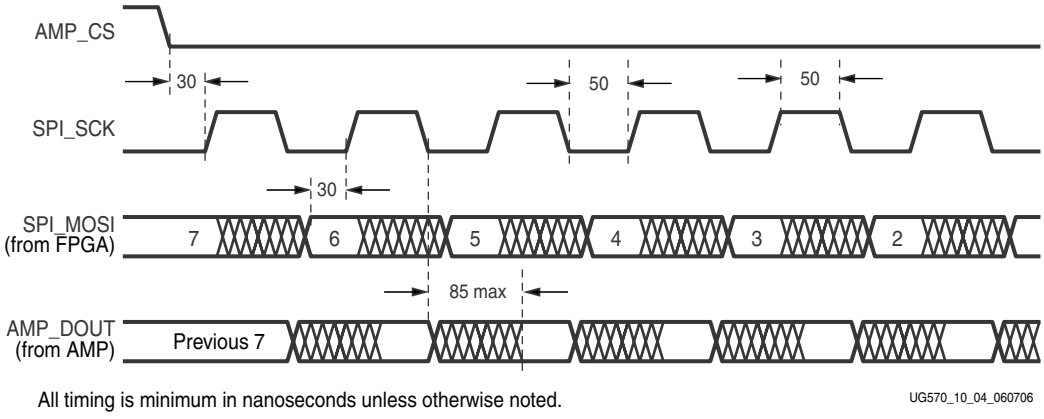


*Figure 10-4:* **SPI Timing When Communicating with Amplifier**

The amplifier interface is relatively slow, supporting only about a 10 MHz clock frequency.

### UCF Location Constraints

Figure 10-5 provides the User Constraint File (UCF) constraints for the amplifier interface, including the I/O pin assignment and I/O standard used.

```
NET "SPI_MOSI" LOC = "T4"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "AMP_CS"   LOC = "N7"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "SPI_SCK"  LOC = "U16" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "AMP_SHDN" LOC = "P7"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "AMP_DOUT" LOC = "E18" | IOSTANDARD = LVCMOS33 ;
```

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*Figure 10-5:* **UCF Location Constraints for the DAC Interface**

## Analog to Digital Converter (ADC)

The LTC1407A-1 provides two ADCs. Both analog inputs are sampled simultaneously when the AD_CONV signal is applied.

### Interface

Table 10-3 lists the interface signals between the FPGA and the ADC. The SPI_MOSI, SPI_MISO, and SPI_SCK signals are shared with other devices on the SPI bus. The DAC_CS signal is the active-Low slave select input to the DAC. The DAC_CLR signal is the active-Low, asynchronous reset input to the DAC.

*Table 10-3:* **ADC Interface Signals**

| Signal | FPGA Pin | Direction | Description |
|---|---|---|---|
| SPI_SCK | U16 | FPGA→ADC | Clock |
| AD_CONV | P11 | FPGA→ADC | Active-High shutdown and reset. |
| SPI_MISO | N10 | FPGA←ADC | Serial data: Master Input, Serial Output. Presents the digital representation of the sample analog values as two 14-bit two's complement binary values. |

### SPI Control Interface

Figure 10-6 provides an example SPI bus transaction to the ADC.

When the AD_CONV signal goes High, the ADC simultaneously samples both analog channels. The results of this conversion are not presented until the next time AD_CONV is asserted, a latency of one sample. The maxim sample rate is approximately 1.5 MHz.

The ADC presents the digital representation of the sampled analog values as a 14-bit, two's complement binary value.

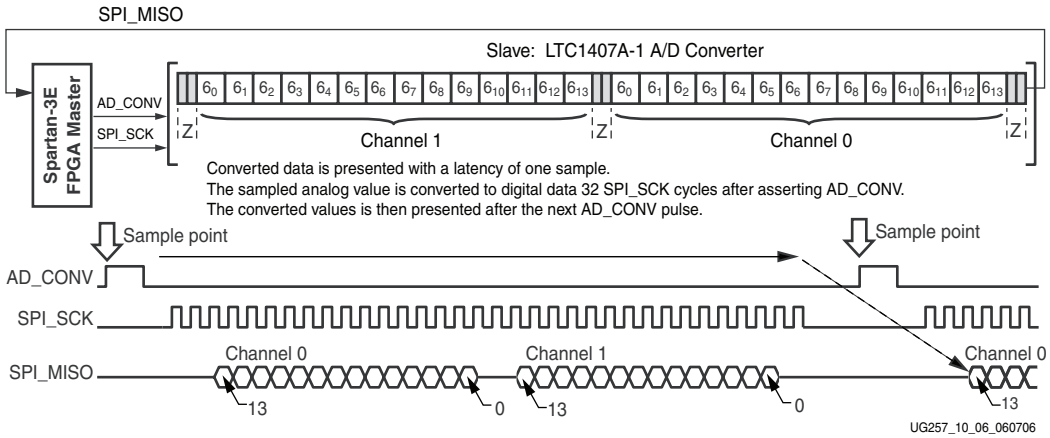


*Figure 10-6:* **Analog-to-Digital Conversion Interface**

Figure 10-7 shows detailed transaction timing. The AD_CONV signal is not a traditional SPI slave select enable. Be sure to provide enough SPI_SCK clock cycles so that the ADC leaves the SPI_MISO signal in the high-impedance state. Otherwise, the ADC blocks communication to the other SPI peripherals. As shown in Figure 10-6, use a 34-cycle communications sequence. The ADC 3-states its data output for two clock cycles before and after each 14-bit data transfer.

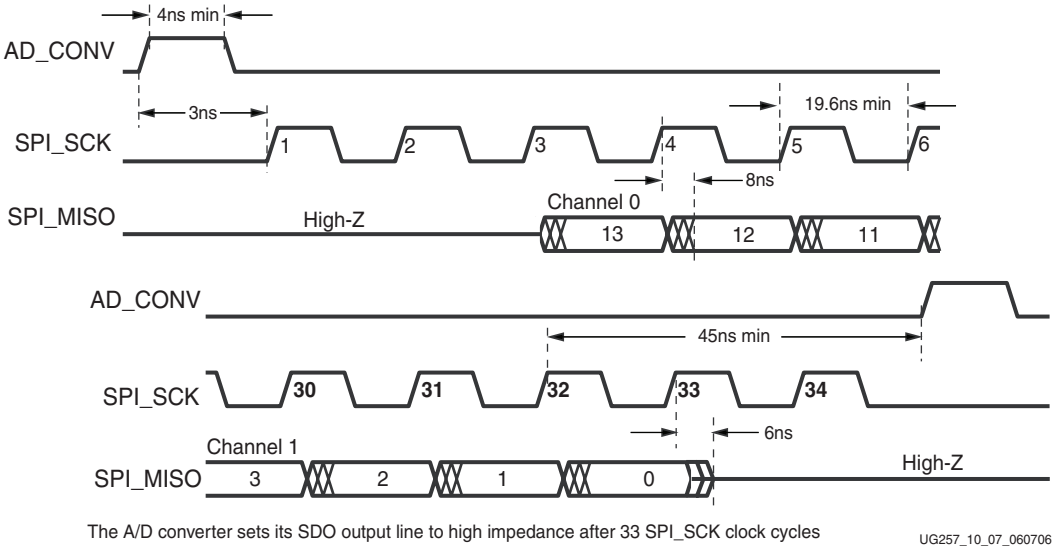


*Figure 10-7:* **Detailed SPI Timing to ADC**

## UCF Location Constraints

Figure 10-8 provides the User Constraint File (UCF) constraints for the amplifier interface, including the I/O pin assignment and I/O standard used.

```
NET "AD_CONV"  LOC = "P11" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "SPI_SCK"  LOC = "U16" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "SPI_MISO" LOC = "N10" | IOSTANDARD = LVCMOS33 ;
```

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*Figure 10-8:* **UCF Location Constraints for the ADC Interface**

# Disable Other Devices on the SPI Bus to Avoid Contention

The SPI bus signals are shared by other devices on the board. It is vital that other devices are disabled when the FPGA communicates with the AMP or ADC to avoid bus contention. Table 10-4 provides the signals and logic values required to disable the other devices. Although the StrataFlash PROM is a parallel device, its least-significant data bit is shared with the SPI_MISO signal. The Platform Flash PROM is only potentially enabled if the FPGA is set up for Master Serial mode configuration.

*Table 10-4:* **Disable Other Devices on SPI Bus**

| Signal | Disabled Device | Disable Value |
|---|---|---|
| SPI_SS_B | SPI Serial Flash | 1 |
| AMP_CS | Programmable Pre-Amplifier | 1 |
| DAC_CS | DAC | 1 |
| SF_CE0 | StrataFlash Parallel Flash PROM | 1 |
| FPGA_INIT_B | Platform Flash PROM | 1 |

# Connecting Analog Inputs

Connect AC signals to VINA or VINB via a DC blocking capacitor.

# Related Resources

- Amplifier and A/D Converter Control for the Spartan-3E Starter Kit (Reference Design)
- http://www.xilinx.com/sp3e1600e
- Xilinx PicoBlaze Soft Processor
- http://www.xilinx.com/picoblaze
- LTC6912 Dual Programmable Gain Amplifiers with Serial Digital Interface
- http://www.linear.com/pc/downloadDocument.do?navId=H0,C1,C1154,C1009,C1121,P7596,D5359
- LTC1407A-1 Serial 14-bit Simultaneous Sampling ADCs with Shutdown
- http://www.linear.com/pc/downloadDocument.do?navId=H0,C1,C1155,C1001,C1158,P2420,D1295

Chapter 11

# Intel StrataFlash Parallel NOR Flash PROM

As shown in Figure 11-1, the MicroBlaze Development Kit boards includes a 128 Mbit (16 Mbyte) Intel StrataFlash parallel NOR Flash PROM. As indicated, some of the StrataFlash connections are shared with other components on the board.

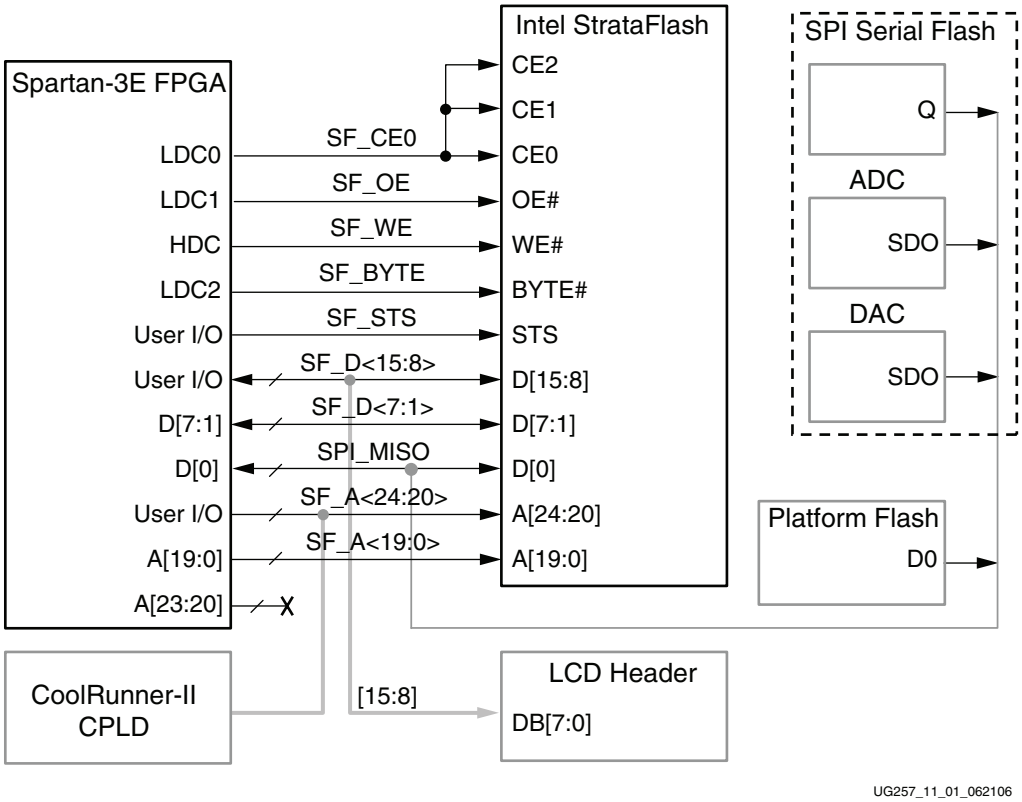


*Figure 11-1:* **Connections to Intel StrataFlash Flash Memory**

The StrataFlash PROM provides various functions:

- Stores a single FPGA configuration in the StrataFlash device.
- Stores two different FPGA configurations in the StrataFlash device and dynamically switch between the two using the Spartan-3E FPGA's MultiBoot feature.
- Stores and executes MicroBlaze processor code directly from the StrataFlash device.

- Stores MicroBlaze processor code in the StrataFlash device and shadows the code into the DDR memory before executing the code.
- Stores non-volatile data from the FPGA.

## StrataFlash Connections

Table 11-1 shows the connections between the FPGA and the StrataFlash device.

Although the XC1600E FPGA only requires just slightly under 6 Mbits per configuration image, the FPGA-to-StrataFlash interface on the board support up to a 256 Mbit StrataFlash. The MicroBlaze Development Kit board ships with a 128 Mbit device. Address line SF_A24 is not used.

In general, the StrataFlash device connects to the XC1600E to support Byte Peripheral Interface (BPI) configuration. The upper four address bits from the FPGA, A[23:19] do not connect directly to the StrataFlash device. Instead, the XC2C64 CPLD controls the pins during configuration. As described in Table 11-1 and Shared Connections, some of the StrataFlash connections are shared with other components on the board.

*Table 11-1:* **FPGA-to-StrataFlash Connections**

| Category | StrataFlash Signal Name | FPGA Pin Number | Function |
|---|---|---|---|
| Address | SF_A24 | A11 | Shared with XC2C64A CPLD. The CPLD actively drives these pins during FPGA configuration, as described in Chapter 16, "XC2C64A CoolRunner-II CPLD". Also connects to FPGA user-I/O pins. SF_A24 is the same as FX2 connector signal FX2_IO<32>. |
| | SF_A23 | N11 | |
| | SF_A22 | V12 | |
| | SF_A21 | V13 | |
| | SF_A20 | T12 | |
| | SF_A19 | V15 | Connects to FPGA pins A[19:0] to support the BPI configuration. |
| | SF_A18 | U15 | |
| | SF_A17 | T16 | |
| | SF_A16 | U18 | |
| | SF_A15 | T17 | |
| | SF_A14 | R18 | |
| | SF_A13 | T18 | |
| | SF_A12 | L16 | |
| | SF_A11 | L15 | |
| | SF_A10 | K13 | |
| | SF_A9 | K12 | |
| | SF_A8 | K15 | |
| | SF_A7 | K14 | |
| | SF_A6 | J17 | |
| | SF_A5 | J16 | |
| | SF_A4 | J15 | |
| | SF_A3 | J14 | |
| | SF_A2 | J12 | |
| | SF_A1 | J13 | |
| | SF_A0 | H17 | |

*Table 11-1:* **FPGA-to-StrataFlash Connections**

| Category | StrataFlash Signal Name | FPGA Pin Number | Function | |
|---|---|---|---|---|
| Data | SF_D15 | T8 | Upper 8 bits of a 16-bit halfword when StrataFlash is configured for x16 data (SF_BYTE=High). Connects to FPGA user I/O. | Signals SF_D<15:8> connect to character LCD pins DB[7:0]. |
| | SF_D14 | R8 | | |
| | SF_D13 | P6 | | |
| | SF_D12 | M16 | | |
| | SF_D11 | M15 | | |
| | SF_D10 | P17 | | |
| | SF_D9 | R16 | | |
| | SF_D8 | R15 | | |
| | SF_D7 | N9 | Upper 7 bits of a data byte or lower 8 bits of a 16-bit halfword. Connects to FPGA pins D[7:1] to support the BPI configuration. | |
| | SF_D6 | M9 | | |
| | SF_D5 | R9 | | |
| | SF_D4 | U9 | | |
| | SF_D3 | V9 | | |
| | SF_D2 | R10 | | |
| | SF_D1 | P10 | | |
| | SPI_MISO | N10 | Bit 0 of data byte and 16-bit halfword. Connects to FPGA pin D0/DIN to support the BPI configuration. Shared with other SPI peripherals and Platform Flash PROM. | |
| Control | SF_CE0 | D16 | StrataFlash Chip Enable. Connects to FPGA pin LDC0 to support the BPI configuration. | |
| | SF_WE | D17 | StrataFlash Write Enable. Connects to FPGA pin HDC to support the BPI configuration. | |
| | SF_OE | C18 | StrataFlash Chip Enable. Connects to FPGA pin LDC1 to support the BPI configuration. | |
| | SF_BYTE | C17 | StrataFlash Byte Enable. Connects to FPGA pin LDC2 to support the BPI configuration.<br>0: x8 data<br>1: x16 data | |
| | SF_STS | B18 | StrataFlash Status signal. Connects to FPGA user-I/O pin. | |

# Shared Connections

Besides the connections to the FPGA, the StrataFlash memory shares some connections to other components.

## Character LCD

The LCD supports an 8-bit or a 4-bit data interface. The eight display data connections are also shared with the SF_D<15:8> signals on the StrataFlash PROM. As shown in Table 11-2, the FPGA controls access to the StrataFlash PROM or the character LCD using the SF_CE0 and LCD_RW signals.

*Table 11-2:* **FPGA Control for StrataFlash and LCD**

| SF_CE0 | LCD_RW | Function |
|---|---|---|
| 1 | 1 | The FPGA reads from the character LCD. |
| 0 | 0 | The FPGA accesses the StrataFlash PROM. |

## Xilinx XC2C64A CPLD

The Xilinx XC2C64A CoolRunner CPLD controls the five upper StrataFlash address lines, SF_A<24:20> during configuration. The four upper BPI-mode address lines from the FPGA, A<23:20> are not connected. Instead, four FPGA user-I/O pins connect to the StrataFlash PROM upper address lines SF_A<23:0>. See Chapter 16, "XC2C64A CoolRunner-II CPLD" for more information.

The most-significant address line, SF_A<24>, is not physically used on the 16 Mbyte StrataFlash PROM. It is provided for upward migration to a larger StrataFlash PROM in the same package footprint. Likewsie, the SF_A<24> signal is also connected to the FX2_IO<32> signal on the FX2 expansion connector.

## SPI Data Line

The least-significant StrataFlash data line, SF_D<0>, is shared with data output signals from serial SPI peripherals, SPI_MISO, and the serial output from the Platform Flash PROM as shown in Table 11-3. To avoid contention, the FPGA application must ensure that only one data source is active at any time.

*Table 11-3:* **Possible Contention on SPI_MISO (SF_D<0>) Data**

| Condition | Function |
|---|---|
| FPGA_M2 = Low<br>FPGA_M1 = Low<br>FPGA_M0 = Low<br>INIT_B = High | Platform Flash outputs data on D0. |
| SF_CE0 = Low<br>SF_OE = Low | StrataFlash outputs data. |
| AD_CONV = High<br>SPI_SCK | Serial data is clocked out of the A/D converter |
| DAC_CS = Low<br>SPI_SCK | DAC outputs previous command in response to SPI_SCK transitions. |

# UCF Location Constraints

## Address

Figure 11-2 provides the UCF constraints for the StrataFlash address pins, including the I/O pin assignment and the I/O standard used.

```
NET "SF_A<24>" LOC = "A11" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<23>" LOC = "N11" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<22>" LOC = "V12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<21>" LOC = "V13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<20>" LOC = "T12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<19>" LOC = "V15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<18>" LOC = "U15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<17>" LOC = "T16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<16>" LOC = "U18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<15>" LOC = "T17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<14>" LOC = "R18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<13>" LOC = "T18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<12>" LOC = "L16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<11>" LOC = "L15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<10>" LOC = "K13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<9>"  LOC = "K12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<8>"  LOC = "K15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<7>"  LOC = "K14" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<6>"  LOC = "J17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<5>"  LOC = "J16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<4>"  LOC = "J15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<3>"  LOC = "J14" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<2>"  LOC = "J12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<1>"  LOC = "J13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<0>"  LOC = "H17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
```

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*Figure 11-2:* **UCF Location Constraints for StrataFlash Address Inputs**

## Data

Figure 11-3 provides the UCF constraints for the StrataFlash data pins, including the I/O pin assignment and the I/O standard used.

```
NET "SF_D<15>" LOC = "T8"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<14>" LOC = "R8"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<13>" LOC = "P6"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<12>" LOC = "M16"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<11>" LOC = "M15"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<10>" LOC = "P17"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<9>"  LOC = "R16"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<8>"  LOC = "R15"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<7>"  LOC = "N9"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<6>"  LOC = "M9"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<5>"  LOC = "R9"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<4>"  LOC = "U9"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<3>"  LOC = "V9"   | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<2>"  LOC = "R10"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<1>"  LOC = "P10"  | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SPI_MISO"  LOC = "N10" | IOSTANDARD = LVCMOS33 | DRIVE = 6 | SLEW = SLOW ;
```

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*Figure 11-3:* **UCF Location Constraints for StrataFlash Data I/Os**

### Control

Figure 11-4 provides the UCF constraints for the StrataFlash control pins, including the I/O pin assignment and the I/O standard used.

```
NET "SF_BYTE" LOC = "C17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_CE0"  LOC = "D16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_OE"   LOC = "C18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_STS"  LOC = "B18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_WE"   LOC = "D17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
```

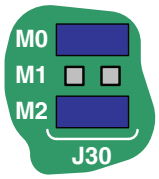
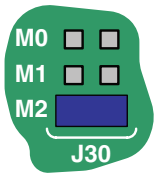
UG257_11_04_060706

*Figure 11-4:* **UCF Location Constraints for StrataFlash Control Pins**

## Setting the FPGA Mode Select Pins

Set the FPGA configuration mode pins for either BPI Up or BPI down mode, as shown in Table 11-4. See

*Table 11-4:* **Selecting BPI-Up or BPI-Down Configuration Modes** (Header J30 in Chapter 4, "FPGA Configuration Options", Figure 4-2)

| Configuration Mode | Mode Pins M2:M1:M0 | FPGA Configuration Image in StrataFlash | Jumper Settings |
|---|---|---|---|
| BPI Up | 0:1:0 | FPGA starts at address 0 and increments through address space. The CPLD controls address lines A[24:20] during BPI configuration. |  |
| BPI Down | 0:1:1 | FPGA starts at address 0xFF_FFFF and decrements through address space. The CPLD controls address lines A[24:20] during BPI configuration. |  |

## Related Resources

- Intel J3 StrataFlash Data Sheet
  http://www.intel.com/design/flcomp/products/j3/techdocs.htm#datasheets
- Application Note 827, Intel StrataFlash® Memory (J3) to Xilinx Spartan-3E FPGA Design Guide
  http://www.intel.com/design/flcomp/applnots/307257.htm

Chapter 12

# SPI Serial Flash

The MicroBlaze Development Kit board includes a STMicroelectronics M25P16 16 Mbit SPI serial Flash, useful in a variety of applications. The SPI Flash provides an alternative means to configure the FPGA—a new feature of Spartan-3E FPGAs as shown in Figure 12-1. The SPI Flash is also available to the FPGA after configuration for a variety of purposes, such as:

- Simple non-volatile data storage
- Storage for identifier codes, serial numbers, IP addresses, etc.
- Storage of MicroBlaze processor code that can be shadowed into DDR SDRAM.

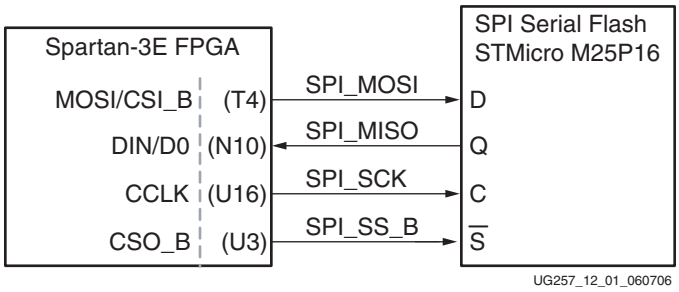



*Figure 12-1:* **Spartan-3E FPGAs Have an Optional SPI Flash Configuration Interface**

*Table 12-1:* **SPI Flash Interface Signals**

| Signal | FPGA Pin | Direction | Description |
|---|---|---|---|
| SPI_MOSI | T4 | FPGA→SPI | Serial data: Master Output, Slave Input |
| SPI_MISO | N10 | FPGA←SPI | Serial data: Master Input, Slave Output |
| SPI_SCK | U16 | FPGA→SPI | Clock |
| SPI_SS_B | U3 | FPGA→SPI | Asynchronous, active-Low slave select input |

# UCF Location Constraints

Figure 12-2 provides the UCF constraints for the SPI serial Flash PROM, including the I/O pin assignment and the I/O standard used.

```
# some connections shared with SPI Flash, DAC, ADC, and AMP
NET "SPI_MISO"  LOC = "N10" | IOSTANDARD = LVCMOS33 ;
NET "SPI_MOSI"  LOC = "T4"  | IOSTANDARD = LVCMOS33  | SLEW = SLOW  | DRIVE = 6 ;
NET "SPI_SCK"   LOC = "U16" | IOSTANDARD = LVCMOS33  | SLEW = SLOW  | DRIVE = 6 ;
NET "SPI_SS_B"  LOC = "U3"  | IOSTANDARD = LVCMOS33  | SLEW = SLOW  | DRIVE = 6 ;
NET "SPI_ALT_CS_JP11" LOC = "R12" | IOSTANDARD = LVCMOS33  | SLEW = SLOW  | DRIVE = 6 ;
```

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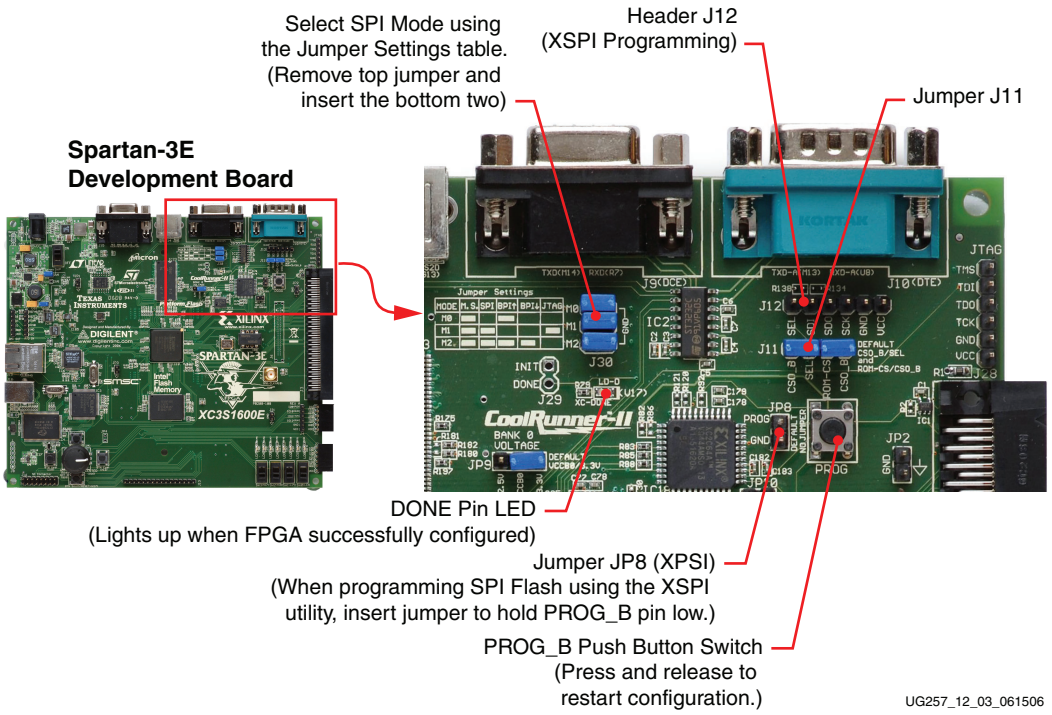
*Figure 12-2:* **UCF Location Constraints for SPI Flash Connections**

# Configuring from SPI Flash

To configure the FPGA from SPI Flash, the FPGA mode select pins must be set appropriately and the SPI Flash must contain a valid configuration image.

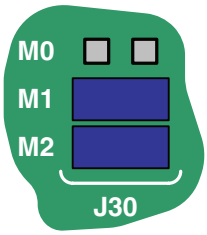



UG257_12_03_061506

*Figure 12-3:* **Configuration Options for SPI Mode**

## Setting the FPGA Mode Select Pins

Set the FPGA configuration mode pins for SPI mode, as shown in Figure 12-4. The location of the configuration mode jumpers (J30) appears in Figure 12-3.




UG257_12_04_061506

*Figure 12-4:* **Set Mode Pins for SPI Mode**

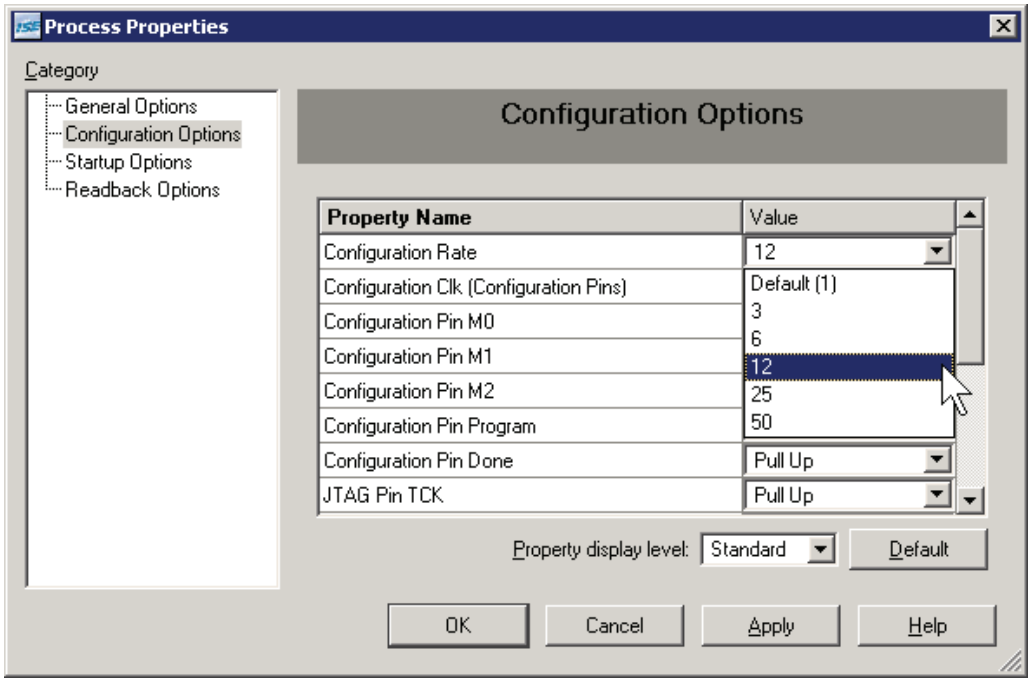
## Creating an SPI Serial Flash PROM File

The following steps describe how to format an FPGA bitstream for an SPI Serial Flash PROM.

### Setting the Configuration Clock Rate

The FPGA supports a 12 MHz configuration clock rate when connected to an M25P16 SPI serial Flash. Set the **`Properties`** for **`Generate Programming File`** so that the **`Configuration Rate`** is **`12`**, as shown in Figure 12-5. See "Generating the FPGA Configuration Bitstream File" in the **`FPGA Configuration Options`** chapter for a more detailed description.

Regenerate the FPGA bitstream programming file with the new settings.




UG257_12_05_060806

*Figure 12-5:* **Set Configuration Rate to 12 MHz When Using the M25P16 SPI Flash**

## Formatting an SPI Flash PROM File

After generating the program file, double-click **`Generate PROM, ACE, or JTAG File`** to launch the iMPACT software, as shown in Figure 12-6.

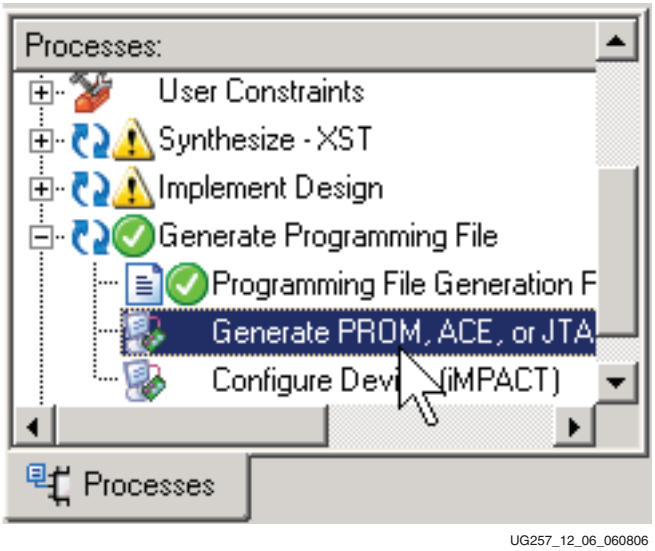



*Figure 12-6:* **Double-Click Generate PROM, ACE, or JTAG File**

After iMPACT starts, double-click **`PROM File Formatter`**, as shown in Figure 12-7.

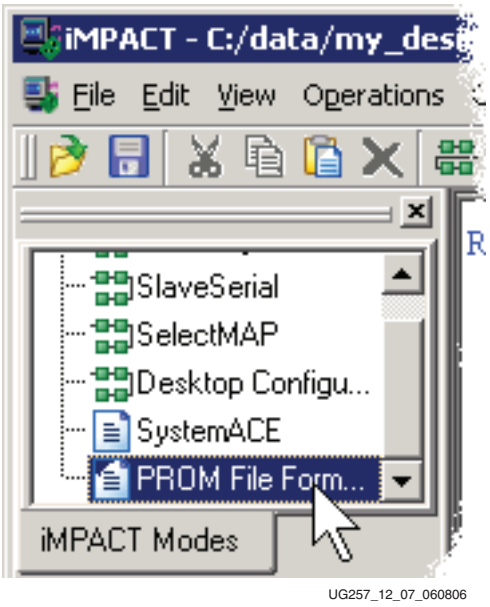



*Figure 12-7:* **Double-Click PROM File Formatter**

Choose **`3rd Party SPI PROM`** as the target PROM type, as shown in Figure 12-8. Select from any of the PROM File Formats; the Intel Hex format (**`MCS`**) is popular. The PROM Formatter automatically swaps the bit direction as SPI Flash PROMs shift out the most-significant bit (MSB) first. Enter the **`Location`** of the directory and the **`PROM File Name`**. Click **`Next >`** when finished.

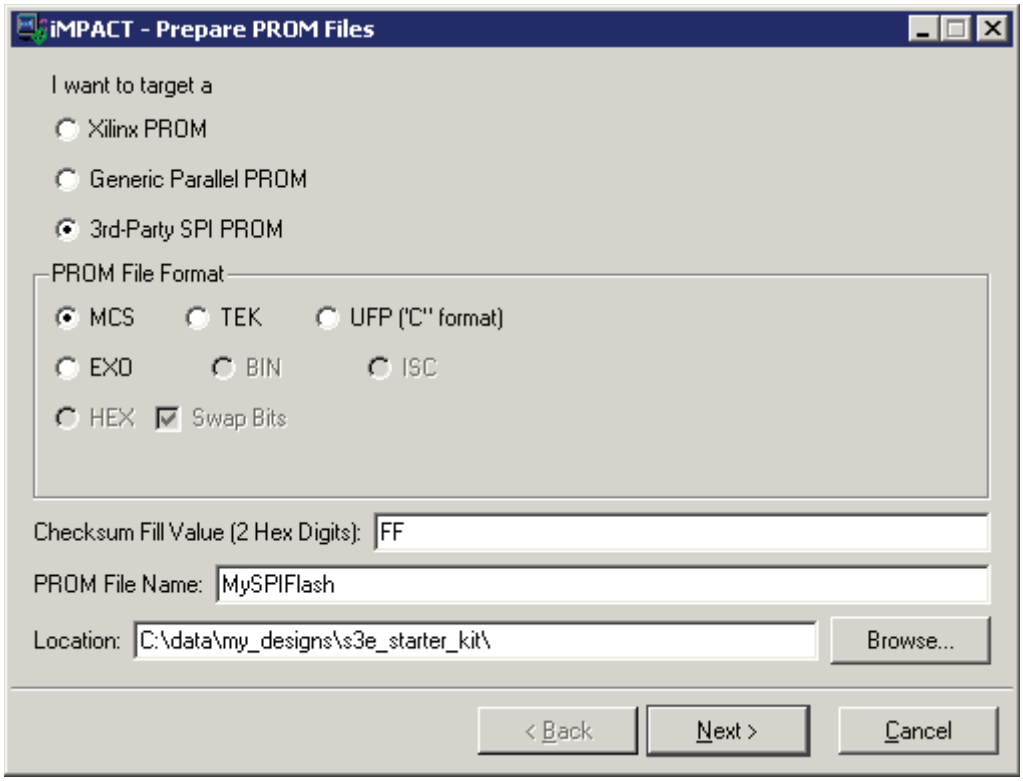



*Figure 12-8:* **Choose the PROM Target Type, the, Data Format, and File Location**

The Spartan-3E Starter Kit board has a 16 Mbit SPI serial Flash PROM. Select **`16M`** from the drop list, as shown in Figure 12-9. Click **`Next >`**.

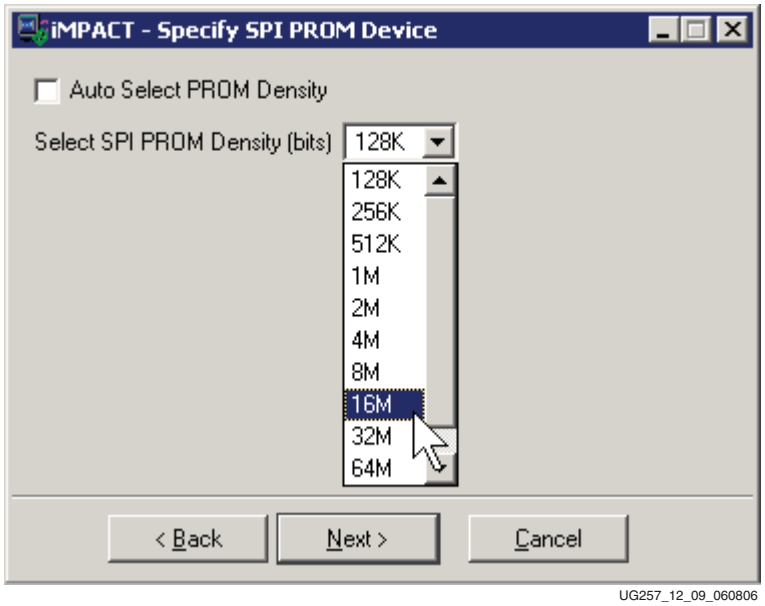



*Figure 12-9:* **Choose 16M**

The PROM Formatter then echoes the settings, as shown in Figure 12-10. Click **Finish**.

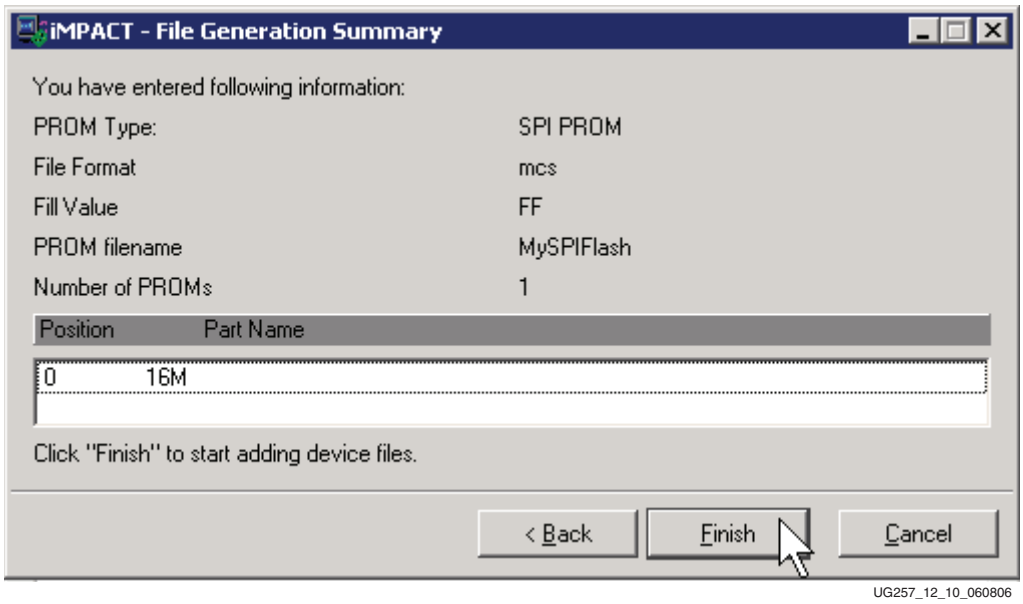



*Figure 12-10:* **Click Finish after Entering PROM Formatter Settings**

The PROM Formatter then prompts for the name(s) of the FPGA configuration bitstream file. As shown in Figure 12-11, click **OK** to start selecting files. Select an FPGA bitstream file (*.bit). Choose **No** after selecting the last FPGA file. Finally, click **OK** to continue.

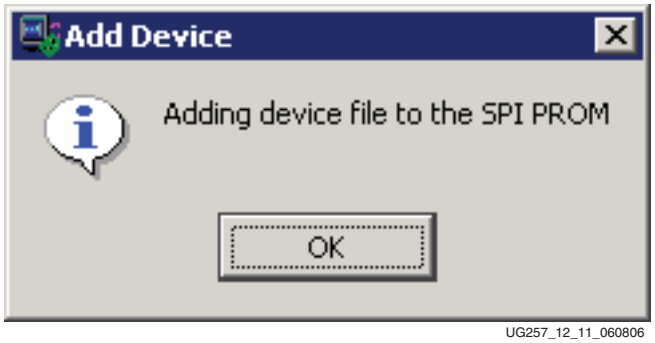



*Figure 12-11:* **Enter FPGA Configuration Bitstream File(s)**

When PROM formatting is complete, the iMPACT software presents the present settings by showing the PROM, the select FPGA bitstream(s), and the amount of PROM space consumed by the bitstream. Figure 12-12 shows an example for a single XC1600E FPGA bitstream stored in an XCF04S Platform Flash PROM.

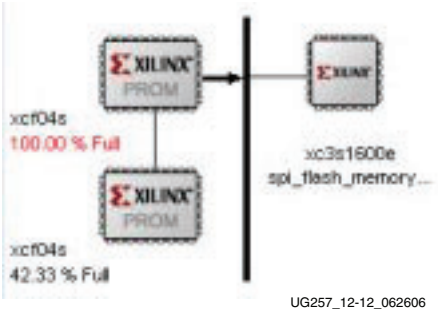



*Figure 12-12:* **PROM Formatting Completed**

To generate the actual PROM file, click **`Operations`** → **`Generate File`** as shown in Figure 12-13.

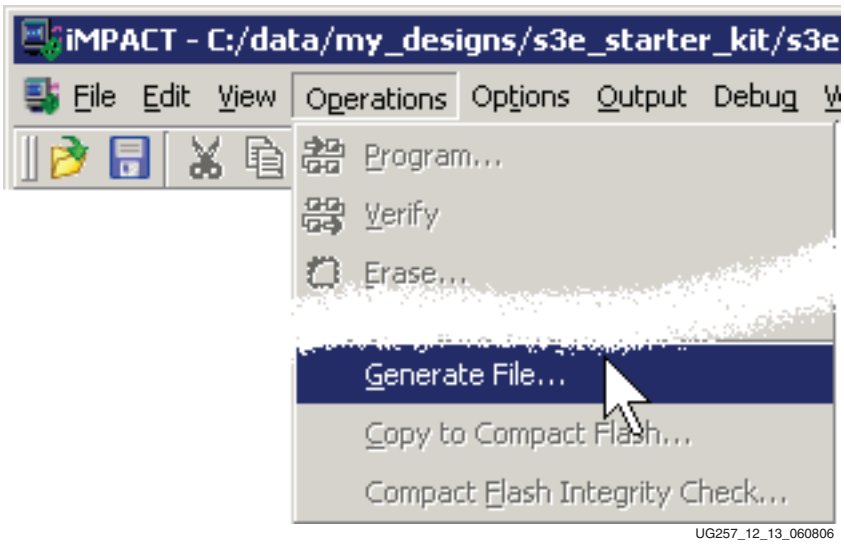



*Figure 12-13:* **Click Operations → Generate File to Create the Formatted PROM File**

As shown in Figure 12-14, the iMPACT software indicates that the PROM file was successfully created. The PROM Formatter creates an output file based on the settings shown in Figure 12-8. In this example, the output file is called **`MySPIFlash.mcs`**.

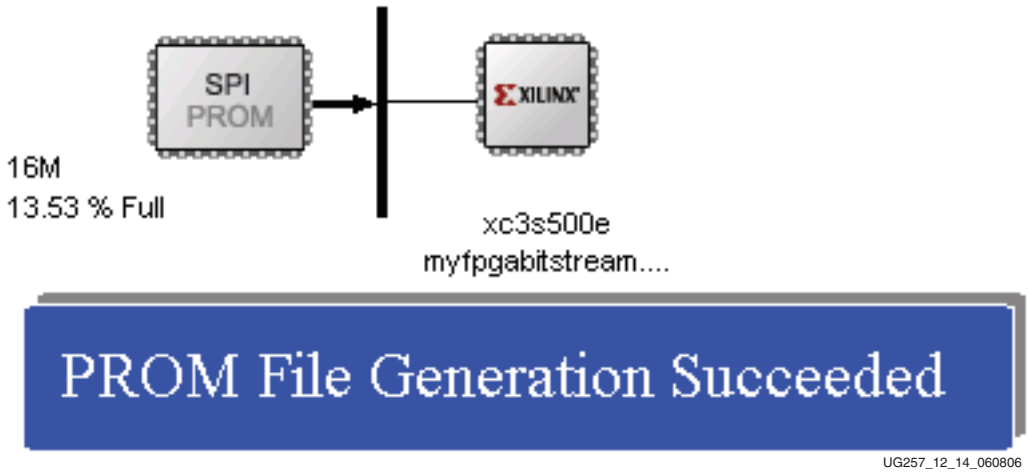



*Figure 12-14:* **PROM File Formatter Succeeded**

## Downloading the Design to SPI Flash

There multiple methods to program the SPI Flash, as listed below.

- Use the XSPI programming software provided with XAPP445. Download the SPI Flash via the parallel port using a JTAG parallel programming cable (not provided with the kit).
- Use the PicoBlaze based SPI Flash programmer reference designs. Use a terminal emulator, such as Hyperlink, to download SPI Flash programming data via the PC's serial port to the FPGA. The embedded PicoBlaze processor then programs the attached SPI serial Flash. See "Related Resources," page 104.
- Via the FPGA's JTAG chain, use a JTAG tool to program the SPI Flash connected to the FPGA. See the link to the Universal Scan SPI Flash programming tutorial in "Related Resources," page 104.
- Additional programming support will be provided in the ISE 8.2i software.

## Downloading the SPI Flash using XSPI

The following steps describe how to download the SPI Flash PROM using the XSPI programming utility.

### Download and Install the XSPI Programming Utility

Download application note XAPP445 and the associated XSPI programming software (see "Related Resources," page 104). Unzip the XSPI software onto the PC.

### Attach a JTAG Parallel Programming Cable

The XSPI programming utility uses a JTAG parallel programming cable, such as:

- Xilinx Parallel Cable IV with flying leads
- Digilent JTAG3 programming cable

These cables are not provided with the MicroBlaze Development Kit board , but can be purchased separately, either from the Xilinx Online Store or from Digilent, Inc. (see "Related Resources," page 104).

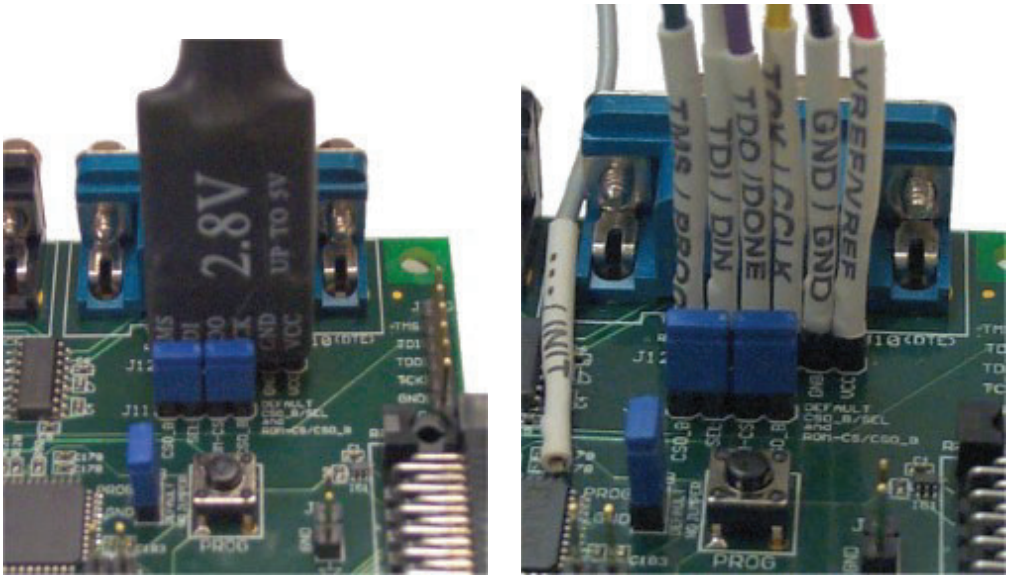
First, turn off the power on the Spartan-3E Starter Kit board.

If the USB cable is attached to the board, disconnect it. Simultaneously connecting both the USB cable and the parallel cable to the PC confuses the iMPACT software.

Connect one end of the JTAG parallel programming cable to the parallel printer port of the PC.

Connect the JTAG end of the cable to Header J12, as shown in Figure 12-15(a). The physical location of Header J12 is more clearly shown in Figure 12-3, page 92. The J12 header connects directly to the SPI Flash pins; it is not connected to the JTAG chain.

The JTAG3 cable directly mounts to Header J12. The labels on the JTAG3 cable face toward the J11 jumpers. If using flying leads, they must be connected as shown in Figure 12-15(b) and Table 12-2. Note the color coding for the leads. The gray INIT lead is left unconnected.




**a) JTAG3 Parallel Connector**

**b) Parallel Cable III or Parallel Cable IV with Flying Leads**

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*Figure 12-15:* **Attaching a JTAG Parallel Programming Cable to the Board**

*Table 12-2:* **Cable Connections to J12 Header**

| Cable and Labels | Connections | | | | | |
|---|---|---|---|---|---|---|
| J12 Header Label | SEL | SDI | SDO | SCK | GND | VCC |
| JTAG3 Cable Label | TMS | TDI | TDO | TCK | GND | VCC |
| Flying Leads Label | TMS/ PROG | TDI/ DIN | TDO/ DONE | TCK/ CCLK | GND/ GND | VREF/ VREF |

## Insert Jumper on JP8 and Hold PROG_B Low

The JTAG parallel programming cable directly accesses the SPI Flash pins. To avoid signal contention with the FPGA, ensure that the connecting FPGA pins are high-impedance. Force the FPGA's PROG_B pin Low by installing a jumper on JP8, next to the PROG push button, as shown in Figure 12-16. See Figure 12-3, page 92 to locate jumper JP8 and surrounding landmarks.


**a) No Jumper: FPGA Operational (default)** **b) Jumper Installed: FPGA Held in Configuration State, I/Os in High Impedance**

UG257_12_16_061506

*Figure 12-16:* **Installing the JP8 Jumper Holds the FPGA in Configuration State**

Re-apply power to the MicroBlaze Development Kit board.

## Programming the SPI Flash with the XSPI Software

Open a command prompt or DOS box and change to the XSPI installation directory.

The XSPI installation software also includes a short user guide, in addition to XAPP445. Type **`xspi`** at the prompt to view quick help.

Type the following command at the prompt to program the SPI Flash using the SPI-formatted Flash file generated earlier. This verifies that the SPI Flash is indeed an M25P16 SPI Flash and then erases, programs, and finally verifies the Flash.

```
C:\xspi>xspi -spi_dev m25p16 -spi_epv -mcs -i MySPIFlash.mcs -o output.txt
```

A disclaimer notice appears on the screen. Press the Enter key to continue. The entire programming process takes slightly longer than a minute, as shown in Figure 12-17.

```
-===< Press ENTER to accept notice and continue >===-

Start  : Mon Feb 27 13:37:07 2006

==> Checking SPI device [STMicro_M25P16_ver_00100] ID code(s)
    - density = [2097152] bytes
              = [16777216] bits
    - mfg_code = [0x20]
    - memory_type = [0x20]
    - density_code = [0x15]
+----------------------------------------+
| Device ID code(s) check ====>   [ OK ]  |
+----------------------------------------+
=> Operation: Erase
=> Operation: Program and Verify using file [MySPIFlash.mcs]
Programmed [283776] of [283776] bytes (w/ polling)
Verified   [283776] of [283776] bytes (0 errors)

--> Total byte mismatches [0] (see [temp.txt])
Finish : Mon Feb 27 13:38:22 2006
Elapsed clock time (00:01:15) = 75 seconds
```

UG257_12_17_060806

*Figure 12-17:* **Programming the M25P16 SPI Flash with the XSPI Programming Utility**

After programming the SPI Flash, remove jumper JP8, as shown in Figure 12-16(a). If properly programmed, the FPGA then configures itself from the SPI Flash PROM and the DONE LED lights. The DONE LED is shown in Figure 12-3, page 92.

# Additional Design Details

Figure 12-18 provides additional details of the SPI Flash interface used on the Spartan-3E Starter Kit board. In most applications, this interface is as simple as that shown in Figure 12-1, page 91. The Spartan-3E Starter Kit board, however, supports of variety of configuration options and demonstrates additional Spartan-3E capabilities.

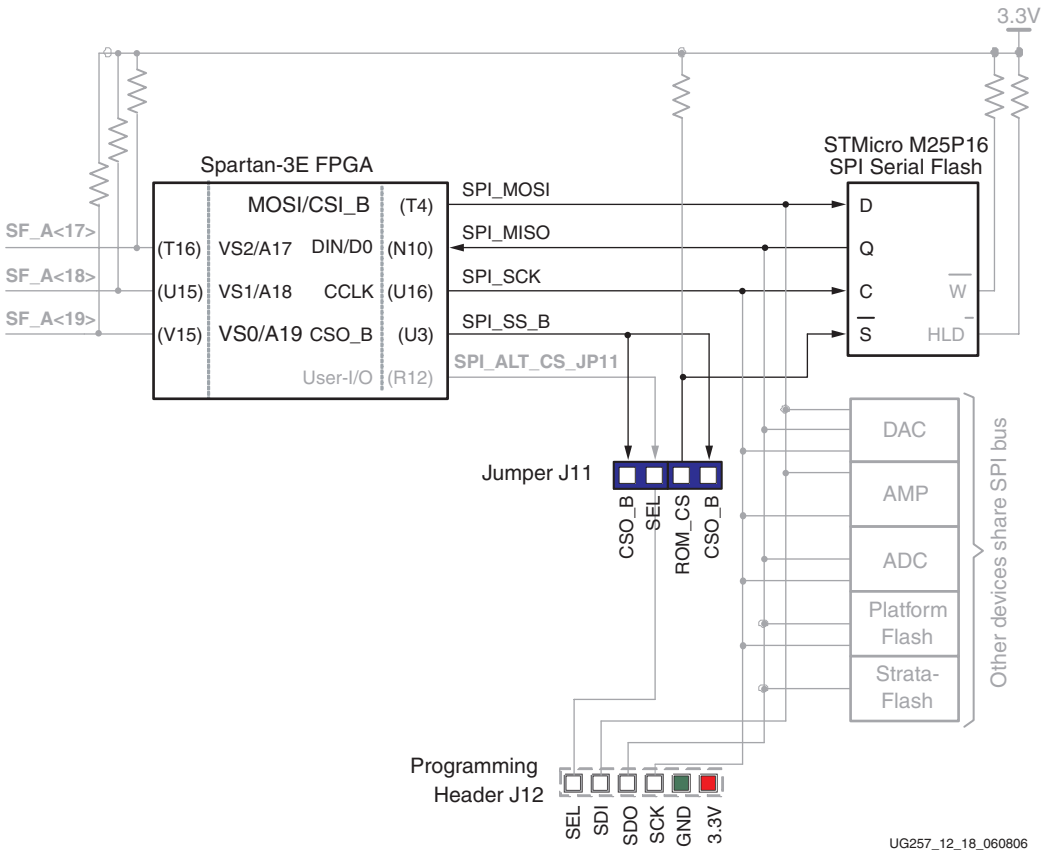


*Figure 12-18:* **Additional SPI Flash Interface Design Details**

## Shared SPI Bus with Peripherals

After configuration, the SPI Flash configuration pins are available to the application. On the Spartan-3E Starter Kit board, the SPI bus is shared by other SPI-capable peripheral devices, as shown in Figure 12-18. To access the SPI Flash memory after configuration, the FPGA application must disable the other devices on the shared SPI bus. Table 12-3 shows the signal names and disable values for the other devices.

*Table 12-3:* **Disable Other Devices on SPI Bus**

| Signal | Disabled Device | Disable Value |
|---|---|---|
| DAC_CS | Digital-to-Analog Converter (DAC) | 1 |
| AMP_CS | Programmable Pre-Amplifier | 1 |

*Table 12-3:* **Disable Other Devices on SPI Bus**

| Signal | Disabled Device | Disable Value |
|---|---|---|
| AD_CONV | Analog-to-Digital Converter (ADC) | 0 |
| SF_CE0 | StrataFlash Parallel Flash PROM | 1 |
| FPGA_INIT_B | Platform Flash PROM | 1 |

## Other SPI Flash Control Signals

The M25P16 SPI Flash has two additional control inputs. The active-Low write protect input (W) and the active-Low bus hold input (HLD) are unused and pulled High via an external pull-up resistor.

## Variant Select Pins, VS[2:0]

When in SPI configuration mode, the FPGA samples the value on three pins, labeled VS[2:0], to determine which SPI read command to issue to the SPI Flash. For the M25P16 Flash, VS[2:0]=<1:1:1> issues the correct command sequence. The VS[2:0] pins are pulled High externally via pull-up resistors to 3.3V. The VS[2:0] pins are also parallel NOR Flash address lines A[19:17] in the FPGA's BPI configuration mode and these signals also connect to the StrataFlash parallel Flash PROM. After SPI configuration, the VS[2:0] pins become user-programmable I/O pins, allowing full access to the StrataFlash PROM, despite that the FPGA configured from SPI Flash.

## Jumper Block J11

In SPI configuration mode, the FPGA selects the attached SPI Flash by asserting the CSO_B pin Low. On the MicroBlaze Development Kit board, the CSO_B pin drives into the jumper J11 block. This jumper block provides the option to move the on-board SPI Flash to a different select line (SPI_ALT_CS_JP11). This way, a different SPI Flash device can be tested by changing the JP11 jumper settings and connecting the alternate SPI Flash on Header JP12. By default, both jumpers are inserted on jumper block header J11.

## Programming Header J12

As shown in Figure 12-15, page 99, Header J12 accepts a JTAG parallel programming cable to program the on-board SPI Flash.

## Multi-Package Layout

STMicroelectronics was rather clever when they defined the package layout for the M25Pxx SPI serial Flash family. The Spartan-3E Starter Kit board supports all three of the package types used for the 16 Mbit device, as shown in Figure 12-19. By default, the board ships with the 8-lead, 8x6 mm MLP package. The multi-package layout also supports the 8-pin SOIC package and the 16-pin SOIC package. Pin 1 for the 8-pin SOIC and MLP packages is located in the top-left corner. However, pin 1 for the 16-pin SOIC package is located in the top-right corner, because the package is rotated 90°. The 16-pin SOIC package also have four pins on each side that do not connect on the board. These pins must be left floating. Why support multiple packages? In a word, flexibility. The multi-package layout provides ...

- **Density migration between smaller- and larger-density SPI Flash PROMs.** Not all SPI Flash densities are available in all packages. The SPI Flash migration strategy follows nicely with the pinout migration provided by Xilinx FPGAs.
- **Consistent configuration PROM layout when migrating between FPGA densities.** The Spartan-3E FPGA's FG320 package footprint supports the XC3S500E, the XC3S1200E, and the XC3S1600E FPGA devices without modification. The SPI Flash multi-package layout allows comparable flexibility in the associated configuration PROM. Ship the optimally-sized SPI Flash memory for the FPGA mounted on the board.
- **Supply security.** If a certain SPI Flash density is not available in the desired package, switch to a different package style or to a different density to secure availability.

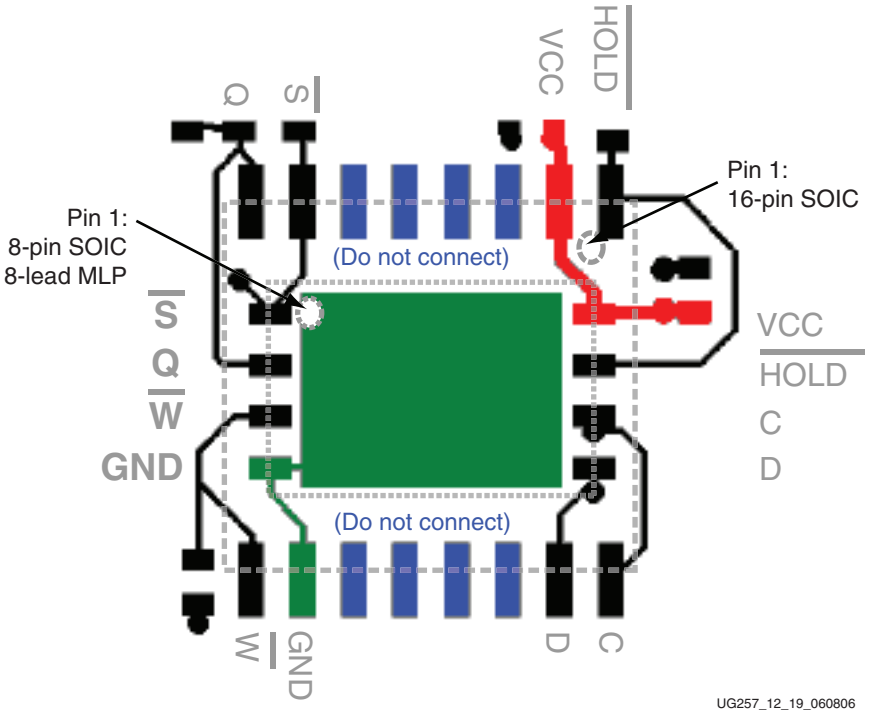


*Figure 12-19:* **Multi-Package Layout for the STMicroelectronics M25Pxx Family**

## Related Resources

- XAPP445: *Configuring Spartan-3E Xilinx FPGAs with SPI Flash Memories*
- http://www.xilinx.com/xlnx/xweb/xil_publications_display.jsp?category=Application+Notes/FPGA+Features+and+Design/Configuration&show=xapp445.pdf
- XSPI SPI Flash Programming Utility
- http://www.xilinx.com/xlnx/xweb/xil_publications_display.jsp?category=Application+Notes/FPGA+Features+and+Design/Configuration&show=xapp445.pdf
- Xilinx Parallel Cable IV with Flying Leads
- http://www.xilinx.com/xlnx/xebiz/productview.jsp?sGlobalNavPick=&category=-19314
- Digilent JTAG3 Programming Cable
- http://www.digilentinc.com/Products/Catalog.cfm?Nav1=Products&Nav2=Cables&Cat=Cable
- STMicroelectronics M25P16 SPI Serial Flash Data Sheet
- http://www.st.com/stonline/books/pdf/docs/10027.pdf
- AN1579: Compatibility between the SO8 Package and the MLP Package for the M25Pxx in Your Application
- http://www.st.com/stonline/products/literature/an/9540.pdf
- PicoBlaze SPI Serial Flash Programmer, via RS-232 (Reference Design)
- http://www.xilinx.com/s3estarter
- Using Serial Flash on the Spartan-3E Starter Kit Board (Reference Design)
- http://www.xilinx.com/s3estarter
- Universal Scan SPI Flash Programming via JTAG Training Video
- http://www.ricreations.com/JTAG-Software-Downloads.htm

Chapter 13

# DDR SDRAM

The MicroBlaze Development Kit board includes a 512 Mbit (32M x 16) Micron Technology DDR SDRAM (MT46V32M16) with a 16-bit data interface, as shown in Figure 13-1. All DDR SDRAM interface pins connect to the FPGA's I/O Bank 3 on the FPGA. I/O Bank 3 and the DDR SDRAM are both powered by 2.5V, generated by an LTC3412 regulator from the board's 5V supply input. The 1.25V reference voltage, common to the FPGA and DDR SDRAM, is generated using a resistor voltage divider from the 2.5V rail.

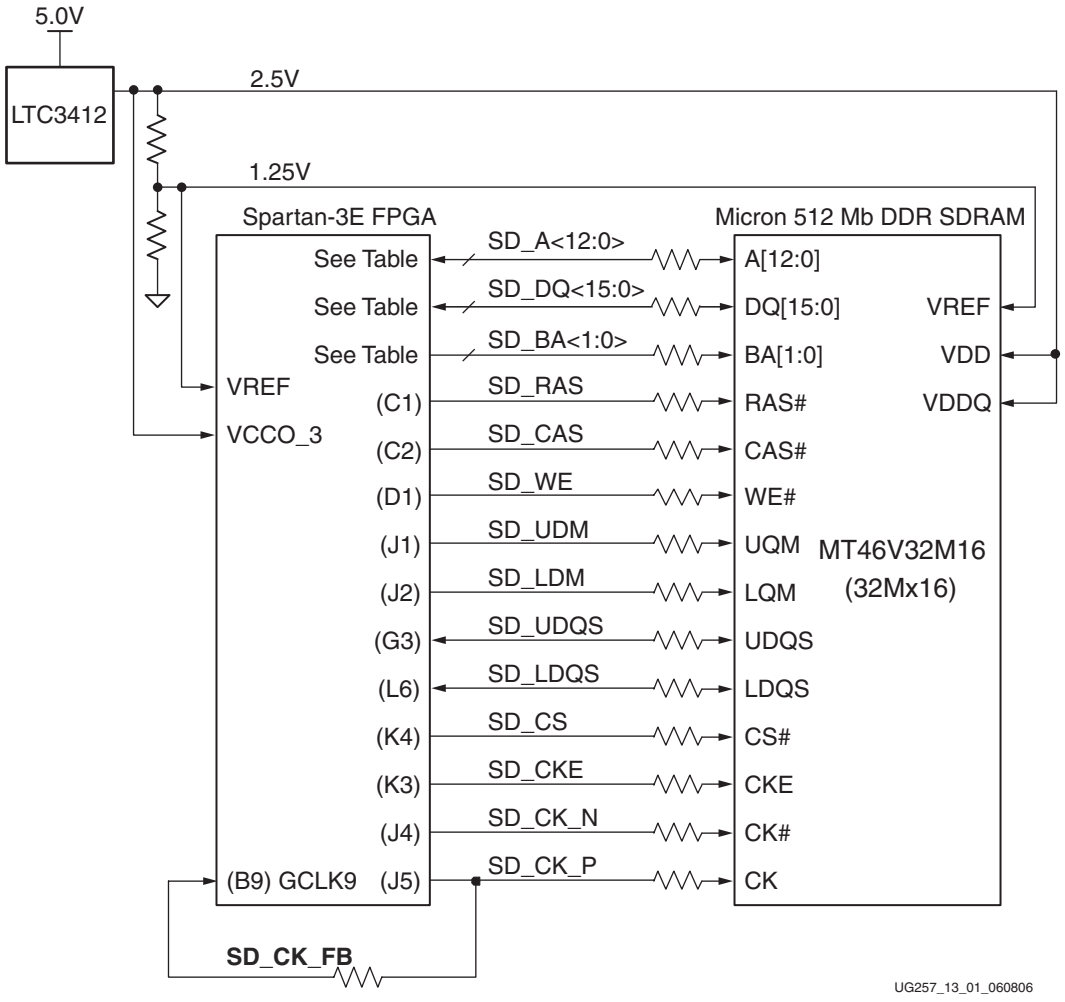


*Figure 13-1:* **FPGA Interface to Micron 512 Mbit DDR SDRAM**

All DDR SDRAM interface signals are terminated.

The differential clock pin SD_CK_P is fed back into FPGA pin B9 in I/O Bank 0 to have best access to one of the FPGA's Digital Clock Managers (DCMs). This path is required when using the MicroBlaze OPB DDR controller. The MicroBlaze OPB DDR SDRAM controller IP core documentation is also available from within the EDK 8.1i development software (see "Related Resources," page 109).

# DDR SDRAM Connections

Table 13-1 shows the connections between the FPGA and the DDR SDRAM.

*Table 13-1:* **FPGA-to-DDR SDRAM Connections**

| Category | DDR SDRAM Signal Name | FPGA Pin Number | Function |
|---|---|---|---|
| Address | SD_A12 | P2 | Address inputs |
| | SD_A11 | N5 | |
| | SD_A10 | T2 | |
| | SD_A9 | N4 | |
| | SD_A8 | H2 | |
| | SD_A7 | H1 | |
| | SD_A6 | H3 | |
| | SD_A5 | H4 | |
| | SD_A4 | E4 | |
| | SD_A3 | P1 | |
| | SD_A2 | R2 | |
| | SD_A1 | R3 | |
| | SD_A0 | T1 | |

*Table 13-1:* **FPGA-to-DDR SDRAM Connections *(Continued)***

| Category | DDR SDRAM Signal Name | FPGA Pin Number | Function |
|---|---|---|---|
| Data | SD_DQ15 | H5 | Data input/output |
| | SD_DQ14 | H6 | |
| | SD_DQ13 | G5 | |
| | SD_DQ12 | G6 | |
| | SD_DQ11 | F2 | |
| | SD_DQ10 | F1 | |
| | SD_DQ9 | E1 | |
| | SD_DQ8 | E2 | |
| | SD_DQ7 | M6 | |
| | SD_DQ6 | M5 | |
| | SD_DQ5 | M4 | |
| | SD_DQ4 | M3 | |
| | SD_DQ3 | L4 | |
| | SD_DQ2 | L3 | |
| | SD_DQ1 | L1 | |
| | SD_DQ0 | L2 | |
| Control | SD_BA1 | K6 | Bank address inputs |
| | SD_BA0 | K5 | |
| | SD_RAS | C1 | Command inputs |
| | SD_CAS | C2 | |
| | SD_WE | D1 | |
| | SD_CK_N | J4 | Differential clock input |
| | SD_CK_P | J5 | |
| | SD_CKE | K3 | Active-High clock enable input |
| | SD_CS | K4 | Active-Low chip select input |
| | SD_UDM | J1 | Data Mask. Upper and Lower data masks |
| | SD_LDM | J2 | |
| | SD_UDQS | G3 | Data Strobe. Upper and Lower data strobes |
| | SD_LDQS | L6 | |
| | SD_CK_FB | B9 | SDRAM clock feedback into top DCM within FPGA. Used by some DDR SDRAM controller cores |

# UCF Location Constraints

## Address

Figure 13-2 provides the User Constraint File (UCF) constraints for the DDR SDRAM address pins, including the I/O pin assignment and the I/O standard used.

```
NET "SD_A<12>"  LOC = "P2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<11>"  LOC = "N5" | IOSTANDARD = SSTL2_I ;
NET "SD_A<10>"  LOC = "T2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<9>"   LOC = "N4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<8>"   LOC = "H2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<7>"   LOC = "H1" | IOSTANDARD = SSTL2_I ;
NET "SD_A<6>"   LOC = "H3" | IOSTANDARD = SSTL2_I ;
NET "SD_A<5>"   LOC = "H4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<4>"   LOC = "E4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<3>"   LOC = "P1" | IOSTANDARD = SSTL2_I ;
NET "SD_A<2>"   LOC = "R2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<1>"   LOC = "R3" | IOSTANDARD = SSTL2_I ;
NET "SD_A<0>"   LOC = "T1" | IOSTANDARD = SSTL2_I ;
```

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*Figure 13-2:* **UCF Location Constraints for DDR SDRAM Address Inputs**

## Data

Figure 13-3 provides the User Constraint File (UCF) constraints for the DDR SDRAM data pins, including the I/O pin assignment and I/O standard used.

```
NET "SD_DQ<15>" LOC = "H5" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<14>" LOC = "H6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<13>" LOC = "G5" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<12>" LOC = "G6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<11>" LOC = "F2" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<10>" LOC = "F1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<9>"  LOC = "E1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<8>"  LOC = "E2" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<7>"  LOC = "M6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<6>"  LOC = "M5" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<5>"  LOC = "M4" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<4>"  LOC = "M3" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<3>"  LOC = "L4" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<2>"  LOC = "L3" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<1>"  LOC = "L1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<0>"  LOC = "L2" | IOSTANDARD = SSTL2_I ;
```

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*Figure 13-3:* **UCF Location Constraints for DDR SDRAM Data I/Os**

### Control

Figure 13-4 provides the User Constraint File (UCF) constraints for the DDR SDRAM control pins, including the I/O pin assignment and the I/O standard used.

```
NET "SD_BA<0>"  LOC = "K5" | IOSTANDARD = SSTL2_I ;
NET "SD_BA<1>"  LOC = "K6" | IOSTANDARD = SSTL2_I ;
NET "SD_CAS"    LOC = "C2" | IOSTANDARD = SSTL2_I ;
NET "SD_CK_N"   LOC = "J4" | IOSTANDARD = SSTL2_I ;
NET "SD_CK_P"   LOC = "J5" | IOSTANDARD = SSTL2_I ;
NET "SD_CKE"    LOC = "K3" | IOSTANDARD = SSTL2_I ;
NET "SD_CS"     LOC = "K4" | IOSTANDARD = SSTL2_I ;

NET "SD_LDM"    LOC = "J2" | IOSTANDARD = SSTL2_I ;
NET "SD_LDQS"   LOC = "L6" | IOSTANDARD = SSTL2_I ;
NET "SD_RAS"    LOC = "C1" | IOSTANDARD = SSTL2_I ;
NET "SD_UDM"    LOC = "J1" | IOSTANDARD = SSTL2_I ;
NET "SD_UDQS"   LOC = "G3" | IOSTANDARD = SSTL2_I ;
NET "SD_WE"     LOC = "D1" | IOSTANDARD = SSTL2_I ;
# Path to allow connection to top DCM connection
NET "SD_CK_FB"  LOC = "B9" | IOSTANDARD = LVCMOS33 ;
```

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*Figure 13-4:* **UCF Location Constraints for DDR SDRAM Control Pins**

### Reserve FPGA VREF Pins

Five pins in I/O Bank 3 are dedicated as voltage reference inputs, VREF. These pins cannot be used for general-purpose I/O in a design. Prohibit the software from using these pins with the constraints provided in Figure 13-5.

```
# Prohibit VREF pins
CONFIG PROHIBIT = D2;
CONFIG PROHIBIT = G4;
CONFIG PROHIBIT = J6;
CONFIG PROHIBIT = L5;
CONFIG PROHIBIT = R4;
```

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*Figure 13-5:* **UCF Location Constraints for StrataFlash Control Pins**

## Related Resources

- Xilinx Embedded Design Kit (EDK)
  http://www.xilinx.com/ise/embedded_design_prod/platform_studio.htm
- MT46V32M16 (32M x 16) DDR SDRAM Data Sheet
  http://download.micron.com/pdf/datasheets/dram/ddr/512MBDDRx4x8x16.pdf
- MicroBlaze OPB Double Data Rate (DDR) SDRAM Controller (v2.00b)
  http://www.xilinx.com/bvdocs/ipcenter/data_sheet/opb_ddr.pdf

Chapter 14

# 10/100 Ethernet Physical Layer Interface

The MicroBlaze Development Kit board includes a Standard Microsystems LAN83C185 10/100 Ethernet physical layer (PHY) interface and an RJ-45 connector, as shown in Figure 14-1. With an Ethernet Media Access Controller (MAC) implemented in the FPGA, the board can optionally connect to a standard Ethernet network. All timing is controlled from an on-board 25 MHz crystal oscillator.

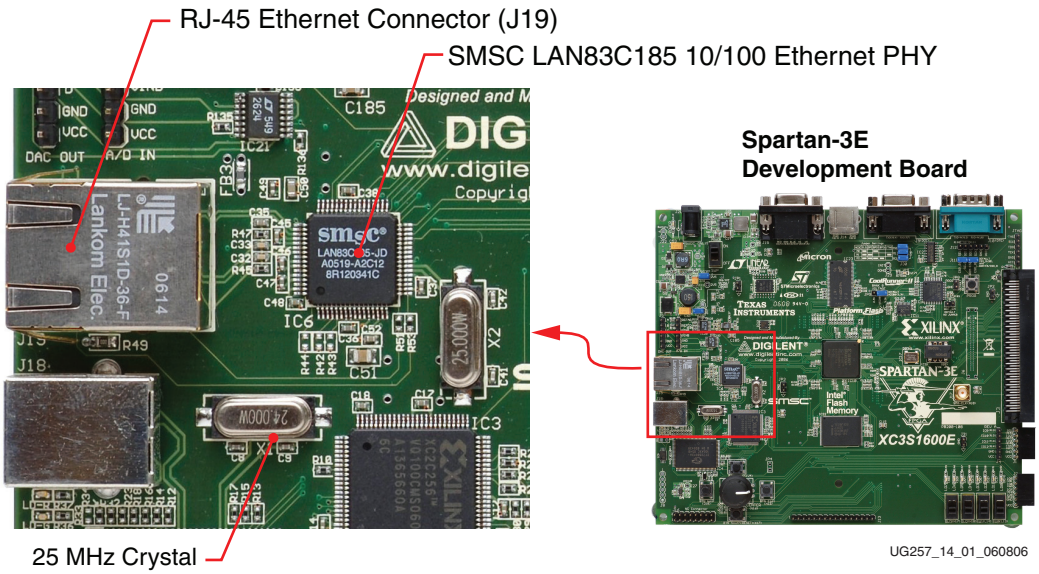


*Figure 14-1:* **10/100 Ethernet PHY with RJ-45 Connector**

# Ethernet PHY Connections

The FPGA connects to the LAN83C185 Ethernet PHY using a standard Media Independent Interface (MII), as shown in Figure 14-2. A more detailed description of the interface signals, including the FPGA pin number, appears in Table 14-1.

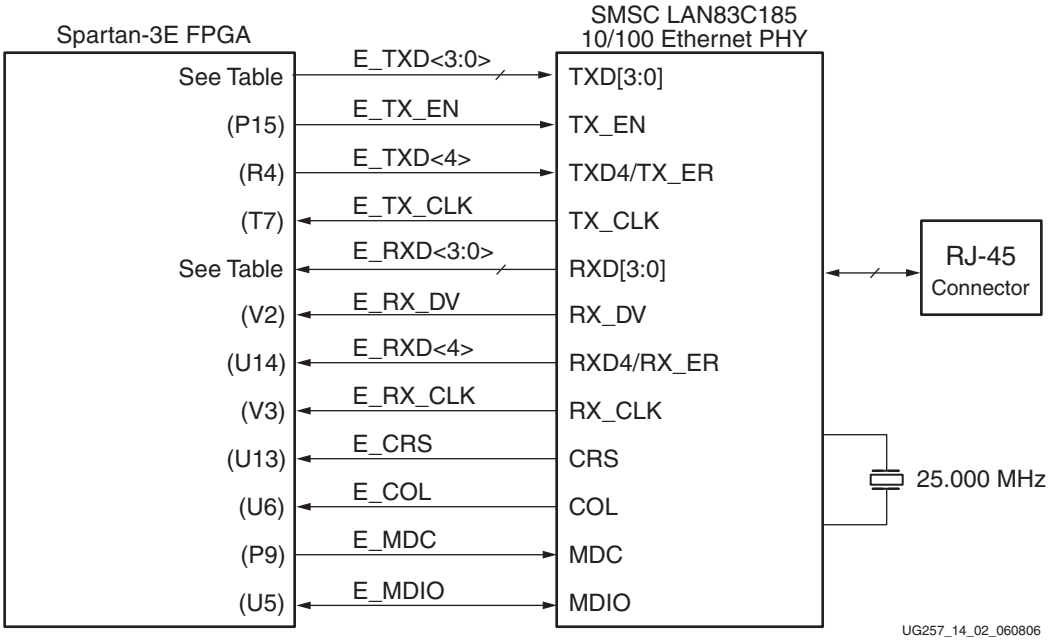


*Figure 14-2:* **FPGA Connects to Ethernet PHY via MII**

*Table 14-1:* **FPGA Connections to the LAN83C185 Ethernet PHY**

| Signal Name | FPGA Pin Number | Function |
|---|---|---|
| E_TXD<4> | R6 | Transmit Data to the PHY. E_TXD<4> is also the MII Transmit Error. |
| E_TXD<3> | T5 | |
| E_TXD<2> | R5 | |
| E_TXD<1> | T15 | |
| E_TXD<0> | R11 | |
| E_TX_EN | P15 | Transmit Enable. |
| E_TX_CLK | T7 | Transmit Clock. 25 MHz in 100Base-TX mode, and 2.5 MHz in 10Base-T mode. |
| E_RXD<4> | U14 | Receive Data from PHY. |
| E_RXD<3> | V14 | |
| E_RXD<2> | U11 | |
| E_RXD<1> | T11 | |
| E_RXD<0> | V8 | |
| E_RX_DV | V2 | Receive Data Valid. |

*Table 14-1:* **FPGA Connections to the LAN83C185 Ethernet PHY *(Continued)***

| Signal Name | FPGA Pin Number | Function |
|---|---|---|
| E_RX_CLK | V3 | Receive Clock. 25 MHz in 100Base-TX mode, and 2.5 MHz in 10Base-T mode. |
| E_CRS | U13 | Carrier Sense |
| E_COL | U6 | MII Collision Detect. |
| E_MDC | P9 | Management Clock. Serial management clock. |
| E_MDIO | U5 | Management Data Input/Output. |

# MicroBlaze Ethernet IP Cores

The Ethernet PHY is primarily intended for use with MicroBlaze applications. As such, an Ethernet MAC is part of the EDK Platform Studio's Base System Builder. Both the full Ethernet MAC and the *Lite* version are available for evaluation, as shown in Figure 14-3. The Ethernet Lite MAC controller core uses fewer FPGA resources and is ideal for applications that do not require support for interrupts, back-to-back data transfers, and statistics counters.

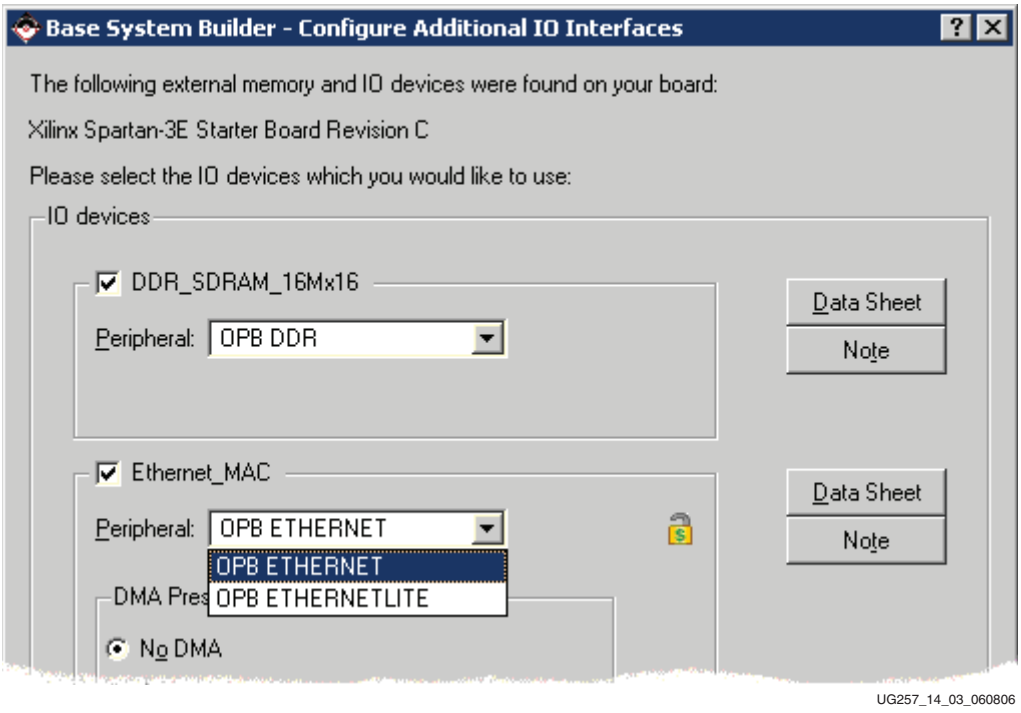


*Figure 14-3:* **Ethernet MAC IP Cores for the Spartan-3E Starter Kit Board**

The Ethernet MAC core requires design constraints to meet the required performance. Refer to the OPB Ethernet MAC data sheet (v1.02) for details. The OPB bus clock frequency must be 65 MHz or higher for 100 Mbps Ethernet operations and 6.5 MHz or faster for 10 Mbps Ethernet operations.

The hardware evaluation versions of the Ethernet MAC cores operate for approximately eight hours in silicon before timing out. To order the full version of the core, visit the Xilinx website at:

http://www.xilinx.com/ipcenter/processor_central/processor_ip/10-100emac/10-100emac_order_register.htm

# UCF Location Constraints

Figure 14-4 provides the UCF constraints for the 10/100 Ethernet PHY interface, including the I/O pin assignment and the I/O standard used.

```
NET "E_COL"    LOC = "U6"  | IOSTANDARD = LVCMOS33 ;
NET "E_CRS"    LOC = "U13" | IOSTANDARD = LVCMOS33 ;
NET "E_MDC"    LOC = "P9"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_MDIO"   LOC = "U5"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_RX_CLK" LOC = "V3"  | IOSTANDARD = LVCMOS33 ;
NET "E_RX_DV"  LOC = "V2"  | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<0>" LOC = "V8"  | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<1>" LOC = "T11" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<2>" LOC = "U11" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<3>" LOC = "V14" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<4>" LOC = "U14" | IOSTANDARD = LVCMOS33 ;
NET "E_TX_CLK" LOC = "T7"  | IOSTANDARD = LVCMOS33 ;
NET "E_TX_EN"  LOC = "P15" | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_TXD<0>" LOC = "R11" | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_TXD<1>" LOC = "T15" | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_TXD<2>" LOC = "R5"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_TXD<3>" LOC = "T5"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
NET "E_TXD<4>" LOC = "R6"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
```

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*Figure 14-4:* **UCF Location Constraints for 10/100 Ethernet PHY Inputs**

# Related Resources

- Standard Microsystems SMSC LAN83C185 10/100 Ethernet PHY
- http://www.smsc.com/main/catalog/lan83c185.html
- Xilinx OPB Ethernet Media Access Controller (EMAC) (v1.02a)
- http://www.xilinx.com/bvdocs/ipcenter/data_sheet/opb_ethernet.pdf
- Xilinx OPB Ethernet Lite Media Access Controller (v1.01a)
- The Ethernet Lite MAC controller core uses fewer FPGA resources and is ideal for applications the do not require support for interrupts, back-to-back data transfers, and statistics counters.
- http://www.xilinx.com/bvdocs/ipcenter/data_sheet/opb_ethernetlite.pdf
- EDK 8.1i Documentation
- http://www.xilinx.com/ise/embedded/edk_docs.htm

Chapter 15

# Expansion Connectors

The MicroBlaze Development Kit board provides a variety of expansion connectors for easy interface flexibility to other off-board components. The board includes the following I/O expansion headers (see Figure 15-1):

- A Hirose 100-pin edge connector with 43 associated FPGA user-I/O pins, including up to 15 differential LVDS I/O pairs and two Input-only pairs
- Three 6-pin Peripheral Module connections
- Landing pads for an Agilent or Tektronix connectorless probe

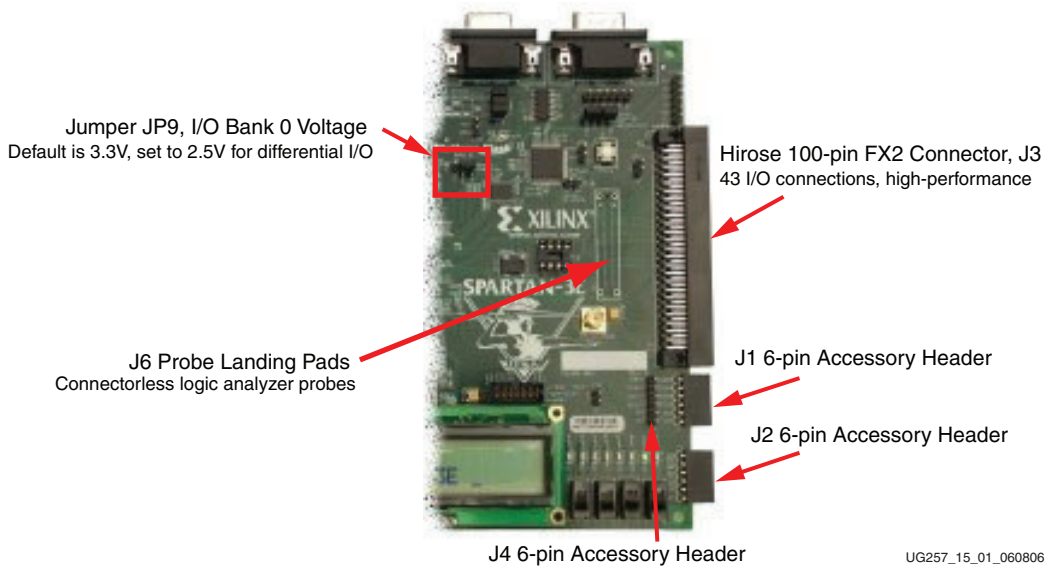


*Figure 15-1:* **Expansion Headers**

## Hirose 100-pin FX2 Edge Connector (J3)

A 100-pin edge connector is located along the right edge of the board (see Figure 15-1). This connector is a Hirose FX2-100P-1.27DS header with 1.27 mm pitch. Throughout the documentation, this connector is called the FX2 connector.

As shown in Figure 15-2, 43 FPGA I/O pins interface to the FX2 connector. All but five of these pins are true, bidirectional I/O pins capable of driving or receiving signals. Five pins, FX2_IP<38:35> and FX2_IP<40> are Input-only pins on the FPGA. These pins are highlighted in light green in Table 15-1 and cannot drive the FX2 connector but can receive signals.

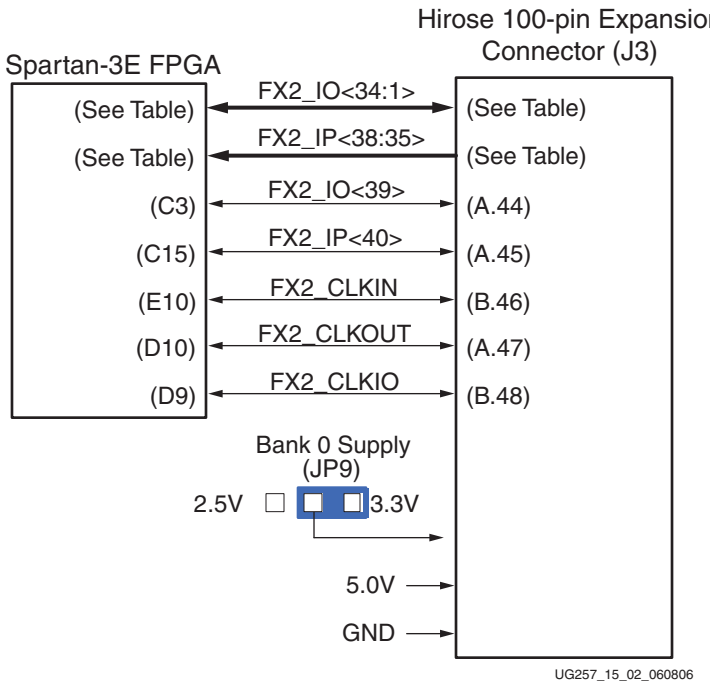


*Figure 15-2:* **FPGA Connections to the Hirose 100-pin Edge Connector**

Three signals are reserved primarily as clock signals between the board and FX2 connector, although all three connect to full I/O pins.

## Voltage Supplies to the Connector

The MicroBlaze Development Kit board provides power to the Hirose 100-pin FX connector and any attached board via two supplies (see Figure 15-2). The 5.0V supply provides a voltage source for any 5V logic on the attached board or alternately provides power to any voltage regulators on the attached board.

A separate supply provides the same voltage at that applied to the FPGA's I/O Bank 0. All FPGA I/Os that interface to the Hirose connector are in Bank 0. The I/O Bank 0 supply is 3.3V by default. However, the voltage level can be changed to 2.5V using jumper JP9. Some FPGA I/O standards—especially the differential standards such as RSDS and LVDS—require a 2.5V output supply voltage.

To support high-speed signals across the connector, a majority of pins on the B-side of the FX2 connector are tied to GND.

## Connector Pinout and FPGA Connections

Table 15-1 shows the pinout for the Hirose 100-pin FX2 connector and the associated FPGA pin connections. The FX2 connect has two rows of connectors, both with 50 connections each, shown in the table using light yellow shading.

Table 15-1 also highlights the shared connections to the eight discrete LEDs, the three 6-pin Accessory Headers (J1, J2, and J4), and the connectorless debugging header (J6).

*Table 15-1:* **Hirose 100-pin FX2 Connector Pinout and FPGA Connections (J3)**

| Signal Name | FPGA Pin | Shared Header Connections | | FX2 Connector | | FPGA Pin | Signal Name |
|---|---|---|---|---|---|---|---|
| | | LED | J6 | A (top) | B (bottom) | | |
| | VCCO_0 | | | 1 | 1 | | SHIELD |
| | VCCO_0 | | | 2 | 2 | GND | GND |
| TMS_B | | | | 3 | 3 | | TDO_XC2C |
| JTSEL | | | | 4 | 4 | | TCK_B |
| TDO_FX2 | | | | 5 | 5 | GND | GND |
| FX2_IO1 | B4 | | ◆ | 6 | 6 | GND | GND |
| FX2_IO2 | A4 | | ◆ | 7 | 7 | GND | GND |
| FX2_IO3 | D5 | | ◆ | 8 | 8 | GND | GND |
| FX2_IO4 | C5 | | ◆ | 9 | 9 | GND | GND |
| FX2_IO5 | A6 | | ◆ | 10 | 10 | GND | GND |
| FX2_IO6 | B6 | | ◆ | 11 | 11 | GND | GND |
| FX2_IO7 | E7 | | ◆ | 12 | 12 | GND | GND |
| FX2_IO8 | F7 | | ◆ | 13 | 13 | GND | GND |
| FX2_IO9 | D7 | | ◆ | 14 | 14 | GND | GND |
| FX2_IO10 | C7 | | ◆ | 15 | 15 | GND | GND |
| FX2_IO11 | F8 | | ◆ | 16 | 16 | GND | GND |
| FX2_IO12 | E8 | | ◆ | 17 | 17 | GND | GND |
| FX2_IO13 | F9 | | ◆ | 18 | 18 | GND | GND |
| FX2_IO14 | E9 | | ◆ | 19 | 19 | GND | GND |
| FX2_IO15 | D11 | | ◆ | 20 | 20 | GND | GND |
| FX2_IO16 | C11 | | ◆ | 21 | 21 | GND | GND |
| FX2_IO17 | F11 | | ◆ | 22 | 22 | GND | GND |
| FX2_IO18 | E11 | | ◆ | 23 | 23 | GND | GND |
| FX2_IO19 | E12 | | | 24 | 24 | GND | GND |
| FX2_IO20 | F12 | | | 25 | 25 | GND | GND |
| FX2_IO21 | A13 | | | 26 | 26 | GND | GND |
| FX2_IO22 | B13 | | | 27 | 27 | GND | GND |
| FX2_IO23 | A14 | | | 28 | 28 | GND | GND |
| FX2_IO24 | B14 | | | 29 | 29 | GND | GND |
| FX2_IO25 | C14 | | | 30 | 30 | GND | GND |
| FX2_IO26 | D14 | | | 31 | 31 | GND | GND |
| FX2_IO27 | A16 | | | 32 | 32 | GND | GND |

*Table 15-1:* **Hirose 100-pin FX2 Connector Pinout and FPGA Connections (J3)**

| Signal Name | FPGA Pin | Shared Header Connections | | FX2 Connector | | FPGA Pin | Signal Name |
|---|---|---|---|---|---|---|---|
| | | LED | J6 | A (top) | B (bottom) | | |
| FX2_IO28 | B16 | | | 33 | 33 | GND | GND |
| FX2_IO29 | E13 | | | 34 | 34 | GND | GND |
| FX2_IO30 | C4 | | | 35 | 35 | GND | GND |
| FX2_IO31 | B11 | | | 36 | 36 | GND | GND |
| FX2_IO32 | A11 | | | 37 | 37 | GND | GND |
| FX2_IO33 | A8 | LED7 | | 38 | 38 | GND | GND |
| FX2_IO34 | G9 | LED6 | | 39 | 39 | GND | GND |
| FX2_IP35 | A7 | LED5 | | 40 | 40 | GND | GND |
| FX2_IP36 | D13 | LED4 | | 41 | 41 | GND | GND |
| FX2_IP37 | E6 | LED3 | | 42 | 42 | GND | GND |
| FX2_IP38 | D6 | LED2 | | 43 | 43 | GND | GND |
| FX2_IO39 | C3 | LED1 | | 44 | 44 | GND | GND |
| FX2_IP40 | C15 | | | 45 | 45 | GND | GND |
| GND | GND | | | 46 | 46 | E10 | FX2_CLKIN |
| FX2_CLKOUT | D10 | | | 47 | 47 | GND | GND |
| GND | GND | | | 48 | 48 | D9 | FX2_CLKIO |
| 5.0V | | | | 49 | 49 | | 5.0V |
| 5.0V | | | | 50 | 50 | | SHIELD |

## Compatible Board

The following board is compatible with the FX2 connector on the MicroBlaze Development Kit board:

- VDEC1 Video Decoder Board from Digilent, Inc.
  http://www.digilentinc.com/Products/Detail.cfm?Prod=VDEC1

## Mating Receptacle Connectors

The MicroBlaze Development Kit board uses a Hirose FX2-100P-1.27DS header connector. The header mates with any compatible 100-pin receptacle connector, including board-mounted and non-locking cable connectors.

## Differential I/O

The Hirose FX2 connector, header J3, supports up to 15 differential I/O pairs and two input-only pairs using either the LVDS or RSDS I/O standards, as listed in Table 15-2. All I/O pairs support differential input termination (DIFF_TERM) as described in the

Spartan-3E data sheet. Select pairs have optional landing pads for external termination resistors.

These signals are not routed with matched differential impedance, as would be required for ultimate performance. However, all traces have similar lengths to minimize skew.

*Table 15-2:* **Differential I/O Pairs**

| Differential Pair | Signal Name | FPGA Pins | FPGA Pin Name | Direction | DIFF_TERM | External Resistor Designator |
|---|---|---|---|---|---|---|
| 1 | FX2_IO1 | B4 | IO_L24N_0 | I/O | Yes | |
| | FX2_IO2 | A4 | IO_L24P_0 | I/O | Yes | |
| 2 | FX2_IO3 | D5 | IO_L23N_0 | I/O | Yes | |
| | FX2_IO4 | C5 | IO_L23P_0 | I/O | Yes | |
| 3 | FX2_IO5 | A6 | IO_L20N_0 | I/O | Yes | |
| | FX2_IO6 | B6 | IO_L20P_0 | I/O | Yes | |
| 4 | FX2_IO7 | E7 | IO_L19N_0 | I/O | Yes | |
| | FX2_IO8 | F7 | IO_L19P_0 | I/O | Yes | |
| 5 | FX2_IO9 | D7 | IO_L18N_0 | I/O | Yes | |
| | FX2_IO10 | C7 | IO_L18P_0 | I/O | Yes | |
| 6 | FX2_IO11 | F8 | IO_L17N_0 | I/O | Yes | |
| | FX2_IO12 | E8 | IO_L17P_0 | I/O | Yes | |
| 7 | FX2_IO13 | F9 | IP_L15N_0 | I/O | Yes | |
| | FX2_IO14 | E9 | IP_L15P_0 | I/O | Yes | |
| 8 | FX2_IO15 | D11 | IP_L09N_0 | I/O | Yes | |
| | FX2_IO16 | C11 | IP_L09P_0 | I/O | Yes | |
| 9 | FX2_IO17 | F11 | IO_L08N_0 | I/O | Yes | R202 |
| | FX2_IO18 | E11 | IO_L08P_0 | I/O | Yes | |
| 10 | FX2_IO19 | E12 | IO_L06N_0 | I/O | Yes | R203 |
| | FX2_IO20 | F12 | IO_L06P_0 | I/O | Yes | |
| 11 | FX2_IO21 | A13 | IO_L05P_0 | I/O | Yes | R204 |
| | FX2_IO22 | B13 | IO_L05N_0 | I/O | Yes | |
| 12 | FX2_IO23 | A14 | IO_L04N_0 | I/O | Yes | R205 |
| | FX2_IO24 | B14 | IO_L04P_0 | I/O | Yes | |
| 13 | FX2_IO25 | C14 | IO_L03N_0 | I/O | Yes | R206 |
| | FX2_IO26 | D14 | IO_L03P_0 | I/O | Yes | |
| 14 | FX2_IO27 | A16 | IO_L01N_0 | I/O | Yes | R207 |
| | FX2_IO28 | B16 | IO_L01P_0 | I/O | Yes | |

*Table 15-2:* **Differential I/O Pairs *(Continued)***

| Differential Pair | Signal Name | FPGA Pins | FPGA Pin Name | Direction | DIFF_TERM | External Resistor Designator |
|---|---|---|---|---|---|---|
| 15 | FX2_IP35 | D12 | IP_L07N_0 | Input | | R208 |
| | FX2_IP36 | C12 | IP_L07P_0 | Input | | |
| 16 | FX2_IP37 | A15 | IP_L02N_0 | Input | | R209 |
| | FX2_IP38 | B15 | IP_L02P_0 | Input | | |
| 17 | FX2_ CLKIN | E10 | IO_L11N_0/ GCLK5 | I/O | Yes | R210 |
| | FX2_ CLKOUT | D10 | IO_L11P_0/ GCLK4 | I/O | Yes | |

## Using Differential Inputs

LVDS and RSDS differential inputs require input termination. Two options are available. The first option is to use external termination resistors, as shown in Figure 15-3a. The board provides landing pads for external 100Ω termination resistors. The resistors are not loaded on the board as shipped. The resistor reference designators are labeled on the silkscreen, as listed in Table 15-2. The landing pads are located on both the top- and bottom-side of the board, between the FPGA and the FX2 connector. The resistors are not loaded on the board as shipped. External termination is always required when using differential input pairs 15 and 16.

The second option, shown in Figure 15-3b, is a Spartan-3E feature called on-chip differential termination, which uses the DIFF_TERM attribute available on differential I/O signals. Each differential I/O pin includes a circuit that behaves like an internal termination resistor of approximately 120Ω. On-chip differential termination is only available on I/O pairs, not on Input-only pairs like pairs 15 and 16 in Table 15-2.

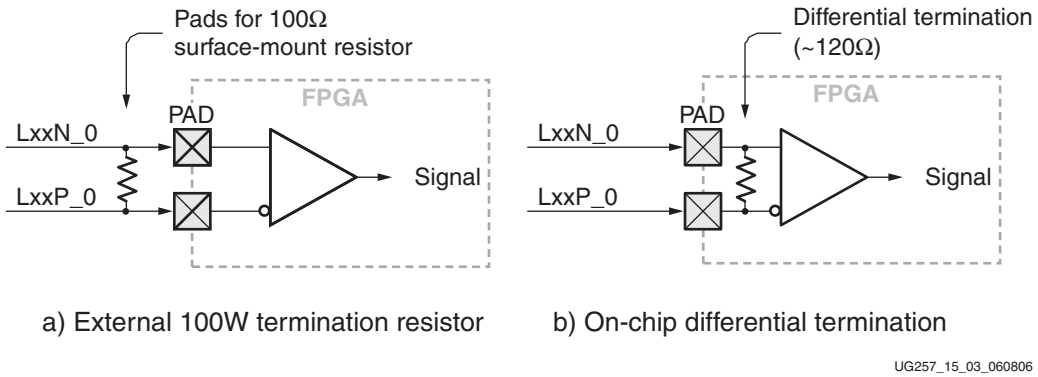


*Figure 15-3:* **Differential Input Termination Options**

Figure 15-4 and Figure 15-5 show the locations of the differential input termination resistor landing pads on the top and bottom side of the board. Table 15-2 indicates which resistor is associated with a specific differential pair.

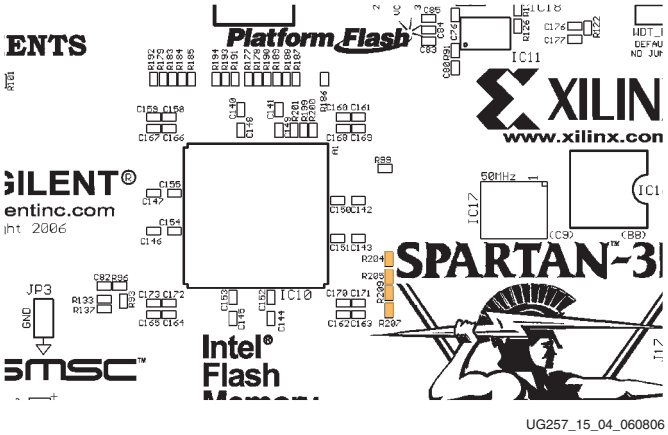


*Figure 15-4:* **Location of Termination Resistor Pads on Top Side of Board**


*Figure 15-5:* **Location of Termination Resistor Pads on Bottom Side of Board**

## Using Differential Outputs

Differential input signals do not require any special voltage. LVDS and RSDS differential outputs signals, on the other hand, require a 2.5V supply on I/O Bank 0. The board provides the option to power I/O Bank 0 with either 3.3V or 2.5V. Figure 15-1, page 115 highlights the location of jumper JP9.

If using differential outputs on the FX2 connector, set jumper JP9 to 2.5V. If the jumper is not set correctly, the outputs switch correctly but the signal levels are out of specification.

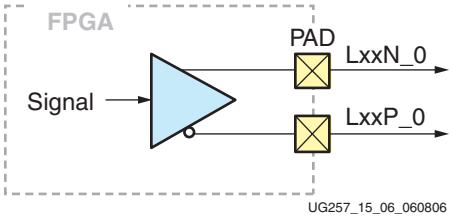


*Figure 15-6:* **Differential Outputs**

## UCF Location Constraints

Figure 15-7 provides the UCF constraints for the FX2 connector, including the I/O pin assignment and the I/O standard used, assuming that all connections use single-ended I/O standards. These header connections are shared with the 6-pin accessory headers, as shown in Figure 15-11, page 124.

```
# ==== FX2 Connector (FX2) ====
NET "FX2_CLKIN" LOC = "E10" | IOSTANDARD = LVCMOS33 ;
NET "FX2_CLKIO" LOC = "D9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_CLKOUT" LOC = "D10" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<1>" LOC = "B4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<2>" LOC = "A4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<3>" LOC = "D5" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<4>" LOC = "C5" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
 NET "FX2_IO<5>" LOC = "A6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
 NET "FX2_IO<6>" LOC = "B6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<7>" LOC = "E7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<8>" LOC = "F7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
 NET "FX2_IO<9>" LOC = "D7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<10>" LOC = "C7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<11>" LOC = "F8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<12>" LOC = "E8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<13>" LOC = "F9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<14>" LOC = "E9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<15>" LOC = "D11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<16>" LOC = "C11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<17>" LOC = "F11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<18>" LOC = "E11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<19>" LOC = "E12" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<20>" LOC = "F12" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<21>" LOC = "A13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<22>" LOC = "B13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<23>" LOC = "A14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<24>" LOC = "B14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<25>" LOC = "C14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<26>" LOC = "D14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<27>" LOC = "A16" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<28>" LOC = "B16" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<29>" LOC = "E13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<30>" LOC = "C4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<31>" LOC = "B11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<32>" LOC = "A11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
# The discrete LEDs are shared with the following 8 FX2 connections #
NET "FX2_IO<33>" LOC = "A8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;# LED7
# NET "FX2_IO<34>" LOC = "G9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED6
# NET "FX2_IP<35>" LOC = "A7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED5
# NET "FX2_IP<36>" LOC = "D13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED4
# NET "FX2_IP<37>" LOC = "E6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED3
# NET "FX2_IP<38>" LOC = "D6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED2
# NET "FX2_IO<39>" LOC = "C3" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED1
#NET "FX2_IP<40>" LOC = "C15" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
```

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*Figure 15-7:* **UCF Location Constraints for Accessory Headers**

# Six-Pin Accessory Headers

The 6-pin accessory headers provide easy I/O interface expansion using the various Digilent Peripheral Modules (see "Related Resources," page 126). The location of the 6-pin headers is provided in Figure 15-1, page 115.

## Header J1

The J1 header, shown in Figure 15-8, is the top-most 6-pin connector along the right edge of the board. It uses a female 6-pin 90° socket. Four FPGA pins connect to the J1 header, J1<4:1>. The board supplies 3.3V to the accessory board mounted in the J1 socket on the bottom pin.

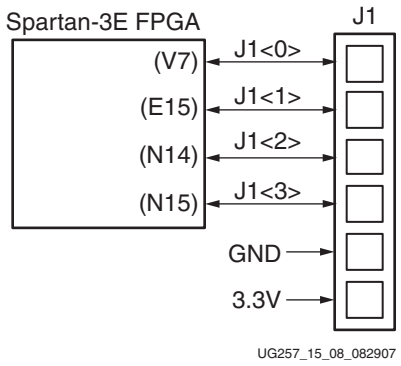


*Figure 15-8:* **FPGA Connections to the J1 Accessory Header**

## Header J2

The J2 header, shown in Figure 15-9, is the bottom-most 6-pin connector along the right edge of the board. It uses a female 6-pin 90° socket. Four FPGA pins connect to the J2 header, J2<4:1>. The board supplies 3.3V to the accessory board mounted in the J4 socket on the bottom pin.

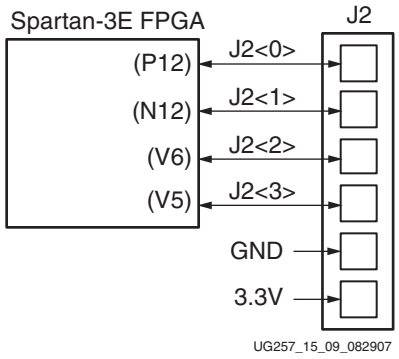


*Figure 15-9:* **FPGA Connections to the J2 Accessory Header**

### Header J4

The J4 header, shown in Figure 15-10, is located immediately to the left of the J1 header. It uses a 6-pin header consisting of 0.1-inch centered stake pins. Four FPGA pins connect to the J4 header, J4<4:1>. Four FPGA pins connect to the J4<4:1> header. The board supplies 3.3V to the accessory board mounted in the J4 socket on the bottom pin.

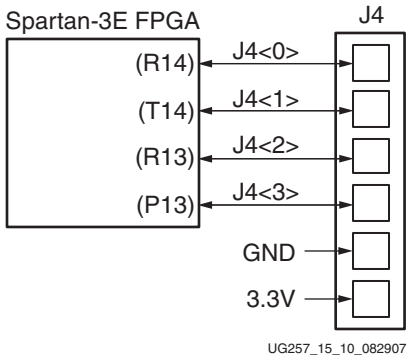


*Figure 15-10:* **FPGA Connections to the J4 Accessory Header**

## UCF Location Constraints

Figure 15-11 provides the User Constraint File (UCF) constraints for accessory headers, including the I/O pin assignment and the I/O standard used. These header connections are shared with the FX2 connector, as shown in Figure 15-7, page 122.

```
# ==== 6-pin header J1 ====
# These four connections are shared with the FX2 connector
#NET "J1<0>"  LOC = "B4" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J1<1>"  LOC = "A4" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J1<2>"  LOC = "D5" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J1<3>"  LOC = "C5" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;

# ==== 6-pin header J2 ====
# These four connections are shared with the FX2 connector
#NET "J2<0>"  LOC = "A6" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J2<1>"  LOC = "B6" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J2<2>"  LOC = "E7" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J2<3>"  LOC = "F7" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;

# ==== 6-pin header J4 ====
# These four connections are shared with the FX2 connector
#NET "J4<0>"  LOC = "D7" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J4<1>"  LOC = "C7" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J4<2>"  LOC = "F8" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
#NET "J4<3>"  LOC = "E8" | IOSTANDARD = LVTTL  | SLEW = SLOW  | DRIVE = 6 ;
```

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*Figure 15-11:* **UCF Location Constraints for Accessory Headers**

# Connectorless Debugging Port Landing Pads (J6)

Landing pads for a connectorless debugging port are provided as header J6, shown in Figure 15-1, page 115. There is no physical connector on the board. Instead a connectorless probe, such as those available from Agilent, provides an interface to a logic analyzer. This debugging port is intended primarily for the Xilinx ChipScope Pro software with the Agilent's FPGA Dynamic Probe. It can, however, be used with either the Agilent or Tektronix probes, without the ChipScope software, using FPGA Editor's probe command. Refer to "Related Resources," page 126 for more information on the ChipScope Pro tool, probes, and connectors.

Table 15-3 provides the connector pinout. Only 18 FPGA pins attach to the connector; the remaining connector pads are unconnected. All 18 FPGA pins are shared with the FX2 connector (J3) and the 6-pin accessory port connectors (J1, J2, and J4). See Table 15-1, page 117 for more information on how these pins are shared.

*Table 15-3:* **Connectorless Debugging Port Landing Pads (J6)**

| Signal Name | FPGA Pin | Connectorless Landing Pads | | FPGA Pin | Signal Name |
|---|---|---|---|---|---|
| FX2_IO1 | B4 | A1 | B1 | GND | GND |
| FX2_IO2 | A4 | A2 | B2 | D5 | FX2_IO3 |
| GND | GND | A3 | B3 | C5 | FX2_IO4 |
| FX2_IO5 | A6 | A4 | B4 | GND | GND |
| FX2_IO6 | B6 | A5 | B5 | E7 | FX2_IO7 |
| GND | GND | A6 | B6 | F7 | FX2_IO8 |
| FX2_IO9 | D7 | A7 | B7 | GND | GND |
| FX2_IO10 | C7 | A8 | B8 | F8 | FX2_IO11 |
| GND | GND | A9 | B9 | E8 | FX2_IO12 |
| FX2_IO13 | F9 | A10 | B10 | GND | GND |
| FX2_IO14 | E9 | A11 | B11 | D11 | FX2_IO15 |
| GND | GND | A12 | B12 | C11 | FX2_IO16 |
| FX2_IO17 | F11 | A13 | B13 | GND | GND |
| FX2_IO18 | E11 | A14 | B14 | | |
| | | A15 | B15 | | |
| | | A16 | B16 | | |
| | | A17 | B17 | | |
| | | A18 | B18 | | |
| | | A19 | B19 | | |
| | | A20 | B20 | | |
| | | A21 | B21 | | |
| | | A22 | B22 | | |
| | | A23 | B23 | | |
| | | A24 | B24 | | |
| | | A25 | B25 | | |
| | | A26 | B26 | | |
| | | A27 | B27 | | |

## Related Resources

- Hirose connectors
  http://www.hirose-connectors.com/
- FX2 Series Connector Data Sheet
  http://www.hirose.co.jp/cataloge_hp/e57220088.pdf
- Digilent, Inc. Peripheral Modules
  http://www.digilentinc.com/Products/Catalog.cfm?Nav1=Products&Nav2=Peripheral&Cat=Peripheral
- Xilinx ChipScope Pro Tool
  http://www.xilinx.com/ise/optional_prod/cspro.htm
- Agilent B4655A FPGA Dynamic Probe for Logic Analyzer
  http://www.home.agilent.com/USeng/nav/-536898189.536883660/pd.html?cmpid=92641
- Agilent 5404A/6A Pro Series Soft Touch Connector
  http://www.home.agilent.com/cgi-bin/pub/agilent/Product/cp_Product.jsp?NAV_ID=-536898227.0.00
- Tektronix P69xx Probe Module s with D-Max Technology
  http://www.tek.com/products/accessories/logic_analyzers/p6800_p6900.html

Chapter 16

# XC2C64A CoolRunner-II CPLD

The MicroBlaze Development Kit board includes a Xilinx XC2C64A CoolRunner-II CPLD. The CPLD is user programmable and available for customer applications. Portions of the CPLD are reserved to coordinate behavior between the various FPGA configuration memories, namely the Xilinx Platform Flash PROM and the Intel StrataFlash PROM. Consequently, the CPLD must provide the following functions in addition to the user application.

- When the FPGA is in the Master Serial configuration mode (FPGA_M<2:0>=000), generate an active-Low enable signal for the XCF04S Platform Flash PROM. The Platform Flash PROM is disabled in all other configuration modes. The CPLD helps reduce the number of jumpers on the board and simplifies the interaction of all the possible FPGA configuration memory sources.
- When the FPGA is actively in the BPI-Up configuration mode (FPGA_M<2:0>=010, DONE=0), set the upper five StrataFlash PROM address lines, A[24:20], to 00000 binary. When the FPGA is actively in the BPI-Down configuration mode (FPGA_M<2:0>=011, DONE=0), set the upper five StrataFlash PROM address lines, A[24:20], to 11111 binary. Set the upper five address lines to ZZZZZ for all non-BPI configuration modes or whenever the FPGA's DONE pin is High. This behavior is identifical to the way the FPGA's upper address lines function during BPI mode. So why add a CPLD to mimic this behavior? A future reference design demonstrates unique configuration capabilities. In a typical BPI-mode application, the CPLD is not required.

Other than the required CPLD functionality, there are between 13 to 21 user-I/O pins and 58 remaining macrocells available to the user application.

Jumper JP10 (WDT_EN) defines the state on the CPLD's XC_WDT_EN signal. By default, this jumper is empty and the signal is pulled to a logic High.

The XC_PROG_B output from the CPLD, if used, must be configured as an open-drain out (*i.e.*, either actively drives Low or floats to Hi-Z, never drives High). This signal connects directly to the FPGA's PROG_B programming pin.

The most-siginficant StrataFlash PROM address bit, SF_A<24>, is the same as the FX2 connector signal called FX2_IO<32>. The 16 Mbyte StrataFlash PROM only physically uses the lower 24 bits, SF_A<23:0>. The extra address bit, SF_A<24>, is provided for upward density migration for the StrataFlash PROM.

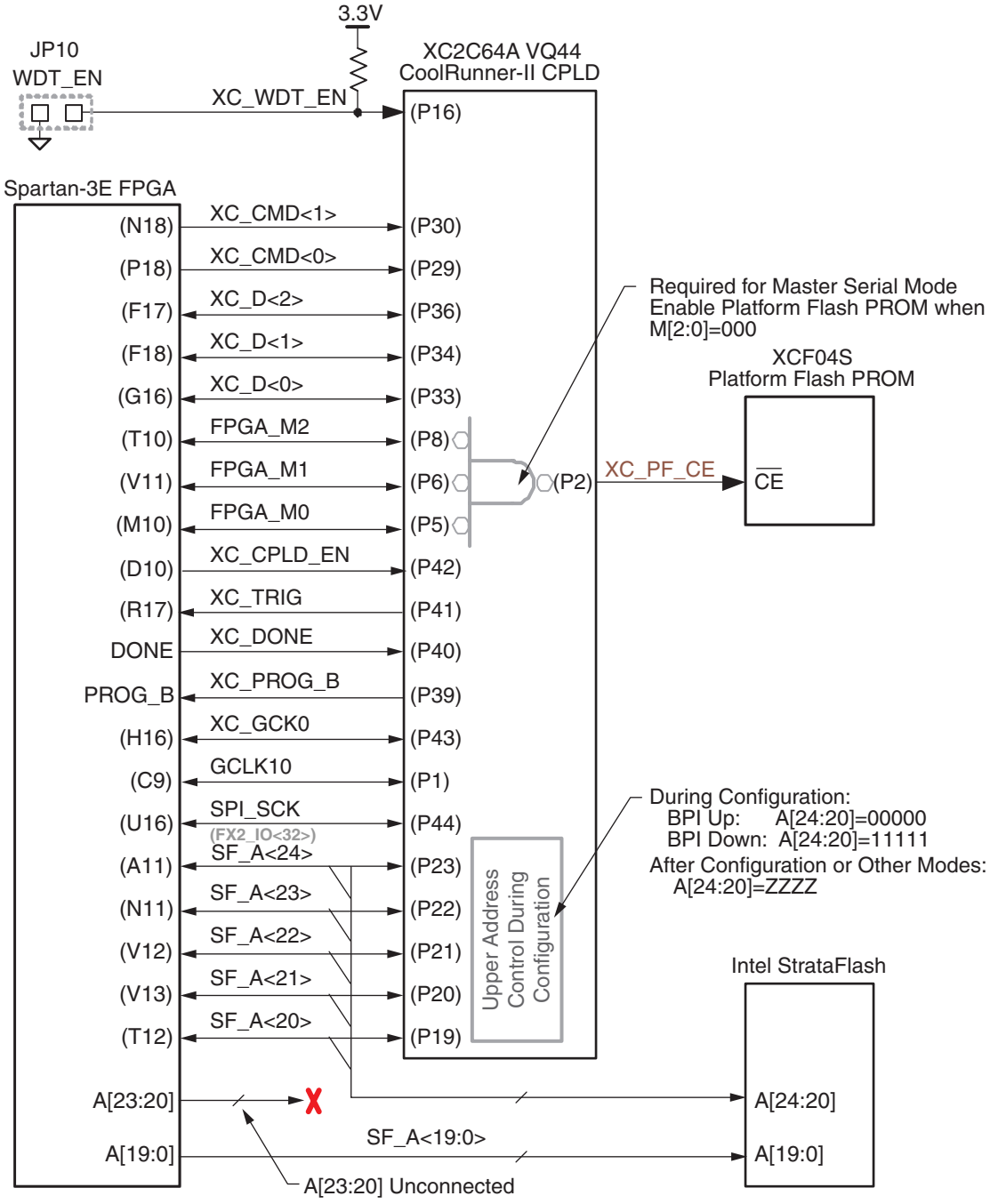


*Figure 16-1:* **XC2C64A CoolRunner-II CPLD Controls Master Serial and BPI Configuration Modes**

# UCF Location Constraints

There are two sets of constraints listed below—one for the Spartan-3E FPGA and one for the XC2C64A CoolRunner-II CPLD.

## FPGA Connections to CPLD

Figure 16-2 provides the UCF constraints for the FPGA connections to the CPLD , including the I/O pin assignment and the I/O standard used.

```
NET "XC_CMD<1>"  LOC = "N18" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_CMD<0>"  LOC = "P18" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_D<2>"    LOC = "F17" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_D<1>"    LOC = "F18" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_D<0>"    LOC = "G16" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "FPGA_M2"    LOC = "T10" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "FPGA_M1"    LOC = "V11" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "FPGA_M0"    LOC = "M10" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_CPLD_EN" LOC = "B10" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "XC_TRIG"    LOC = "R17" | IOSTANDARD = LVCMOS33 ;
NET "XC_GCK0"    LOC = "H16" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "GCLK10"     LOC = "C9"  | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "SPI_SCK"    LOC = "U16" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
# SF_A<24> is the same as FX2_IO<32>
NET "SF_A<24>"   LOC = "A11" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "SF_A<23>"   LOC = "N11" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "SF_A<22>"   LOC = "V12" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "SF_A<21>"   LOC = "V13" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
NET "SF_A<20>"   LOC = "T12" | IOSTANDARD = LVCMOS33  | DRIVE = 4  | SLEW = SLOW ;
```

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*Figure 16-2:* **UCF Location Constraints for FPGA Connections to CPLD**

## CPLD

Figure 16-3 provides the UCF constraints for the CPLD , including the I/O pin assignment and the I/O standard used

.

```
NET "XC_WDT_EN"  LOC = "P16" | IOSTANDARD = LVCMOS33 ;
NET "XC_CMD<1>"  LOC = "P30" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_CMD<0>"  LOC = "P29" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_D<2>"    LOC = "P36" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_D<1>"    LOC = "P34" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_D<0>"    LOC = "P33" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "FPGA_M2"    LOC = "P8"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "FPGA_M1"    LOC = "P6"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "FPGA_M0"    LOC = "P5"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_CPLD_EN" LOC = "P42" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_TRIG"    LOC = "P41" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_DONE"    LOC = "P40" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_PROG_B"  LOC = "P39" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "XC_GCK0"    LOC = "P43" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "GCLK10"     LOC = "P1"  | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "SPI_SCK"    LOC = "P44" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
# SF_A<24> is the same as FX2_IO<32>
NET "SF_A<24>"   LOC = "P23" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "SF_A<23>"   LOC = "P22" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "SF_A<22>"   LOC = "P21" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "SF_A<21>"   LOC = "P20" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
NET "SF_A<20>"   LOC = "P19" | IOSTANDARD = LVCMOS33 | SLEW = SLOW ;
```

UG257_16_03_060806

*Figure 16-3:* **UCF Location Constraints for the XC2C64A CPLD**

## Related Resources

- CoolRunner-II CPLD Family Data Sheet
  http://direct.xilinx.com/bvdocs/publications/ds090.pdf
- XC2C64A CoolRunner-II CPLD Data Sheet
  http://direct.xilinx.com/bvdocs/publications/ds311.pdf
- Default XC2C64A CPLD Design for Spartan-3E Starter Kit Board
  http://www.xilinx.com/s3estarter

Chapter 17

# DS2432 1-Wire SHA-1 EEPROM

The MicroBlaze Development Kit board includes a Maxim DS2432 serial EEPROM with an integrated SHA-1 engine. As shown in Figure 17-1, the DS2432 EEPROM uses the Maxim 1-Wire interface, which uses a single wire for power and serial communication.

The DS2432 EEPROM offers one of many possible means to copy and protect the FPGA configuration bitstream, thereby making cloning difficult. Xilinx application note XAPP780, listed under "Related Resources" provides one possible implementation method.

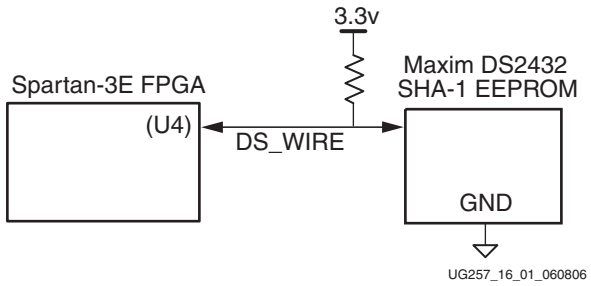


*Figure 17-1:* **SHA-1 EEPROM**

## UCF Location Constraints

Figure 17-2 provides the UCF constraints for the FPGA connections to the DS2432 SHA-1 EEPROM, including the I/O pin assignment and the I/O standard used.

```
NET "DS_WIRE"  LOC = "U4" | IOSTANDARD = LVCMOS33 | SLEW = SLOW  | DRIVE = 8 ;
```

UG257_17_02_061606

*Figure 17-2:* **UCF Location Constraints for DS2432 SHA-1 EEPROM**

## Related Resources

- Maxim DS2432 1-Wire EEPROM with SHA-1 Engine
  http://www.maxim-ic.com/quick_view2.cfm/qv_pk/2914
- XAPP780: *FPGA IFF Copy Protection Using Dallas Semiconductor/Maxim DS2432 Secure EEPROMs*
  http://www.xilinx.com/bvdocs/appnotes/xapp780.pdf

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# Appendix A

# Schematics

This appendix provides the following circuit board schematics:

- "FX2 Expansion Header, 6-pin Headers, and Connectorless Probe Header"
- "RS-232 Ports, VGA Port, and PS/2 Port"
- "Ethernet PHY, Magnetics, and RJ-11 Connector"
- "Voltage Regulators"
- "FPGA Configurations Settings, Platform Flash PROM, SPI Serial Flash, JTAG Connections"
- "FPGA I/O Banks 0 and 1, Oscillators"
- "FPGA I/O Banks 2 and 3"
- "Power Supply Decoupling"
- "XC2C64A CoolRunner-II CPLD"
- "Linear Technology ADC and DAC "
- "Intel StrataFlash Parallel NOR Flash Memory and Micron DDR SDRAM "
- "Buttons, Switches, Rotary Encoder, and Character LCD "
- "DDR SDRAM Series Termination and FX2 Connector Differential Termination"

# FX2 Expansion Header, 6-pin Headers, and Connectorless Probe Header

Headers J1, J2, and J4 are six-pin connectors compatible with the Digilent Accessory board format.

Headers J3A and J3B are the connections to the FX2 expansion connector located along the right edge of the board.

Header J5 provides the four analog outputs from the Digital-to-Analog Converter (DAC).

Header J6 is the landing pad for an Agilent or Tektronix connectorless probe.

Header J7 provides the two analog inputs to the programmable pre-amplifier (AMP) and two-channel Analog-to-Digital Converter (ADC).

The diagram in the lower left corner shows the JTAG chain.

See Chapter 15, "Expansion Connectors," for additional information.

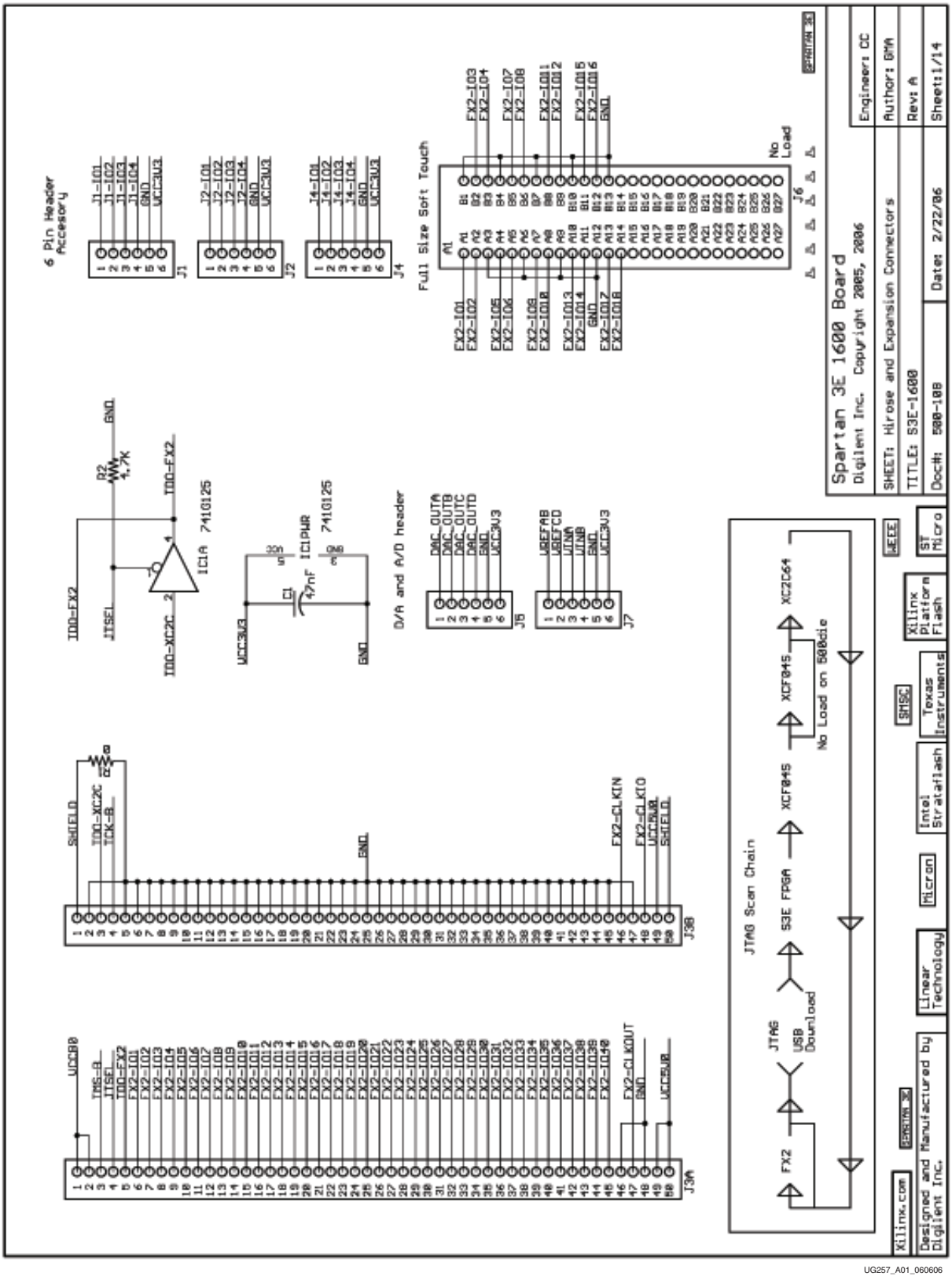


*Figure 18-1:* **Schematic Sheet 1**

## RS-232 Ports, VGA Port, and PS/2 Port

IC2 is the Maxim LVTTL to RS-232 level converter. One of the serial channels connects to a female DB9 DCE connector (J9) and the other connects to a male DB9 DTE connector (J10). See Chapter 7, "RS-232 Serial Ports," for additional information.

Connector J14 is a PS/2-style mouse/keyboard connector, powered from 5 volts. See Chapter 8, "PS/2 Mouse/Keyboard Port," for additional information.

Connector J15 is a VGA connector, suitable for driving most VGA-compatible monitors and flat-screen displays. See Chapter 6, "VGA Display Port," for additional information.

Header J12 provides programming support for the SPI serial Flash. Jumper J11 controls how the SPI serial Flash is enabled in the application. See Chapter 12, "SPI Serial Flash," for additional information.

The SMA connector allows an external clock source to drive one of the FPGA's global clock inputs. Alternatively, the FPGA can provide a high-performance clock to another board via the SMA connector. See Chapter 3, "Clock Sources," for additional information.

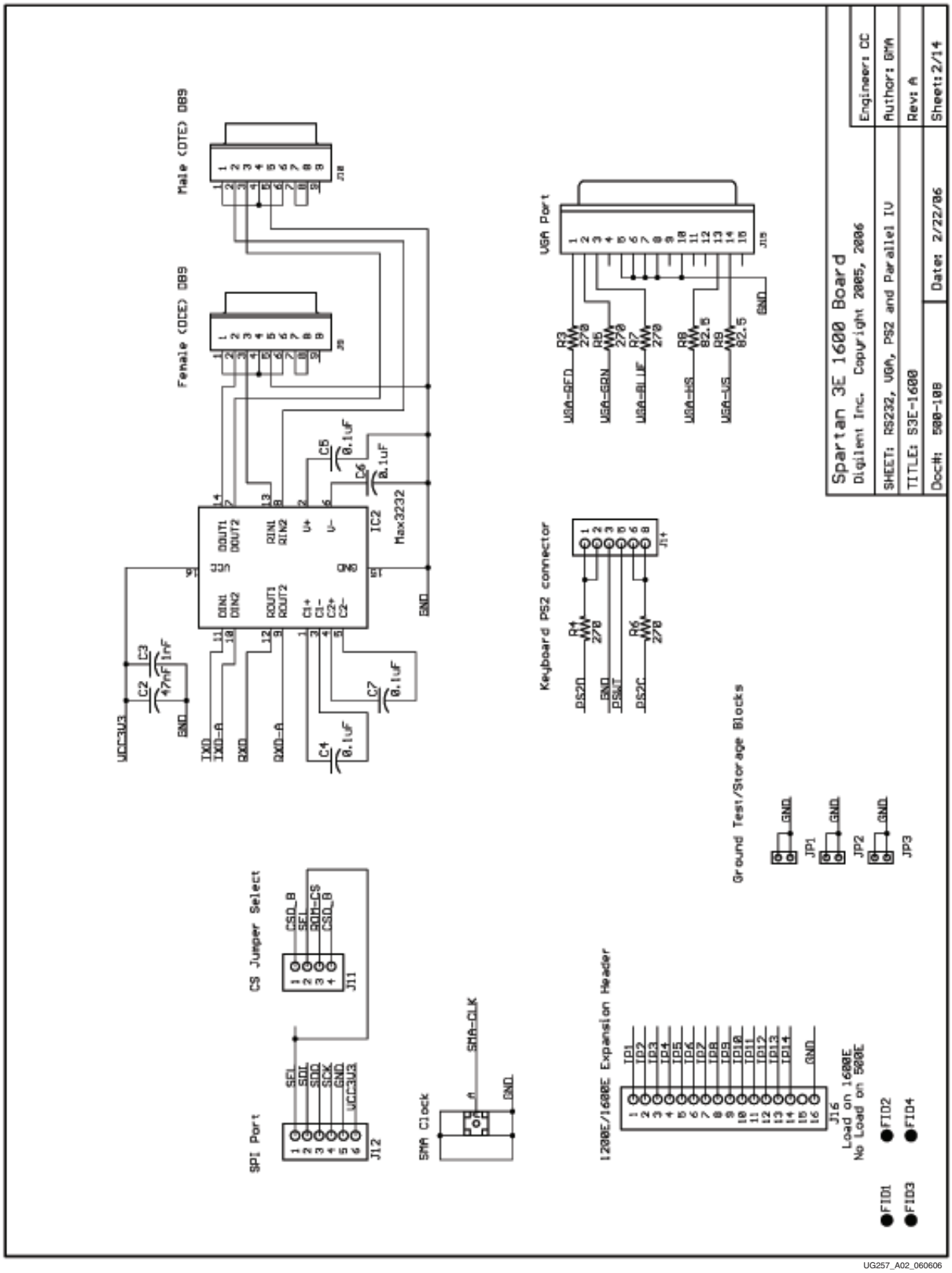


*Figure 18-2:* **Schematic Sheet 2**

# Ethernet PHY, Magnetics, and RJ-11 Connector

IC6 is an SMSC 10/100 Ethernet PHY, with its associated 25 MHz oscillator. The PHY requires an Ethernet MAC implemented within the FPGA.

J19 is the RJ-11 Ethernet connector associated with the 10/100 Ethernet PHY.

See Chapter 14, "10/100 Ethernet Physical Layer Interface," for additional information.

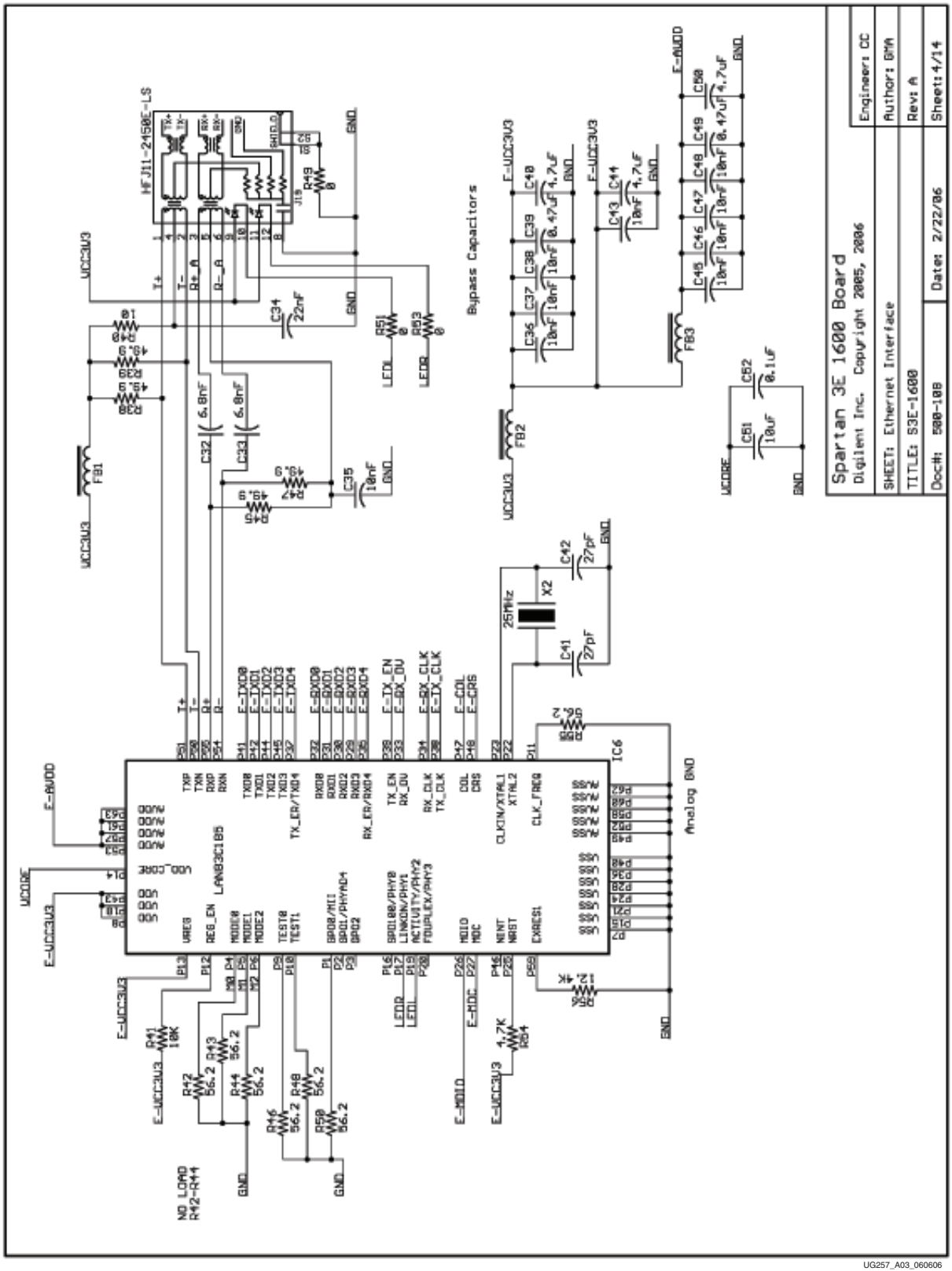


*Figure 18-3:* **Schematic Sheet 4**

## Voltage Regulators

IC7 is a Texas Instruments TPS75003 triple-output regulator. The regulator provides 1.2V to the FPGA's VCCINT supply input, 2.5V to the FPGA's VCCAUX supply input, and 3.3V to other components on the board and to the FPGA's VCCO supply inputs on I/O Banks 0, 1, and 2.

Jumpers JP6 and JP7 provide a means to measure current across the FPGA's VCCAUX and VCCINT supplies respectively.

IC8 is a Linear Technology LT3412 regulator, providing 2.5V to the on-board DDR SDRAM. Resistors R65 and R67 create a voltage divider to create the termination voltage required for the DDR SDRAM interface.

IC9 is a 1.8V supply to the Embedded USB download/debug circuit and to the CPLD's VCCINT supply input.

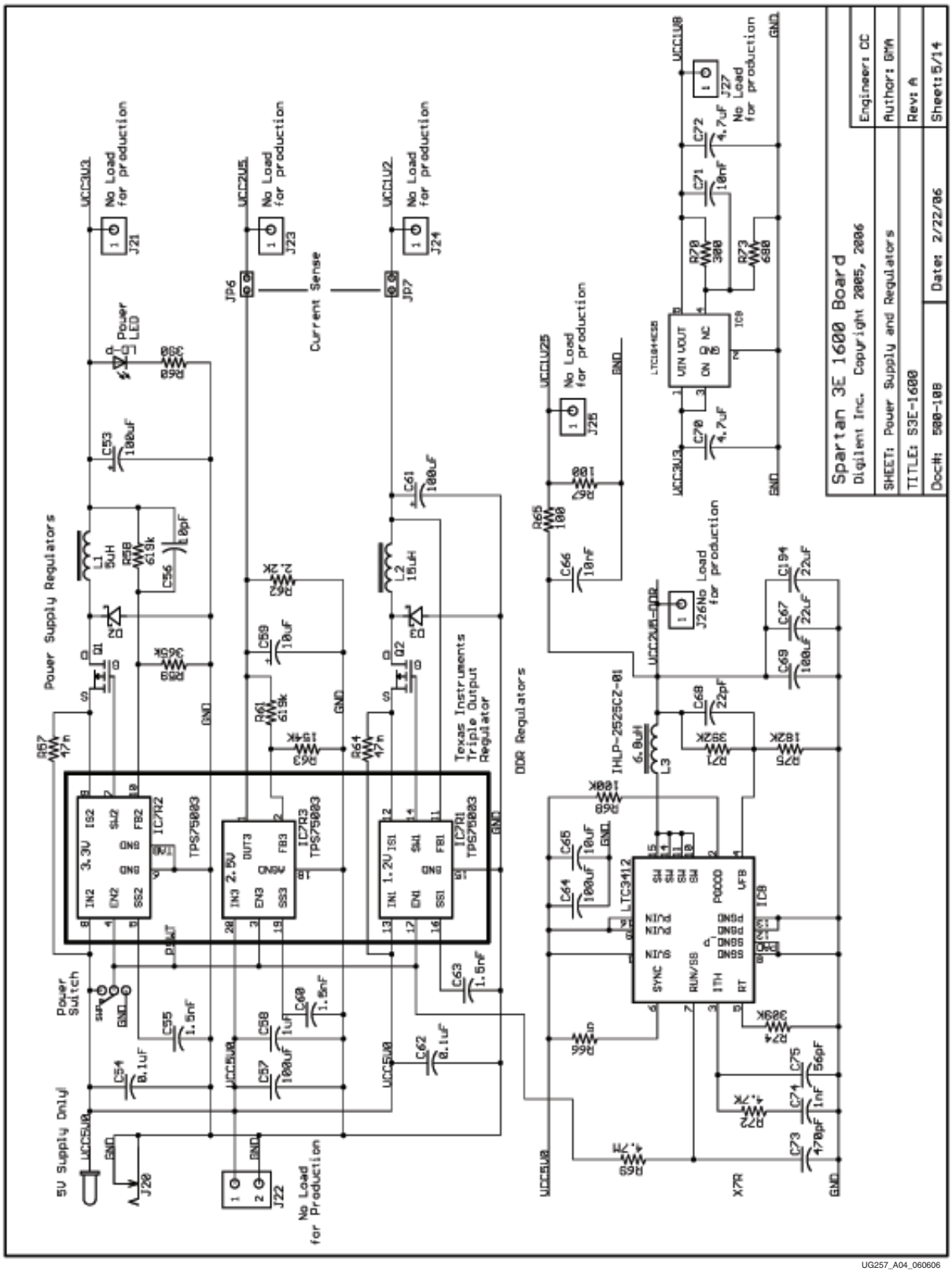


*Figure 18-4:* **Schematic Sheet 5**

# FPGA Configurations Settings, Platform Flash PROM, SPI Serial Flash, JTAG Connections

IC10MISC represents the various FPGA configuration connections.

IC11 is a 4 Mbit XCF04S Platform Flash PROM. Landing pads for a second XCF04S PROM is shown as IC13, although the second PROM is not mounted on the XC3S500E version of the board. Resistor R100 jumpers over the JTAG chain, bypassing the second XCF04S PROM.

Jumper header J30 selects the FPGA's configuration mode. See Table 4-1, page 25 for additional information.

Header J28 is an alternate JTAG header.

IC12 is a Maxim/Dallas Semiconductor DS2432 SHA-1 EEPROM. See Chapter 17, "DS2432 1-Wire SHA-1 EEPROM," for more information.

IC14 and IC15 are alternate landing pads for the STMicro SPI serial Flash. IC14 accepts the 16-pin SOIC package option, while IC15 accepts either the 8-pin SOIC or MLP package option. See Figure 12-19, page 103 for additional informaton.

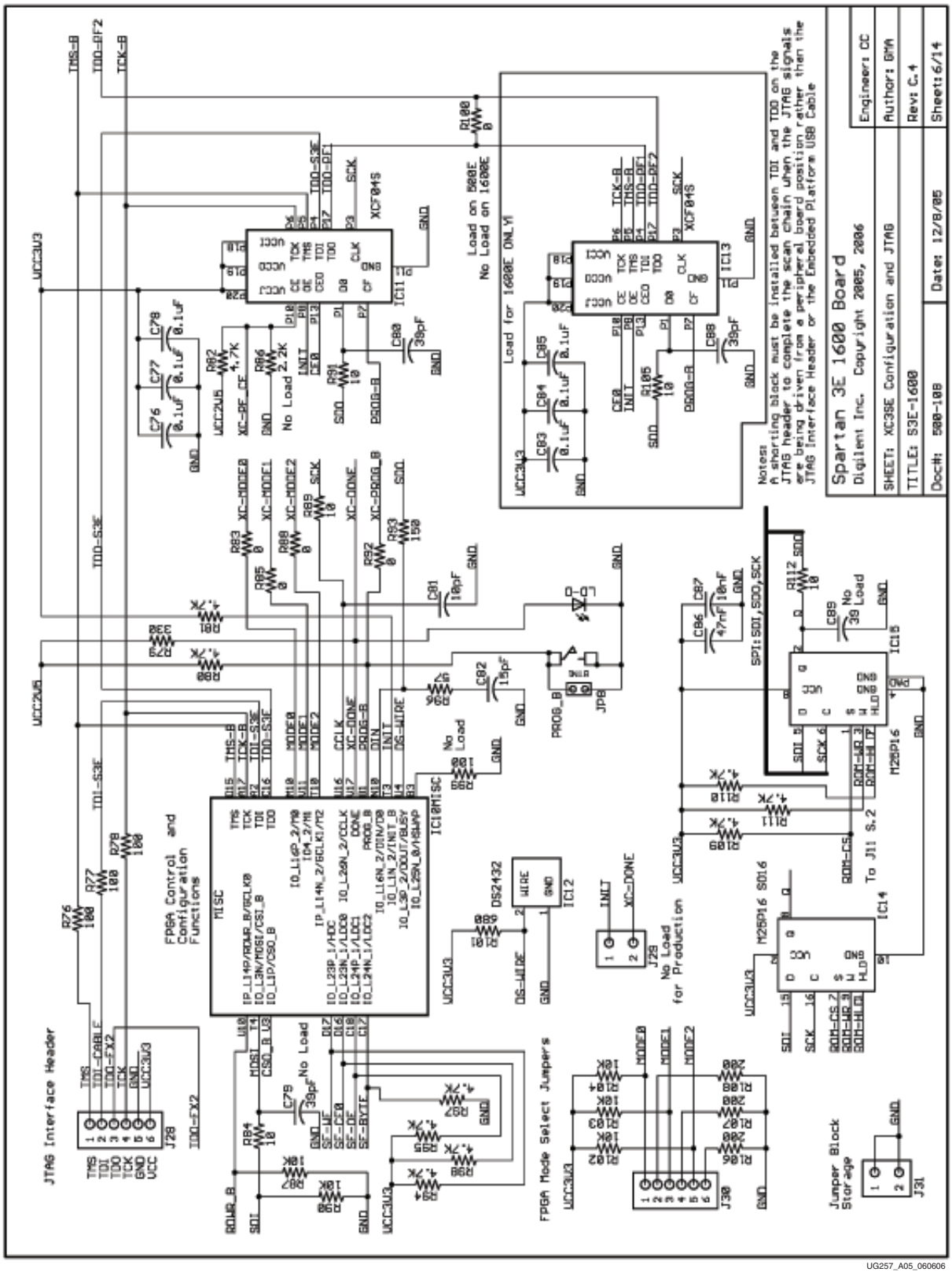


*Figure 18-5:* **Schematic Sheet 6**

# FPGA I/O Banks 0 and 1, Oscillators

IC10B0 represents the connections to I/O Bank 0 on the FPGA. The VCCO input to Bank 0 is 3.3V by default, but can be set to 2.5V using jumper JP9.

IC10B1 represents the connections to I/O Bank 1 on the FPGA.

IC17 is the 50 MHz clock oscillator. Chapter 3, "Clock Sources," for additional information.

IC16 is an 8-pin DIP socket to insert an alternate clock oscillator with a different frequency.

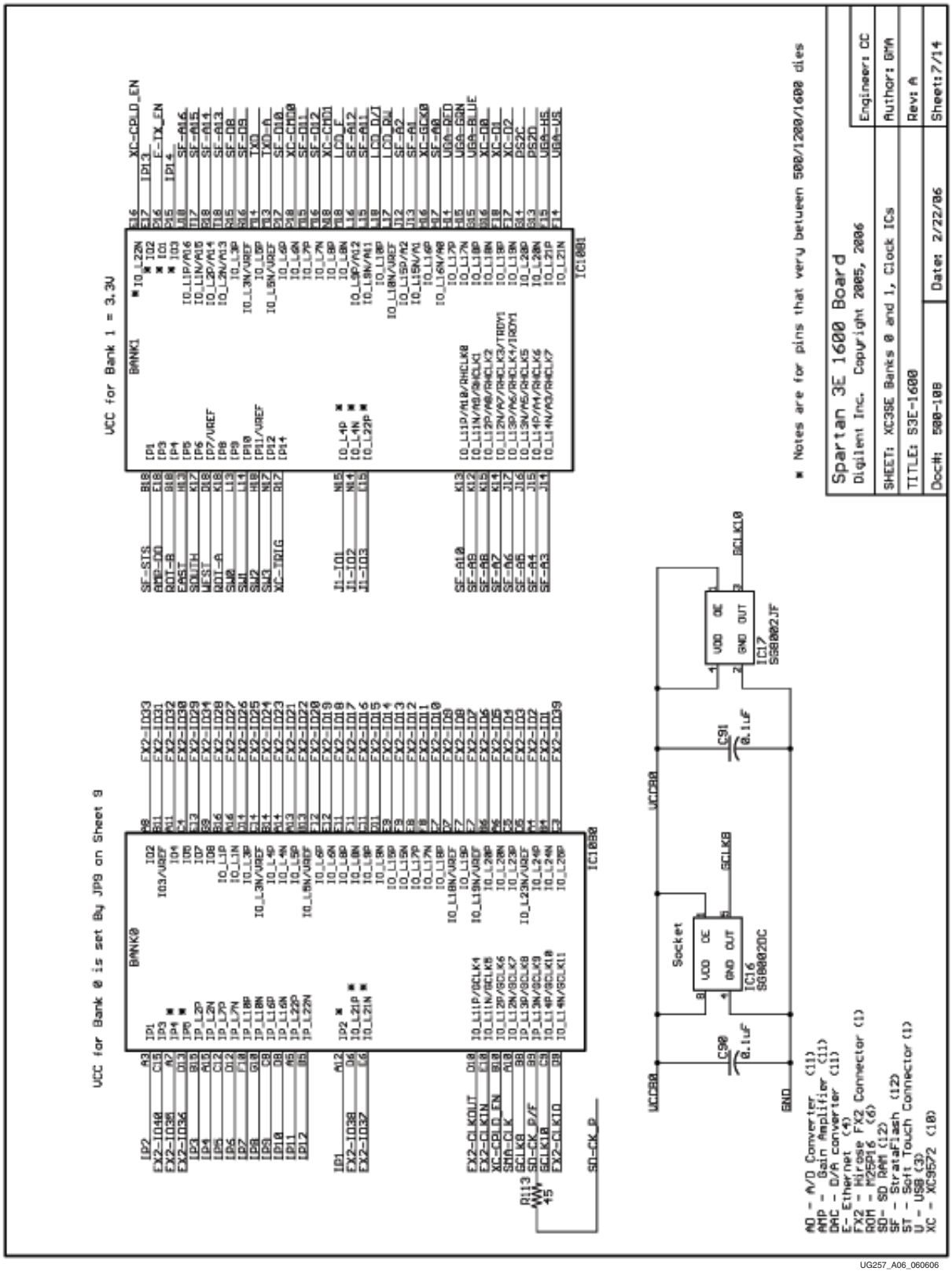


*Figure 18-6:* **Schematic Sheet 7**

## FPGA I/O Banks 2 and 3

IC10B2 represents the connections to I/O Bank 2 on the FPGA. Some of the I/O Bank 2 connections are used for FPGA configuration and are listed as IC10MISC.

IC10B3 represents the connections to I/O Bank 3 on the FPGA. Bank 3 is dedicated to the DDR SDRAM interface and is consequently powered by 2.5V. See Chapter 13, "DDR SDRAM," for additional information.

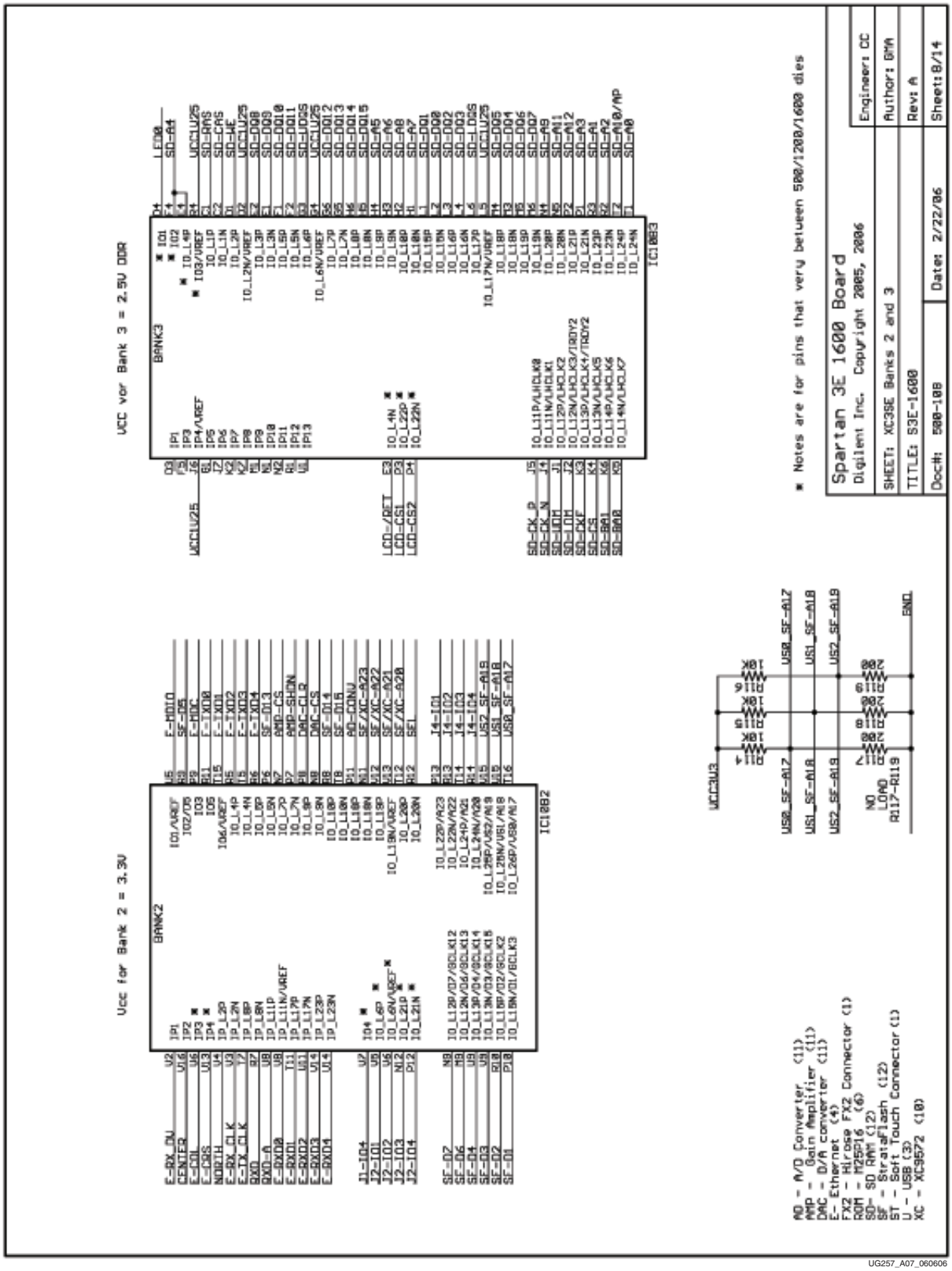


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*Figure 18-7:* **Schematic Sheet 8**

## Power Supply Decoupling

IC10PWR represents the various voltage supply inputs to the FPGA and shows the power decoupling network.

Jumper JP9 defines the voltage applied to VCCO on I/O Bank 0. The default setting is 3.3V. See "Voltage Control," page 20 and "Voltage Supplies to the Connector," page 116 for additional details.

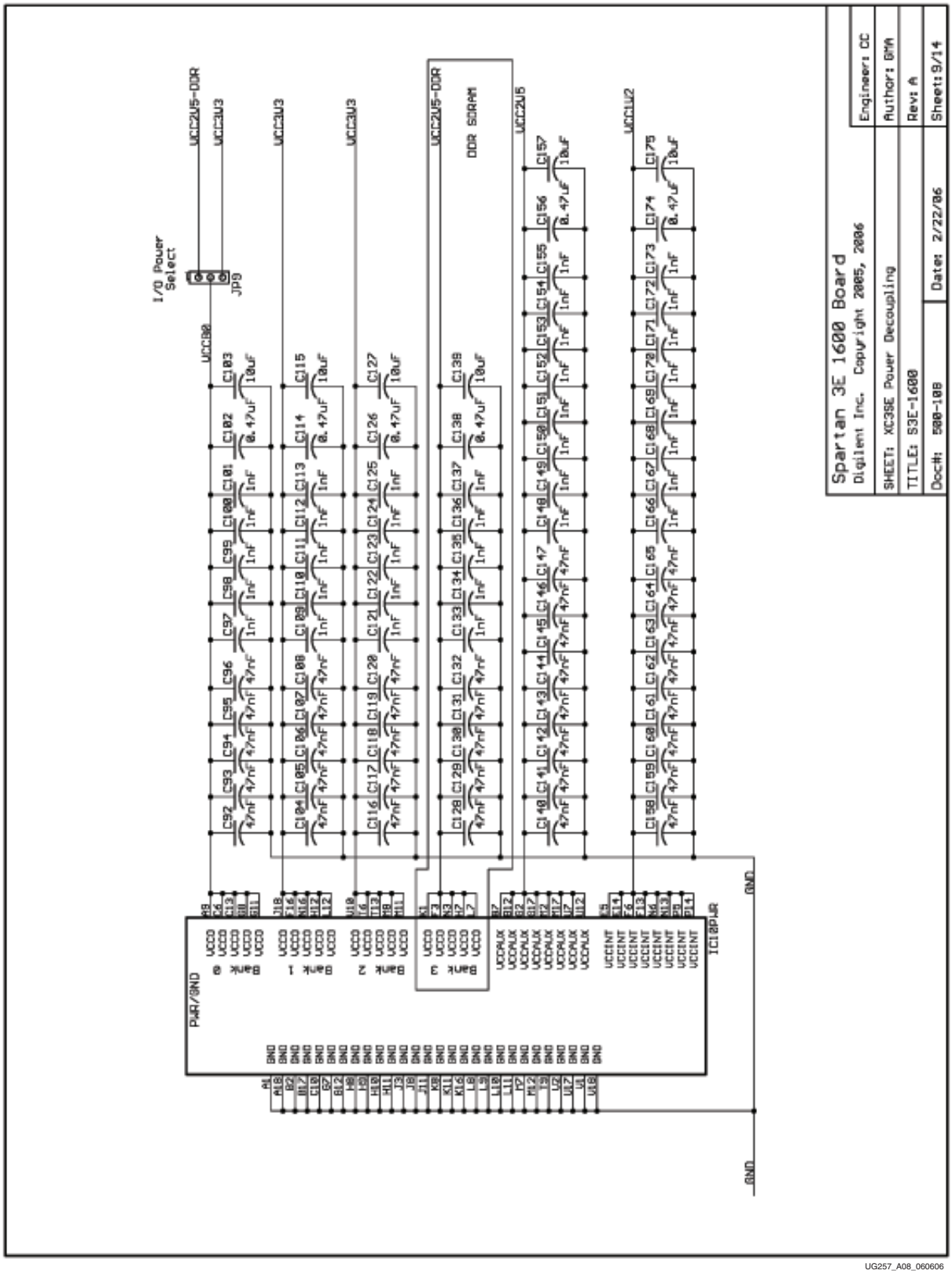


*Figure 18-8:* **Schematic Sheet 9**

# XC2C64A CoolRunner-II CPLD

IC18 is a Xilinx XC2C64A CoolRunner-II CPLD. The CPLD primarily provides additional flexibility when configuring the FPGA from parallel NOR Flash and during MultiBoot configurations.

When the CPLD is loaded with the appropriate design, JP10 enables a watchdog timer in the CPLD used during fail-safe MultiBoot configurations.

See Chapter 16, "XC2C64A CoolRunner-II CPLD," for more information.

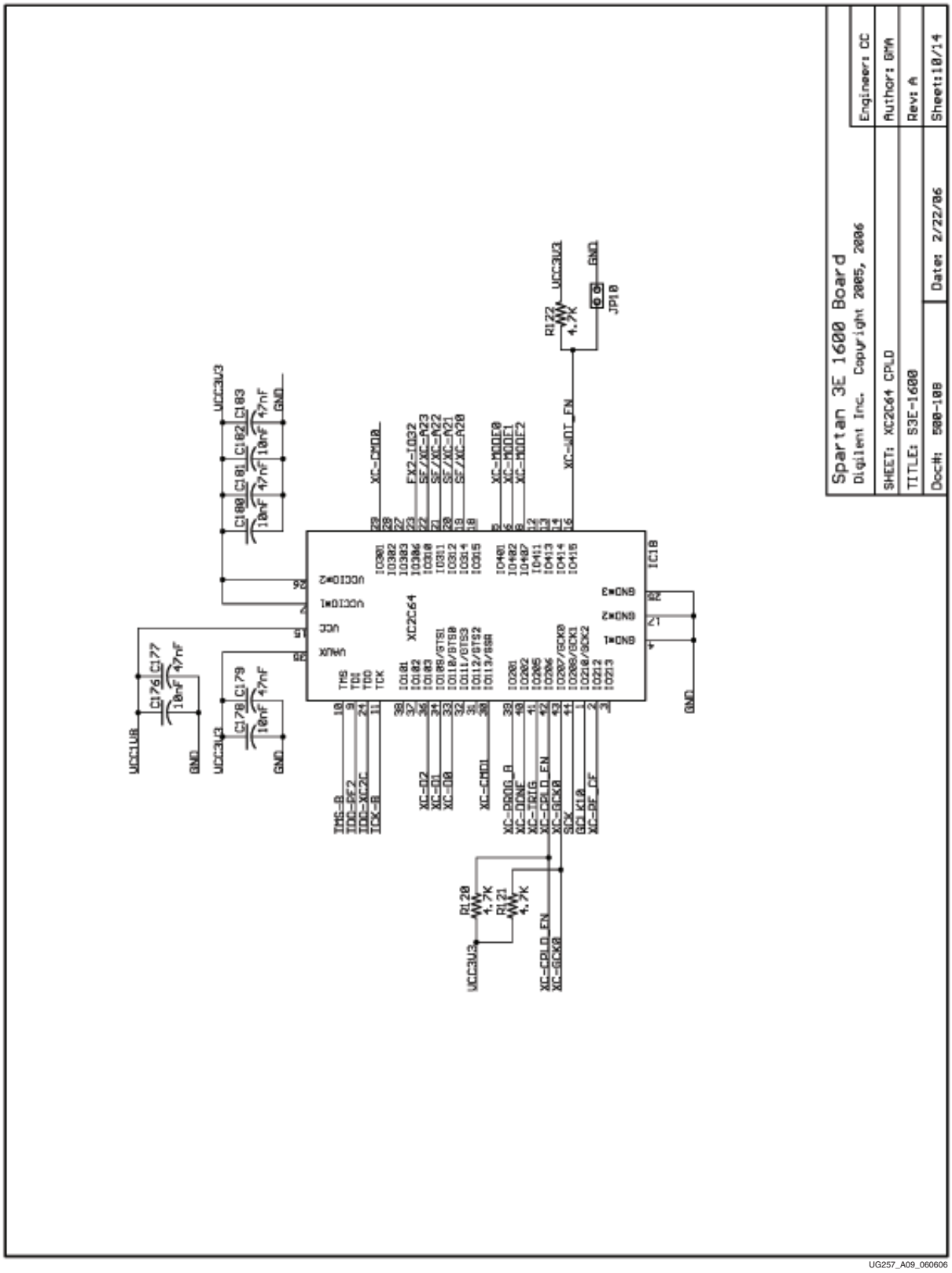


*Figure 18-9:* **Schematic Sheet 10**

# Linear Technology ADC and DAC

IC19 is a Linear Technology LTC1407A-1 two-channel ADC. IC20 is a Linear Technology LTC6912 programmable pre-amplifier (AMP) to condition the analog inputs to the ADC. See Chapter 10, "Analog Capture Circuit," for additional information.

IC21 is a Linear Technology LTC2624 four-channel DAC. See Chapter 9, "Digital to Analog Converter (DAC)," for additional information.

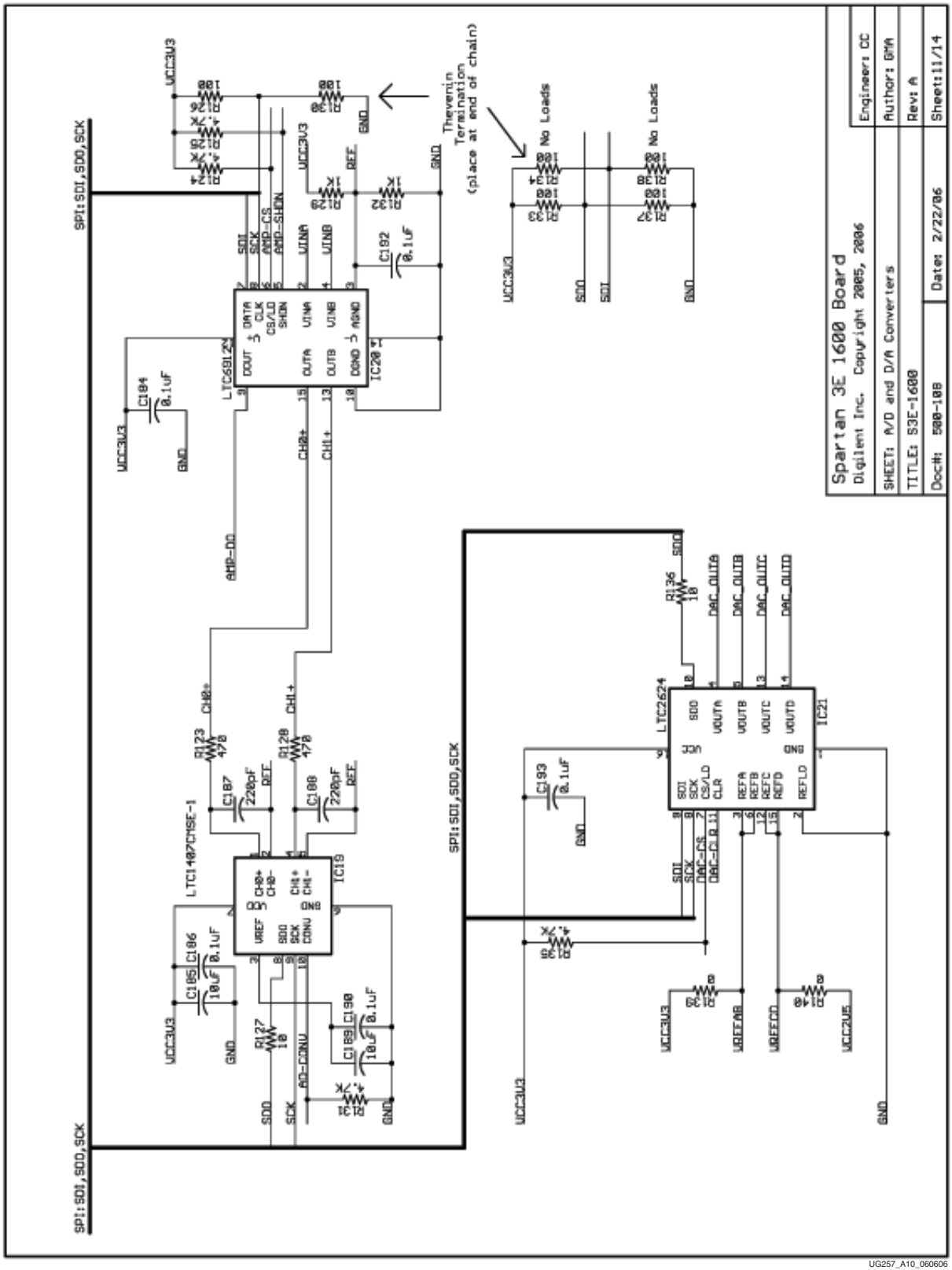


*Figure 18-10:* **Schematic Sheet 11**

# Intel StrataFlash Parallel NOR Flash Memory and Micron DDR SDRAM

IC22 is a 128 Mbit (16 Mbyte) Intel StrataFlash parallel NOR Flash PROM. See Chapter 11, "Intel StrataFlash Parallel NOR Flash PROM," for additional information.

IC23 is a 512 Mbit (64 Mbyte) Micron DDR SDRAM. See Chapter 13, "DDR SDRAM," for additional information.

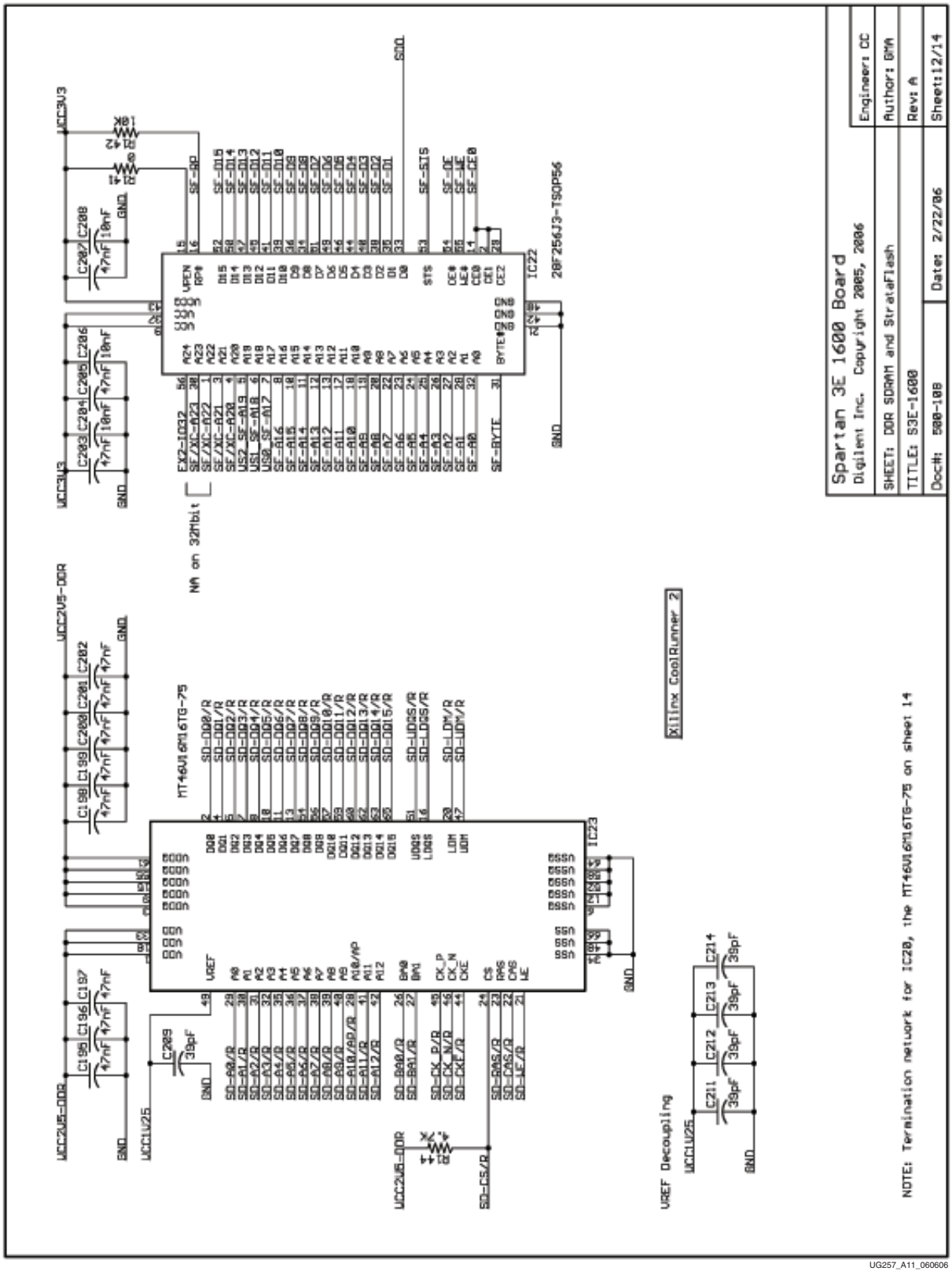


*Figure 18-11:* **Schematic Sheet 12**

## Buttons, Switches, Rotary Encoder, and Character LCD

SW0, SW1, SW2, and SW3 are slide switches.

Push-button switches W, E, S, and N are located around the ROT1 push-button switch/rotary encoder.

LD0 through LD7 are discrete LEDs.

See Chapter 2, "Switches, Buttons, and Knob," for additional information.

DISP1 is a 2x16 character LCD screen. See Chapter 5, "Character LCD Screen," for additional information.

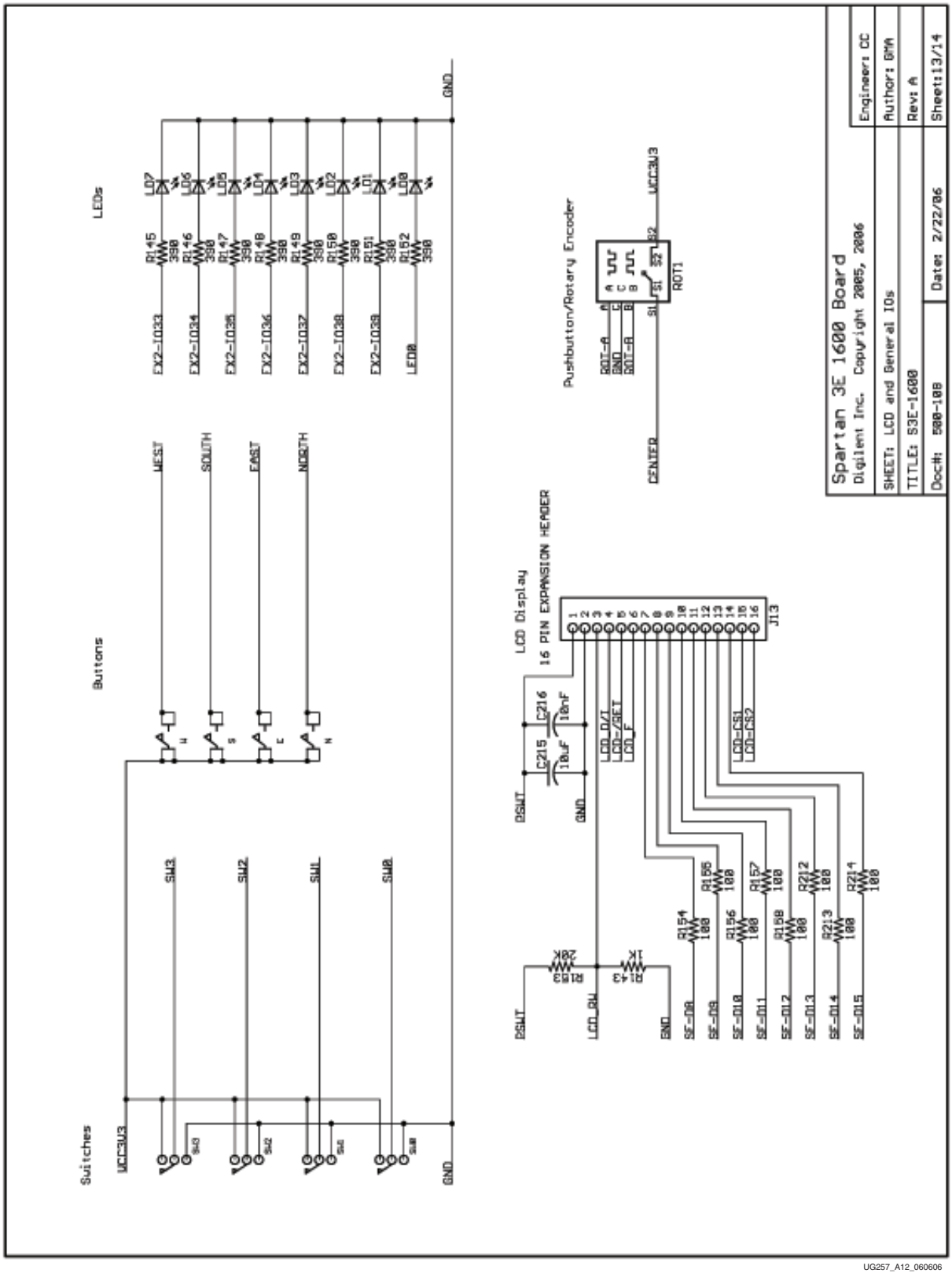


*Figure 18-12:* **Schematic Sheet 13**

# DDR SDRAM Series Termination and FX2 Connector Differential Termination

Resistors R160 through R201 represent the series termination resistors for the DDR SDRAM. See Chapter 13, "DDR SDRAM," for additional information.

Resistors R202 through R210 are not loaded on the board. These landing pads provide optional connections for 100Ω differential termination resistors. See "Using Differential Inputs," page 120 for additional information.

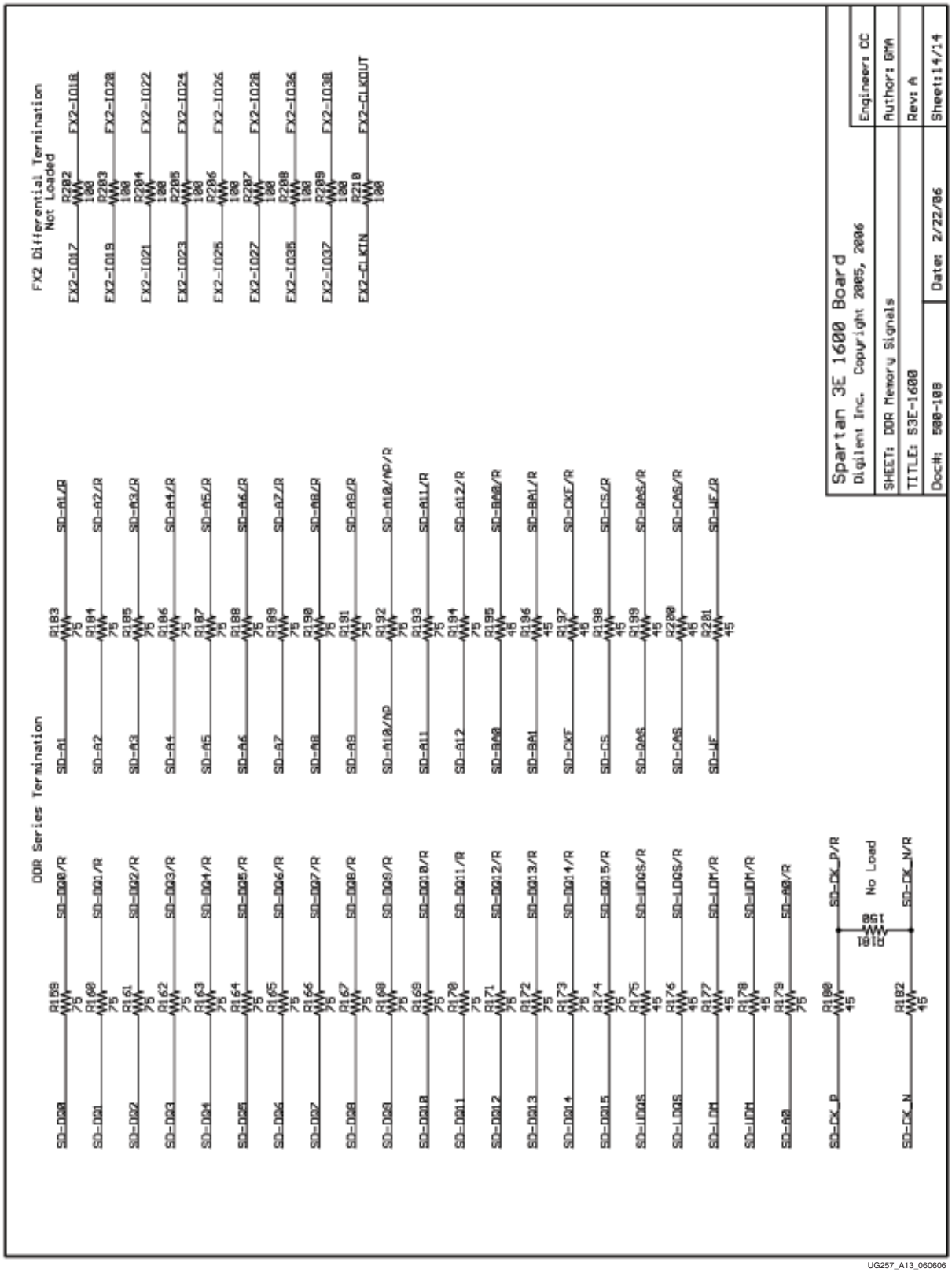


*Figure 18-13:* **Schematic Sheet 14**

Appendix B

# Example User Constraints File (UCF)

```
##################################################################
### SPARTAN-3E MicroBlaze Development KIT BOARD CONSTRAINTS FILE
##################################################################
# ==== FPGA Configuration Mode, INIT_B Pins (FPGA) ====
NET "FPGA_M0" LOC = "M10" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "FPGA_M1" LOC = "V11" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "FPGA_M2" LOC = "T10" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "FPGA_INIT_B" LOC = "T3" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 4 ;
NET "FPGA_RDWR_B" LOC = "U10" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 4 ;
NET "FPGA_HSWAP" LOC = "B3" | IOSTANDARD = LVCMOS33 ;
#
# ==== Clock inputs (CLK) ====
NET "CLK_50MHZ" LOC = "C9" | IOSTANDARD = LVCMOS33 ; # GCLK10
# Define clock period for 50 MHz oscillator (40%/60% duty-cycle)
NET "CLK_50MHZ" PERIOD = 20.0ns HIGH 40%;
#
NET "CLK_AUX_66MHZ" LOC = "B8" | IOSTANDARD = LVCMOS33 ; # GCLK8 Populated with 66MHz Osc
# Define clock period for 66 MHz oscillator (50%/50% duty-cycle)
NET "CLK_AUX_66MHZ" PERIOD = 14.9ns HIGH 50%;
#
NET "CLK_SMA" LOC = "A10" | IOSTANDARD = LVCMOS33 ;
#
# ==== RS-232 Serial Ports (RS232) ====
NET "RS232_DCE_RXD" LOC = "R7" | IOSTANDARD = LVTTL ;
NET "RS232_DCE_TXD" LOC = "M14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = SLOW ;
NET "RS232_DTE_RXD" LOC = "U8" | IOSTANDARD = LVTTL ;
NET "RS232_DTE_TXD" LOC = "M13" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = SLOW ;
#
# ==== Rotary Pushbutton Switch (ROT) ====
NET "ROT_A" LOC = "K18" | IOSTANDARD = LVTTL | PULLUP ;
NET "ROT_B" LOC = "G18" | IOSTANDARD = LVTTL | PULLUP ;
NET "ROT_CENTER" LOC = "V16" | IOSTANDARD = LVTTL | PULLDOWN ;
#
# ==== Pushbuttons (BTN) ====
NET "BTN_EAST" LOC = "H13" | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_NORTH" LOC = "V4" | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_SOUTH" LOC = "K17" | IOSTANDARD = LVTTL | PULLDOWN ;
NET "BTN_WEST" LOC = "D18" | IOSTANDARD = LVTTL | PULLDOWN ;
#
# ==== Slide Switches (SW) ====
NET "SW<0>" LOC = "L13" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<1>" LOC = "L14" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<2>" LOC = "H18" | IOSTANDARD = LVTTL | PULLUP ;
NET "SW<3>" LOC = "N17" | IOSTANDARD = LVTTL | PULLUP ;
#
# ==== Discrete LEDs (LED) ====
```

```
# These are shared connections with the FX connector
NET "LED<0>" LOC = "D4" | IOSTANDARD = SSTL2_I ;
NET "LED<1>" LOC = "C3" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO39
NET "LED<2>" LOC = "D6" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO38
NET "LED<3>" LOC = "E6" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO37
NET "LED<4>" LOC = "D13" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO36
NET "LED<5>" LOC = "A7" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO35
NET "LED<6>" LOC = "G9" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO34
NET "LED<7>" LOC = "A8" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # FX2-IO33
#
# ==== Character LCD (LCD) ====
NET "LCD_E" LOC = "M18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_DI" LOC = "L18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_RW" LOC = "L17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "LCD_RET" LOC = "E3" | IOSTANDARD = SSTL2_I ;
NET "LCD_CS1" LOC = "P3" | IOSTANDARD = SSTL2_I ;
NET "LCD_CS2" LOC = "P4" | IOSTANDARD = SSTL2_I ;
# LCD data connections are shared with StrataFlash connections SF_D<15:8>
#NET "SF_D<8>" LOC = "R15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<9>" LOC = "R16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<10>" LOC = "P17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<11>" LOC = "M15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<12>" LOC = "M16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<13>" LOC = "P6" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<14>" LOC = "R8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#NET "SF_D<15>" LOC = "T8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
#
# ==== PS/2 Mouse/Keyboard Port (PS2) ====
NET "PS2_CLK" LOC = "G14" | IOSTANDARD = LVCMOS33 | DRIVE = 8 | SLEW = SLOW ;
NET "PS2_DATA" LOC = "G13" | IOSTANDARD = LVCMOS33 | DRIVE = 8 | SLEW = SLOW ;
#
# ==== Analog-to-Digital Converter (ADC) ====
# some connections shared with SPI Flash, DAC, ADC, and AMP
NET "AD_CONV" LOC = "P11" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
# ==== Programmable Gain Amplifier (AMP) ====
# some connections shared with SPI Flash, DAC, ADC, and AMP
NET "AMP_CS" LOC = "N7" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "AMP_DOUT" LOC = "E18" | IOSTANDARD = LVCMOS33 ;
NET "AMP_SHDN" LOC = "P7" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
#
# ==== Digital-to-Analog Converter (DAC) ====
# some connections shared with SPI Flash, DAC, ADC, and AMP
NET "DAC_CLR" LOC = "P8" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "DAC_CS" LOC = "N8" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
#
# ==== 1-Wire Secure EEPROM (DS)
NET "DS_WIRE" LOC = "U4" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 8 ; # SD0
#
# ==== Ethernet PHY (E) ====
NET "E_COL" LOC = "U6" | IOSTANDARD = LVCMOS33 ;
NET "E_CRS" LOC = "U13" | IOSTANDARD = LVCMOS33 ;
NET "E_MDC" LOC = "P9" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_MDIO" LOC = "U5" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_RX_CLK" LOC = "V3" | IOSTANDARD = LVCMOS33 ;
NET "E_RX_DV" LOC = "V2" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<0>" LOC = "V8" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<1>" LOC = "T11" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<2>" LOC = "U11" | IOSTANDARD = LVCMOS33 ;
NET "E_RXD<3>" LOC = "V14" | IOSTANDARD = LVCMOS33 ;
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NET "E_RXD<4>" LOC = "U14" | IOSTANDARD = LVCMOS33 ;
NET "E_TX_CLK" LOC = "T7" | IOSTANDARD = LVCMOS33 ;
NET "E_TX_EN" LOC = "P15" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_TXD<0>" LOC = "R11" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_TXD<1>" LOC = "T15" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_TXD<2>" LOC = "R5" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_TXD<3>" LOC = "T5" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
NET "E_TXD<4>" LOC = "R6" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 8 ;
#
# ==== DDR SDRAM (SD) ==== (I/O Bank 3, VCCO=2.5V)
NET "SD_A<0>" LOC = "T1" | IOSTANDARD = SSTL2_I ;
NET "SD_A<1>" LOC = "R3" | IOSTANDARD = SSTL2_I ;
NET "SD_A<2>" LOC = "R2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<3>" LOC = "P1" | IOSTANDARD = SSTL2_I ;
NET "SD_A<4>" LOC = "E4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<5>" LOC = "H4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<6>" LOC = "H3" | IOSTANDARD = SSTL2_I ;
NET "SD_A<7>" LOC = "H1" | IOSTANDARD = SSTL2_I ;
NET "SD_A<8>" LOC = "H2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<9>" LOC = "N4" | IOSTANDARD = SSTL2_I ;
NET "SD_A<10>" LOC = "T2" | IOSTANDARD = SSTL2_I ;
NET "SD_A<11>" LOC = "N5" | IOSTANDARD = SSTL2_I ;
NET "SD_A<12>" LOC = "P2" | IOSTANDARD = SSTL2_I ;
NET "SD_BA<0>" LOC = "K5" | IOSTANDARD = SSTL2_I ;
NET "SD_BA<1>" LOC = "K6" | IOSTANDARD = SSTL2_I ;
NET "SD_CAS" LOC = "C2" | IOSTANDARD = SSTL2_I ;
NET "SD_CK_N" LOC = "J4" | IOSTANDARD = SSTL2_I ;
NET "SD_CK_P" LOC = "J5" | IOSTANDARD = SSTL2_I ;
NET "SD_CKE" LOC = "K3" | IOSTANDARD = SSTL2_I ;
NET "SD_CS" LOC = "K4" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<0>" LOC = "L2" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<1>" LOC = "L1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<2>" LOC = "L3" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<3>" LOC = "L4" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<4>" LOC = "M3" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<5>" LOC = "M4" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<6>" LOC = "M5" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<7>" LOC = "M6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<8>" LOC = "E2" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<9>" LOC = "E1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<10>" LOC = "F1" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<11>" LOC = "F2" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<12>" LOC = "G6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<13>" LOC = "G5" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<14>" LOC = "H6" | IOSTANDARD = SSTL2_I ;
NET "SD_DQ<15>" LOC = "H5" | IOSTANDARD = SSTL2_I ;
NET "SD_LDM" LOC = "J2" | IOSTANDARD = SSTL2_I ;
NET "SD_LDQS" LOC = "L6" | IOSTANDARD = SSTL2_I ;
NET "SD_RAS" LOC = "C1" | IOSTANDARD = SSTL2_I ;
NET "SD_UDM" LOC = "J1" | IOSTANDARD = SSTL2_I ;
NET "SD_UDQS" LOC = "G3" | IOSTANDARD = SSTL2_I ;
NET "SD_WE" LOC = "D1" | IOSTANDARD = SSTL2_I ;
# Path to allow connection to top DCM connection
NET "SD_CK_FB" LOC = "B9" | IOSTANDARD = LVCMOS33 ;
# Prohibit VREF pins
CONFIG PROHIBIT = D2;
CONFIG PROHIBIT = G4;
CONFIG PROHIBIT = J6;
CONFIG PROHIBIT = L5;
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CONFIG PROHIBIT = R4;
# ==== Intel StrataFlash Parallel NOR Flash (SF) ====
NET "SF_A<0>" LOC = "H17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<1>" LOC = "J13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<2>" LOC = "J12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<3>" LOC = "J14" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<4>" LOC = "J15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<5>" LOC = "J16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<6>" LOC = "J17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<7>" LOC = "K14" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<8>" LOC = "K15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<9>" LOC = "K12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<10>" LOC = "K13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<11>" LOC = "L15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<12>" LOC = "L16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<13>" LOC = "T18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<14>" LOC = "R18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<15>" LOC = "T17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<16>" LOC = "U18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<17>" LOC = "T16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<18>" LOC = "U15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<19>" LOC = "V15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<20>" LOC = "T12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<21>" LOC = "V13" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<22>" LOC = "V12" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<23>" LOC = "N11" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_A<24>" LOC = "A11" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_BYTE" LOC = "C17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_CE0" LOC = "D16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<1>" LOC = "P10" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<2>" LOC = "R10" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<3>" LOC = "V9" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<4>" LOC = "U9" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<5>" LOC = "R9" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<6>" LOC = "M9" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<7>" LOC = "N9" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<8>" LOC = "R15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<9>" LOC = "R16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<10>" LOC = "P17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<11>" LOC = "M15" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<12>" LOC = "M16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<13>" LOC = "P6" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<14>" LOC = "R8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_D<15>" LOC = "T8" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_OE" LOC = "C18" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
NET "SF_STS" LOC = "B18" | IOSTANDARD = LVCMOS33 ;
NET "SF_WE" LOC = "D17" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
# ==== STMicro SPI serial Flash (SPI) ====
# some connections shared with SPI Flash, DAC, ADC, and AMP
NET "SPI_MISO" LOC = "N10" | IOSTANDARD = LVCMOS33 ;
NET "SPI_MOSI" LOC = "T4" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "SPI_SCK" LOC = "U16" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "SPI_SS_B" LOC = "U3" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
NET "SPI_ALT_CS_JP11" LOC = "R12" | IOSTANDARD = LVCMOS33 | SLEW = SLOW | DRIVE = 6 ;
# ==== VGA Port (VGA) ====
NET "VGA_BLUE" LOC = "G15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_GREEN" LOC = "H15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_HSYNC" LOC = "F15" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
NET "VGA_RED" LOC = "H14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
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NET "VGA_VSYNC" LOC = "F14" | IOSTANDARD = LVTTL | DRIVE = 8 | SLEW = FAST ;
#
# ==== FX2 Connector (FX2) ====
NET "FX2_CLKIN" LOC = "E10" | IOSTANDARD = LVCMOS33 ;
NET "FX2_CLKIO" LOC = "D9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_CLKOUT" LOC = "D10" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<1>" LOC = "B4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<2>" LOC = "A4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<3>" LOC = "D5" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<4>" LOC = "C5" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<5>" LOC = "A6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<6>" LOC = "B6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<7>" LOC = "E7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<8>" LOC = "F7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<9>" LOC = "D7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<10>" LOC = "C7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<11>" LOC = "F8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<12>" LOC = "E8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<13>" LOC = "F9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<14>" LOC = "E9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<15>" LOC = "D11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<16>" LOC = "C11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<17>" LOC = "F11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<18>" LOC = "E11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<19>" LOC = "E12" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "FX2_IO<20>" LOC = "F12" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<21>" LOC = "A13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<22>" LOC = "B13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<23>" LOC = "A14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<24>" LOC = "B14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<25>" LOC = "C14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<26>" LOC = "D14" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<27>" LOC = "A16" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<28>" LOC = "B16" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<29>" LOC = "E13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<30>" LOC = "C4" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<31>" LOC = "B11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "FX2_IO<32>" LOC = "A11" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
# The discrete LEDs are shared with the following 8 FX2 connections
# NET "FX2_IO<33>" LOC = "A8" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED7
# NET "FX2_IO<34>" LOC = "G9" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED6
# NET "FX2_IP<35>" LOC = "A7" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED5
# NET "FX2_IP<36>" LOC = "D13" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED4
# NET "FX2_IP<37>" LOC = "E6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED3
# NET "FX2_IP<38>" LOC = "D6" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED2
# NET "FX2_IO<39>" LOC = "C3" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ; # LED1
NET "FX2_IP<40>" LOC = "C15" | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
# ==== 6-pin header J1 ====
# These are independent of the FX2 connector
#NET "J1<0>" LOC = "V7" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J1<1>" LOC = "E15" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J1<2>" LOC = "N14" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J1<3>" LOC = "N15" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
# ==== 6-pin header J2 ====
# These are independent of the FX2 connector
#NET "J2<0>" LOC = "P12" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J2<1>" LOC = "N12" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J2<2>" LOC = "V6" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J2<3>" LOC = "V5" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
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# ==== 6-pin header J4 ====
# These are independent of the FX2 connector
#NET "J4<0>" LOC = "R14" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J4<1>" LOC = "T14" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J4<2>" LOC = "R13" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#NET "J4<3>" LOC = "P13" | IOSTANDARD = LVTTL | SLEW = SLOW | DRIVE = 6 ;
#
# ==== J15 Input Only Connector ====
NET "INPUT_IO<1>" LOC = "A12" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<2>" LOC = "A3" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<3>" LOC = "B15" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<4>" LOC = "A15" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<5>" LOC = "C13" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<6>" LOC = "D12" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<7>" LOC = "F10" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<8>" LOC = "G10" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<9>" LOC = "C8" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<10>" LOC = "D8" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<11>" LOC = "A5" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
NET "INPUT_IO<12>" LOC = "B5" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE = 8 ;
#NET "INPUT_IO<13>" LOC = "E17" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE =
8 ;
#NET "INPUT_IO<14>" LOC = "P15" | PULLDOWN | IOSTANDARD = LVCMOS33 | SLEW = FAST | DRIVE =
8 ;

#
# ==== Xilinx CPLD (XC) ====
NET "XC_CMD<0>" LOC = "P18" | IOSTANDARD = LVTTL | DRIVE = 4 | SLEW = SLOW ;
NET "XC_CMD<1>" LOC = "N18" | IOSTANDARD = LVTTL | DRIVE = 4 | SLEW = SLOW ;
NET "XC_CPLD_EN" LOC = "B10" | IOSTANDARD = LVTTL ;
NET "XC_D<0>" LOC = "G16" | IOSTANDARD = LVTTL | DRIVE = 4 | SLEW = SLOW ;
NET "XC_D<1>" LOC = "F18" | IOSTANDARD = LVTTL | DRIVE = 4 | SLEW = SLOW ;
NET "XC_D<2>" LOC = "F17" | IOSTANDARD = LVTTL | DRIVE = 4 | SLEW = SLOW ;
NET "XC_TRIG" LOC = "R17" | IOSTANDARD = LVCMOS33 ;
NET "XC_GCK0" LOC = "H16" | IOSTANDARD = LVCMOS33 | DRIVE = 4 | SLEW = SLOW ;
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